



Intel[®] Server Board S5000PAL / S5000XAL

Technical Product Specification

Intel order number: D31979-006



Revision 1.3

January 2007

Enterprise Platforms and Services Division - Marketing

Revision History

Date	Revision Number	Modifications
April 2006	1.0	First external release.
June 2006	1.1	Updated theoretical memory bandwidth performance numbers. Added Platform Control sections.
August 2006	1.2	Memory RAS is now available. Updated Snoop Filter Section. Updated Figures #16 and #25.
January 2007	1.3	Updated Table 44 BMC sensor. Updated CMOS clear and password reset usage procedures. Updated regulatory tables.

Disclaimers

Information in this document is provided in connection with Intel® products. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Intel's Terms and Conditions of Sale for such products, Intel assumes no liability whatsoever, and Intel disclaims any express or implied warranty, relating to sale and/or use of Intel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Intel products are not intended for use in medical, life saving, or life sustaining applications. Intel may make changes to specifications and product descriptions at any time, without notice.

Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined." Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them.

The Intel® Server Board S5000PAL and the Intel® Server Board S5000XAL may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Intel Corporation server baseboards support peripheral components and contain a number of high-density VLSI and power delivery components that need adequate airflow to cool. Intel's own chassis are designed and tested to meet the intended thermal requirements of these components when the fully integrated system is used together. It is the responsibility of the system integrator that chooses not to use Intel developed server building blocks to consult vendor datasheets and operating parameters to determine the amount of air flow required for their specific application and environmental conditions. Intel Corporation can not be held responsible if components fail or the server board does not operate correctly when used outside any of their published operating or non-operating limits.

Intel, Pentium, Itanium, and Xeon are trademarks or registered trademarks of Intel Corporation.

*Other brands and names may be claimed as the property of others.

Copyright © Intel Corporation 2006-2007.

Table of Contents

1. Introduction	12
1.1 Chapter Outline.....	12
1.2 Server Board Use Disclaimer	12
2. Product Overview.....	13
2.1 Intel® Server Board S5000PAL / S5000XAL Feature Set	13
2.2 Server Board Layout.....	14
2.2.1 Connector and Component Locations	15
2.2.2 Light Guided Diagnostic LED Locations	17
2.2.3 External I/O Connector Locations.....	18
2.2.4 Server Board Mechanical Drawings	19
3. Functional Architecture	24
3.1 Intel® 5000P and 5000X Memory Controller Hubs (MCH)	25
3.1.1 System Bus Interface.....	25
3.1.2 Processor Support.....	25
3.1.3 Memory Sub-system.....	27
3.1.4 Snoop Filter (5000X MCH only).....	33
3.2 ESB-2 IO Controller	33
3.2.1 PCI Sub-system.....	34
3.2.2 Serial ATA Support	36
3.2.3 Parallel ATA (PATA) Support	37
3.2.4 USB 2.0 Support.....	37
3.3 Video Support	37
3.4 Network Interface Controller (NIC)	39
3.4.1 Intel® I/O Acceleration Technolgy	39
3.4.2 MAC Address Definition.....	39
3.5 Super I/O	40
4. Platform Management.....	43
4.1 Platform Control.....	44
4.1.1 Overview.....	44
4.1.2 FBDIMM Open Loop Throughput Throttling	45
4.1.3 Fan Speed Control.....	45
5. Connector / Header Locations and Pin-outs.....	48
5.1 Board Connector Information.....	48
5.2 Power Connectors	49
5.3 System Management Headers	50

5.3.1	Intel® Remote Management Module (RMM) Connector	50
5.3.2	Intel® RMM NIC Connector	51
5.3.3	LCP/AUX IPMB Header	52
5.3.4	IPMB Header	52
5.4	Riser Card Slots.....	52
5.5	SSI Control Panel Connector.....	57
5.6	Bridge Board Connector	57
5.7	I/O Connector Pinout Definition	59
5.7.1	VGA Connector.....	59
5.7.2	NIC Connectors	59
5.7.3	IDE Connector	60
5.7.4	Intel® I/O Expansion Module Connector	60
5.7.5	SATA Connectors	61
5.7.6	Serial Port Connectors.....	62
5.7.7	Keyboard and Mouse Connector	62
5.7.8	USB 2.0 Connectors	63
5.8	Fan Headers	64
6.	Jumper Block Settings	65
6.1	Recovery Jumper Blocks	65
6.1.1	CMOS Clear and Password Reset Usage Procedure	66
6.1.2	BMC Force Update Procedure	66
6.2	BIOS Select Jumper	67
6.3	External RJ45 Serial Port Jumper Block.....	68
7.	Light Guided Diagnostics.....	69
7.1	5-Volt Standby LED	69
7.2	System ID LED and System Status LED	70
7.2.1	System Status LED – BMC Initialization.....	71
7.3	DIMM Fault LEDs	72
7.4	Processor Fault LED.....	72
7.5	Post Code Diagnostic LEDs	73
8.	Power and Environmental Specifications.....	74
8.1	Intel® Server Board S5000PAL / S5000XAL Design Specifications	74
8.2	Server Board Power Requirements	75
8.2.1	Processor Power Support.....	75
8.2.2	Power Supply Output Requirements	76
8.2.3	Turn On No Load Operation	76
8.2.4	Grounding	77
8.2.5	Standby Outputs	77

8.2.6	Remote Sense	77
8.2.7	Voltage Regulation	77
8.2.8	Dynamic Loading	78
8.2.9	Capacitive Loading	78
8.2.10	Closed-Loop Stability	78
8.2.11	Common Mode Noise	78
8.2.12	Ripple / Noise	79
8.2.13	Soft Starting	79
8.2.14	Timing Requirements.....	79
8.2.15	Residual Voltage Immunity in Standby Mode	82
9.	Regulatory and Certification Information.....	83
9.1	Product Regulatory Compliance	83
9.1.1	Product Safety & Electromagnetic (EMC) Compliance.....	83
9.2	Electromagnetic Compatibility Notices	84
9.2.1	FCC Verification Statement (USA)	84
9.2.2	ICES-003 (Canada)	84
9.2.3	Europe (CE Declaration of Conformity)	84
9.2.4	BSMI (Taiwan)	85
9.2.5	RRL (Korea).....	85
9.3	Product Ecology Compliance.....	86
9.4	Other Markings	87
	Appendix A: Integration and Usage Tips.....	88
	Appendix B: BMC Sensor Tables	89
	Appendix C: POST Code Diagnostic LED Decoder	105
	Appendix D: POST Error Messages and Handling	109
	Appendix E: Supported Intel® Server Chassis	112
	Glossary.....	115
	Reference Documents	118

List of Figures

Figure 1. Components & Connector Location Diagram	16
Figure 2. Light Guided Diagnostic LED Location Diagram	17
Figure 3. Intel® Server Board S5000PAL / S5000XAL ATX I/O Layout	18
Figure 4. Intel® Server Board S5000PAL / S5000XAL – Hole and Component Positions (1 of 2)19	
Figure 5. Intel® Server Board S5000PAL / S5000XAL – Hole and Component Positions (2 of 2)20	
Figure 6. Intel® Server Board S5000PAL / S5000XAL – Restricted Areas on Side 1	21
Figure 7. Intel® Server Board S5000PAL / S5000XAL – Restricted Areas on Side 2	22
Figure 8. Intel® Server Board S5000PAL / S5000XAL - Primary Side Duct and VR Restrictions23	
Figure 9. Server Board Functional Block Diagram.....	24
Figure 10. CEK Processor Mounting	27
Figure 11. Memory Layout	27
Figure 12. Recommended Minimum Two DIMM Memory Configuration	30
Figure 13. Recommended Four DIMM Configuration	31
Figure 14. Single Branch Mode Sparing DIMM Configuration	32
Figure 15. Serial Port Configuration Jumper Location	41
Figure 16. SMBUS Block Diagram.....	43
Figure 17. Recovery Jumper Blocks (J1D1, J1D2, J1D3)	65
Figure 18. BIOS Select Jumper (J3H1)	67
Figure 19. External RJ45 Serial Port Configuration Jumper	68
Figure 20. 5V Standby Status LED Location	69
Figure 21. System ID LED and System Status LED Locations.....	70
Figure 22. DIMM Fault LED Locations	72
Figure 23. Processor Fault LED Location	72
Figure 24. POST Code Diagnostic LED Location	73
Figure 25. Power Distribution Block Diagram	75
Figure 26. Output Voltage Timing	80
Figure 27. Turn On/Off Timing (Power Supply Signals).....	81
Figure 28. Diagnostic LED Placement Diagram	105
Figure 29. 1U – Intel® Server Chassis SR1500 Overview	112
Figure 30. 1U – Intel® Server Chassis SR1550 Overview	113
Figure 31. 2U – Intel® Server Chassis SR2500 Overview	114

List of Tables

Table 1. Processor Support Matrix	26
Table 2. I ² C Addresses for Memory Module SMB	28
Table 3. Maximum 8 DIMM System Memory Configuration – x8 Single Rank	28
Table 4. Maximum 8 DIMM System Memory Configuration – x4 Dual Rank	28
Table 5. PCI Bus Segment Characteristics.....	34
Table 6. Video Modes	38
Table 7. NIC2 Status LED.....	39
Table 8. Serial A Header Pin-out	40
Table 9. Rear Serial B Port Adapter Pin-out.....	41
Table 10. Board Connector Matrix	48
Table 11. Power Connector Pin-out (J3K3)	49
Table 12. 12V Power Connector Pin-out (J3K4).....	49
Table 13. Power Supply Signal Connector Pin-out (J1K1)	49
Table 14. Intel® RMM Connector Pin-out (J1C5)	50
Table 15. 30-pin Intel® RMM NIC Module Connector Pin-out (J1B2)	51
Table 16. LPC/AUX IPMB Header Pin-out (J1C2).....	52
Table 17. IPMB Header Pin-out (J1C3)	52
Table 18. Low-profile Riser Slot Pin-out (J5B1).....	52
Table 19. Full-height Riser Slot Pin-out (J4F1).....	53
Table 20. Front Panel SSI Standard 24-pin Connector Pin-out (J3H2)	57
Table 21. 120-pin Bridgeboard Connector Pin-out (J4G1)	57
Table 22. VGA Connector Pin-out (J6A1).....	59
Table 23. RJ-45 10/100/1000 NIC Connector Pin-out (JA8A1, JA8A2).....	59
Table 24. 44-pin IDE Connector Pin-out (J3G1)	60
Table 25. 50-pin Intel® I/O Expansion Module Connector Pin-out (J3B1).....	61
Table 26. SATA Connector Pin-out (J1H1, J1G2, J1G1, J1F2, J1E3)	61
Table 27. External RJ-45 Serial ‘B’ Port Pin-out (J9A2)	62
Table 28. Internal 9-pin Serial ‘A’ Header Pin-out (J1B1).....	62
Table 29. Stacked PS/2 Keyboard and Mouse Port Pin-out (J9A1)	62
Table 30. External USB Connector Pin-out (J5A1, J6A2).....	63
Table 31. Internal USB Connector Pin-out (J1J1).....	63
Table 32. SSI Fan Connector Pin-out (J9K1, J5K1, J3K1, J3K2, J7A2, J7A1)	64
Table 33. Recovery Jumpers (J1D1, J1D2, J1D3)	65
Table 34: Server Board Design Specifications	74
Table 35. Dual-Core Intel® Xeon® Processor 5000 Sequence TDP Guidelines per processor ..	75

Table 36. 600W Load Ratings	76
Table 37: No load operating range	76
Table 38. Voltage Regulation Limits	77
Table 39. Transient Load Requirements.....	78
Table 40. Capacitive Loading Conditions	78
Table 41. Ripple and Noise.....	79
Table 42. Output Voltage Timing	80
Table 43. Turn On/Off Timing	81
Table 44. BMC Sensors.....	91
Table 45: POST Progress Code LED Example	105
Table 46. Diagnostic LED POST Code Decoder	106
Table 47. POST Error Messages and Handling.....	109
Table 48. POST Error Beep Codes	111
Table 49. BMC Beep Codes	111

< This page intentionally left blank. >

1. Introduction

This Technical Product Specification (TPS) provides board specific information detailing the features, functionality, and high level architecture of the Intel® Server Board S5000PAL and Intel® Server Board S5000XAL. The *Intel® S5000 Series Chipsets Server Board Family Datasheet* should also be referenced for more in depth detail of various board sub-systems including chipset, BIOS, System Management, and System Management software.

In addition, design level information for specific sub-systems can be obtained by ordering the External Product Specifications (EPS) or External Design Specifications (EDS) for a given sub-system. EPS and EDS documents are not publicly available. They are only made available under NDA with Intel and must be ordered through your local Intel representative.

The Intel® Server Board S5000PAL/XAL may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Refer to the *Intel® Server Board S5000PAL/XAL Specification Update* for published errata.

1.1 Chapter Outline

This document is divided into the following chapters

- Chapter 1 – Introduction
- Chapter 2 – Server Board Overview
- Chapter 3 – Functional Architecture
- Chapter 4 – Platform Management
- Chapter 5 – Connector & Header Location and Pin-out
- Chapter 6 – Configuration Jumpers
- Chapter 7 – Light Guided Diagnostics
- Chapter 8 – Power and Environmental Specifications
- Chapter 9 – Regulatory and Certification Information
- Appendix A – Integration and Usage Tips
- Appendix B – BMC Sensor Tables
- Appendix C – POST Code Diagnostic LED Decoder
- Appendix D – Post Code Errors
- Appendix E – Supported Intel® Server Chassis

1.2 Server Board Use Disclaimer

Intel Corporation server boards support add-in peripherals and contain a number of high-density VLSI and power delivery components that need adequate airflow to cool. Intel ensures through its own chassis development and testing that when Intel server building blocks are used together, the fully integrated system will meet the intended thermal requirements of these components. It is the responsibility of the system integrator who chooses not to use Intel developed server building blocks to consult vendor datasheets and operating parameters to determine the amount of air flow required for their specific application and environmental conditions. Intel Corporation cannot be held responsible if components fail or the server board does not operate correctly when used outside any of their published operating or non-operating limits.

2. Product Overview

The Intel® Server Board S5000PAL and Intel® Server Board S5000XAL are monolithic printed circuit boards with features that were designed to support the high-density 1U and 2U server markets.

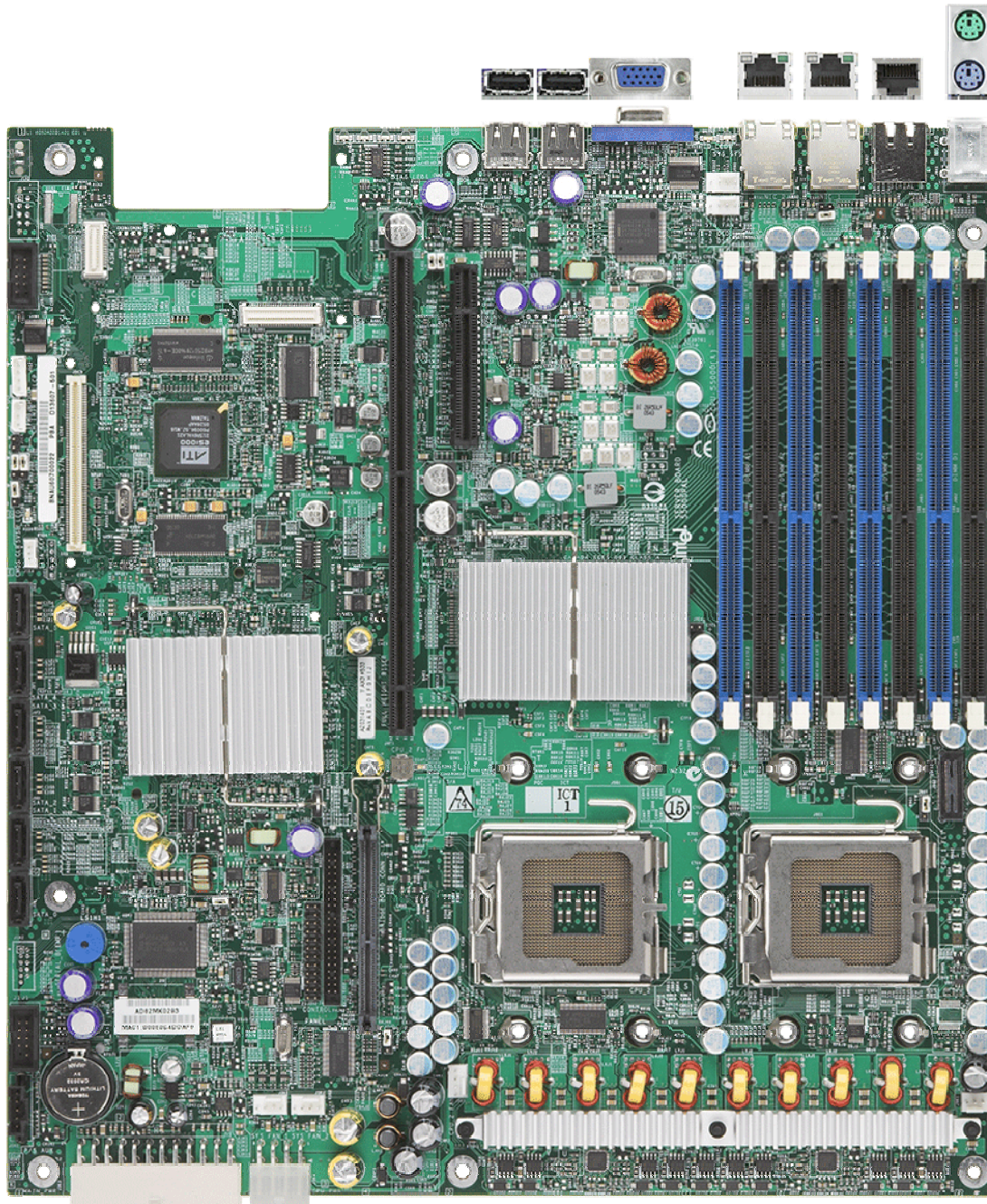
2.1 Intel® Server Board S5000PAL / S5000XAL Feature Set

Feature	Description
Processors	771-pin LGA sockets supporting 1 or 2 Dual-Core Intel® Xeon® processors 5000 sequence, with system bus speeds of 667 MHz, 1066 MHz, or 1333 MHz
Memory	8 Keyed DIMM slots supporting fully buffered DIMM technology (FBDIMM) memory. 240-pin DDR2-533 and DDR2-677 FBDIMMs must be used.
Chipset	Intel® 5000 Chipset Family which includes the following components: Intel® 5000P Memory Controller Hub or Intel® 5000X Memory Controller Hub Intel® 6321ESB I/O Controller Hub ¹ Note: Intel will only make available an OEM SKU of this server board using the Intel® 5000X Memory Controller Hub.
On-board Connectors/Headers	External connections: <ul style="list-style-type: none"> ▪ Stacked PS/2* ports for keyboard and mouse ▪ RJ45 Serial B port ▪ Two RJ45 NIC connectors for 10/100/1000 Mb connections ▪ Two USB 2.0 ports ▪ Video Connector Internal connectors/headers: <ul style="list-style-type: none"> ▪ One USB port header, capable of providing two USB 2.0 ports ▪ One DH10 Serial A header ▪ Six SATA ports via the ESB-2 supporting 3Gb/s and integrated SW RAID 0/1/10 support ▪ One 44pin (power + I/O) ATA/100 connector for optical drive support ▪ One Intel® Remote Management Module (Intel® RMM) connector (Intel® RMM use is optional) ▪ One Intel® I/O Expansion Module Connector supporting: <ul style="list-style-type: none"> ▪ Dual GB NIC Intel® I/O Expansion Module (Optional) ▪ External SAS Intel® I/O Expansion Module (Optional) ▪ Infiniband* I/O Expansion Module (Optional) ▪ SSI-compliant 24-pin control panel header ▪ SSI-compliant 24-pin main power connector, supporting the ATX-12V standard on the first 20 pins ▪ 8-Pin +12V Processor Power Connector
Add-in PCI, PCI-X*, PCI Express* Cards	<ul style="list-style-type: none"> ▪ One low profile riser slot supporting 1U or 2U PCIe* riser cards ▪ One full height riser slot supporting 1U or 2U PCI-X* and PCIe* riser cards
On-board Video	ATI* ES1000 video controller with 16MB DDR SDRAM
On-board Hard Drive Controller	<ul style="list-style-type: none"> ▪ Six ESB-2 3Gb/s SATA ports. ▪ Intel® Embedded Server RAID Technology II with SW RAID levels 0/1/10. ▪ Optional support for SW RAID 5 with activation key.²
LAN	Two 10/100/1000 Intel® 82563EB PHYs supporting Intel® I/O Acceleration Technology
System Fans	Six 4-pin Fan Headers supporting two processor fans, and four system fans
System Management	Support for Intel® System Management Software

¹ For the remainder of this document, the Intel® 6321ESB I/O Controller Hub will be referred to as ESB-2.

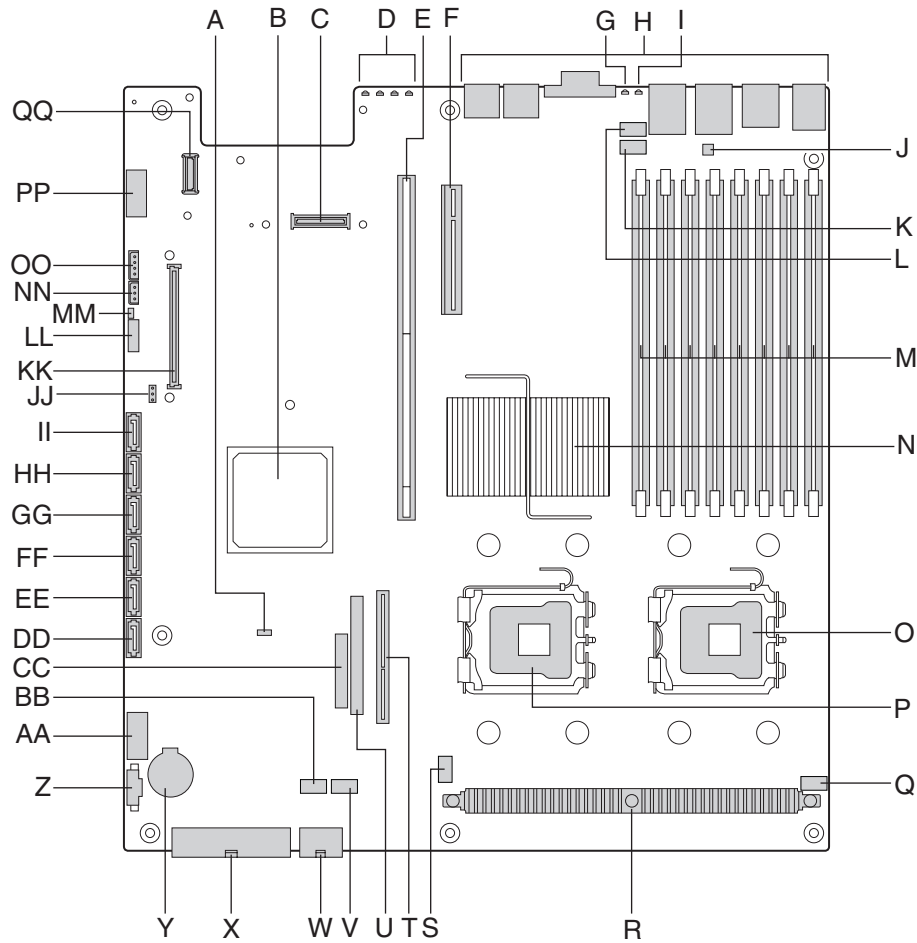
² Onboard SATA SW RAID 5 support provided as a post-launch product feature.

2.2 Server Board Layout



2.2.1 Connector and Component Locations

The following figure shows the board layout of the server board. Each connector and major component is identified by a number or letter, and a description is given below the figure.

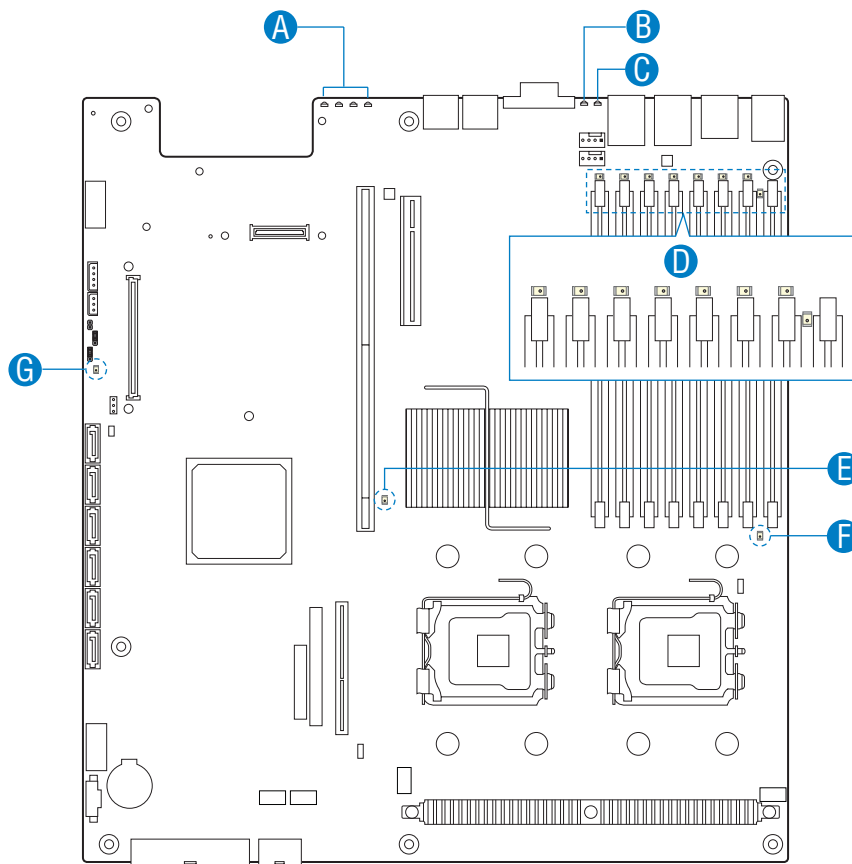


TP02071

	Description		Description
A	BIOS Bank Select Jumper	V	System Fan #2 Header
B	Intel® ESB-2 IO Controller Hub	W	CPU Power Connector
C	IO Module Option Connector	X	Main Power Connector
D	POST Code Diagnostic LEDs	Y	Battery
E	Intel® Adaptive Slot – Full Height	Z	Power Supply Management Connector
F	PCI Express* Riser Slot – Low Profile	AA	Dual Port USB 2.0 Header
G	System Identification LED - Blue	BB	System Fan #1 Header
H	External IO Connectors	CC	SSI 24-pin Control Panel Header
I	Status LED – Green / Amber	DD	SATA 0
J	Serial 'B' Port Configuration Jumper	EE	SATA 1
K	System Fan #4 Header	FF	SATA 2
L	System Fan #3 Header	GG	SATA 3
M	FBDIMM Slots	HH	SATA 4
N	Intel® 5000P Memory Controller Hub (MCH) or Intel® 5000X Memory Controller Hub (MCH)	II	SATA 5
O	CPU #1 Connector	JJ	SATA SW RAID 5 Activation Key Connector
P	CPU #2 Connector	KK	Intel® Remote Management Module (RMM) Connector
Q	CPU #1 Fan Header	LL	System Recovery Jumper Block
R	Voltage Regulator Heat Sink	MM	Chassis Intrusion Switch Header
S	CPU #2 Fan Header	NN	3-pin IPMB Header
T	Bridge Board Connector	OO	Intel® Local Control Panel Header
U	ATA-100 Optical Drive Connector (Power+IO)	PP	Serial 'A' Header
		QQ	Intel® RMM NIC Connector

Figure 1. Components & Connector Location Diagram

2.2.2 Light Guided Diagnostic LED Locations



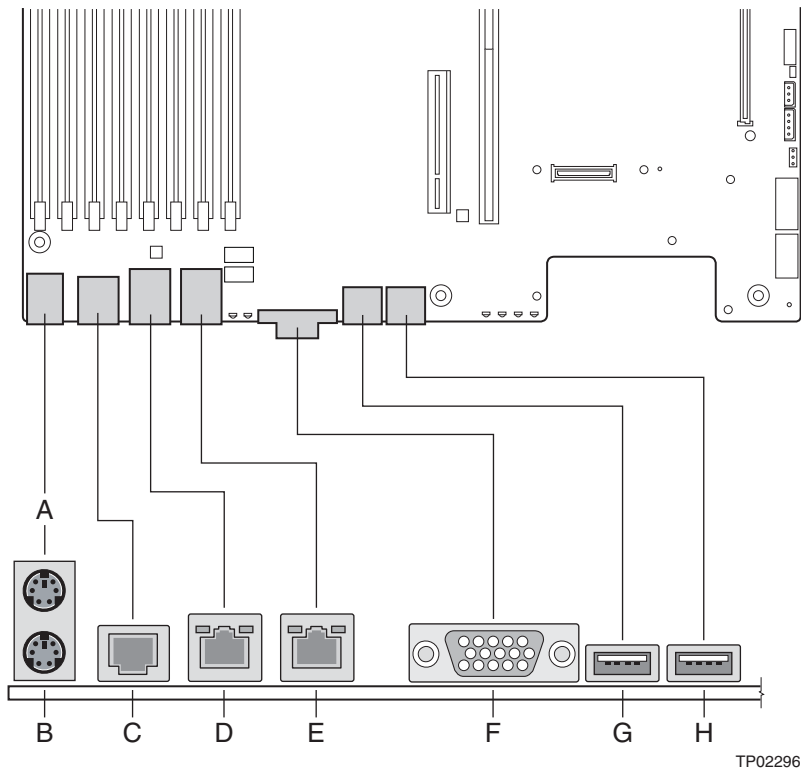
TP02317

Description		Description	
A	Post Code Diagnostic LEDs	E	CPU Fault LED
B	System Identification LED – Blue	F	CPU Fault LED
C	System Status LED – Green / Amber	G	5-Volt Stand-by Present LED
D	DIMM Fault LEDs		

Figure 2. Light Guided Diagnostic LED Location Diagram

2.2.3 External I/O Connector Locations

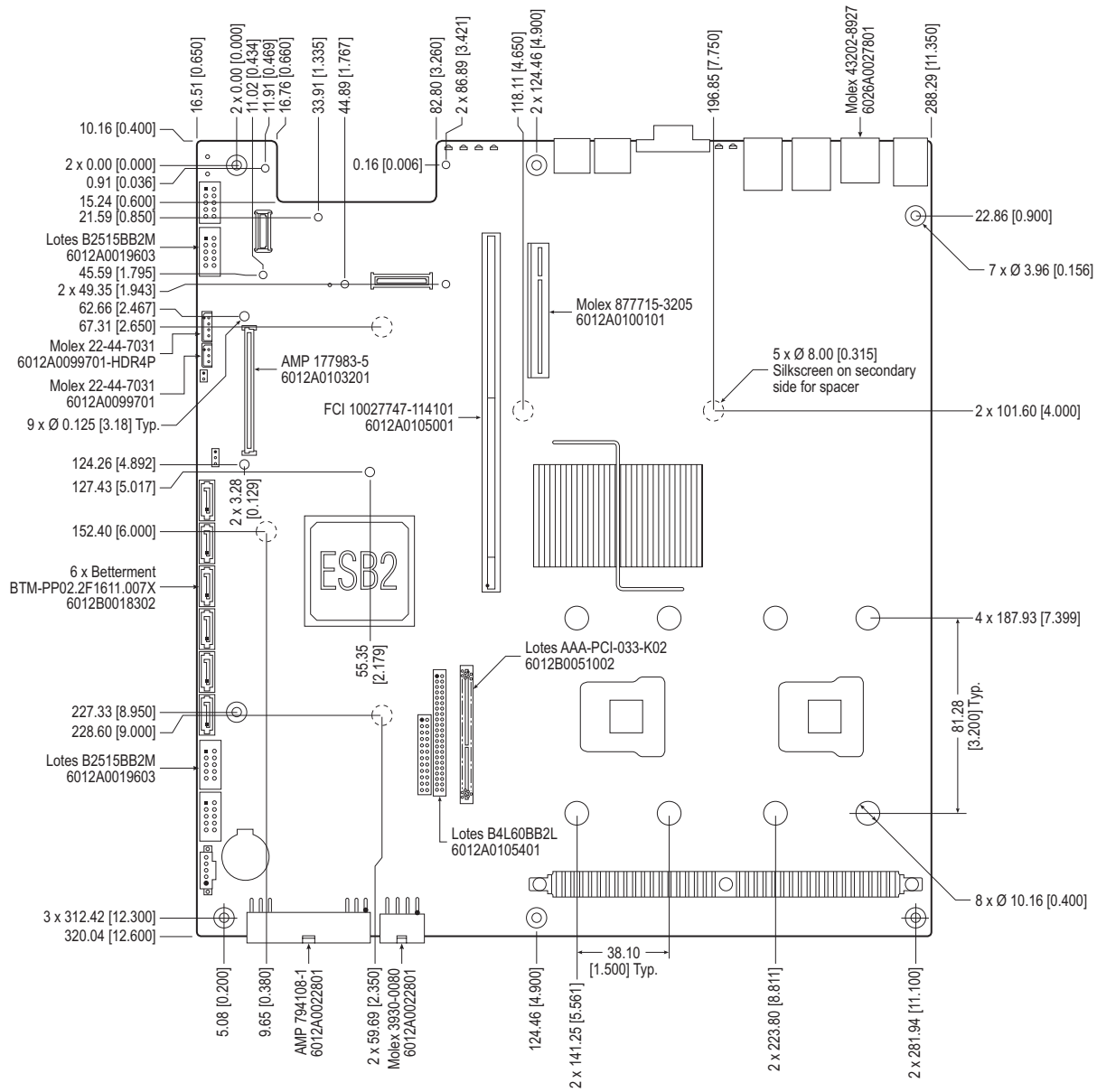
The drawing below shows the layout of the rear I/O components for the server board.



A	PS/2 Mouse	E	NIC port 2 (1 Gb)
B	PS/2 Keyboard	F	Video
C	Serial Port B	G	USB port 1
D	NIC port 1 (1 Gb)	H	USB port 2

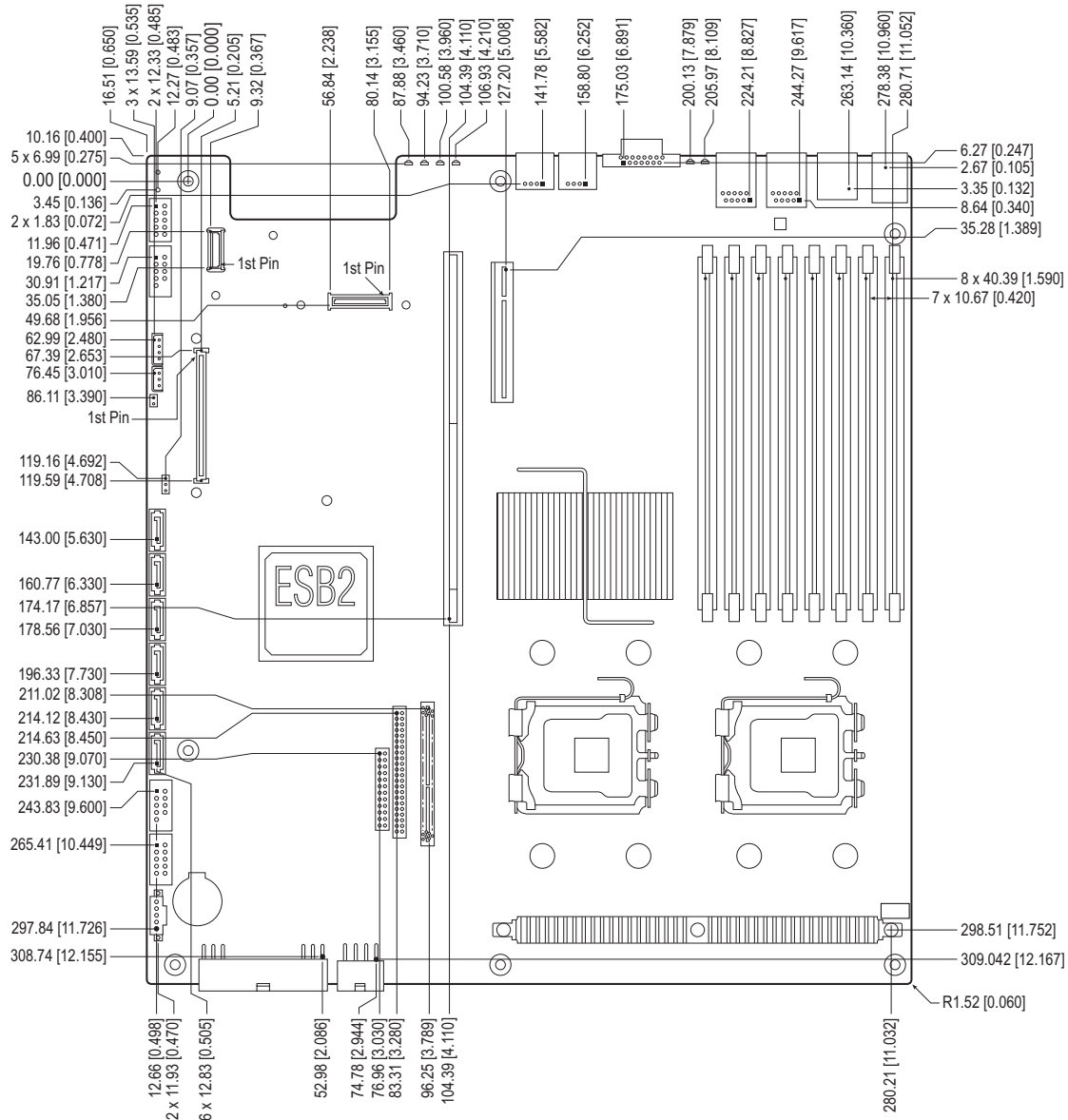
Figure 3. Intel® Server Board S5000PAL / S5000XAL ATX I/O Layout

2.2.4 Server Board Mechanical Drawings



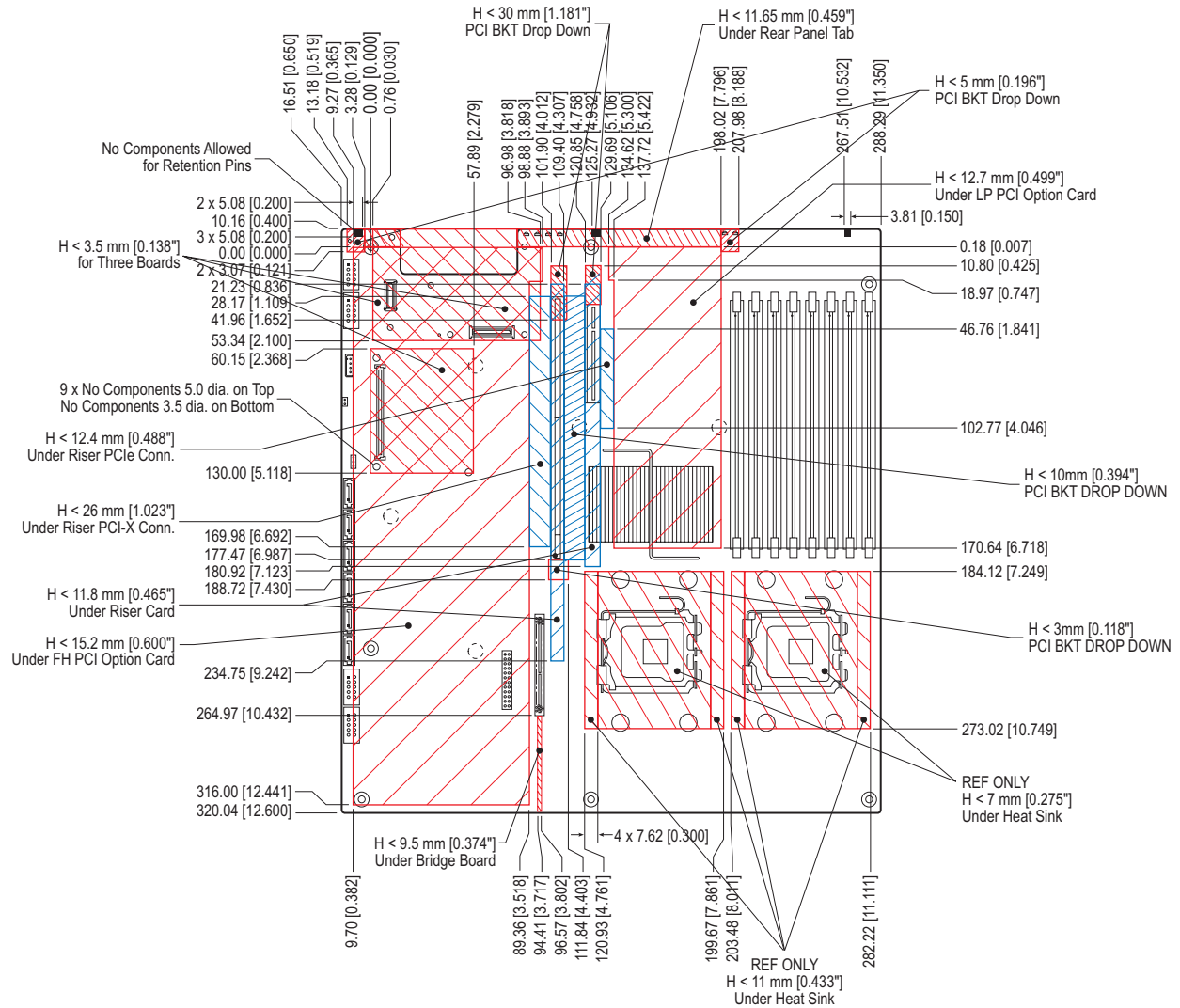
TP02316

Figure 4. Intel® Server Board S5000PAL / S5000XAL – Hole and Component Positions (1 of 2)



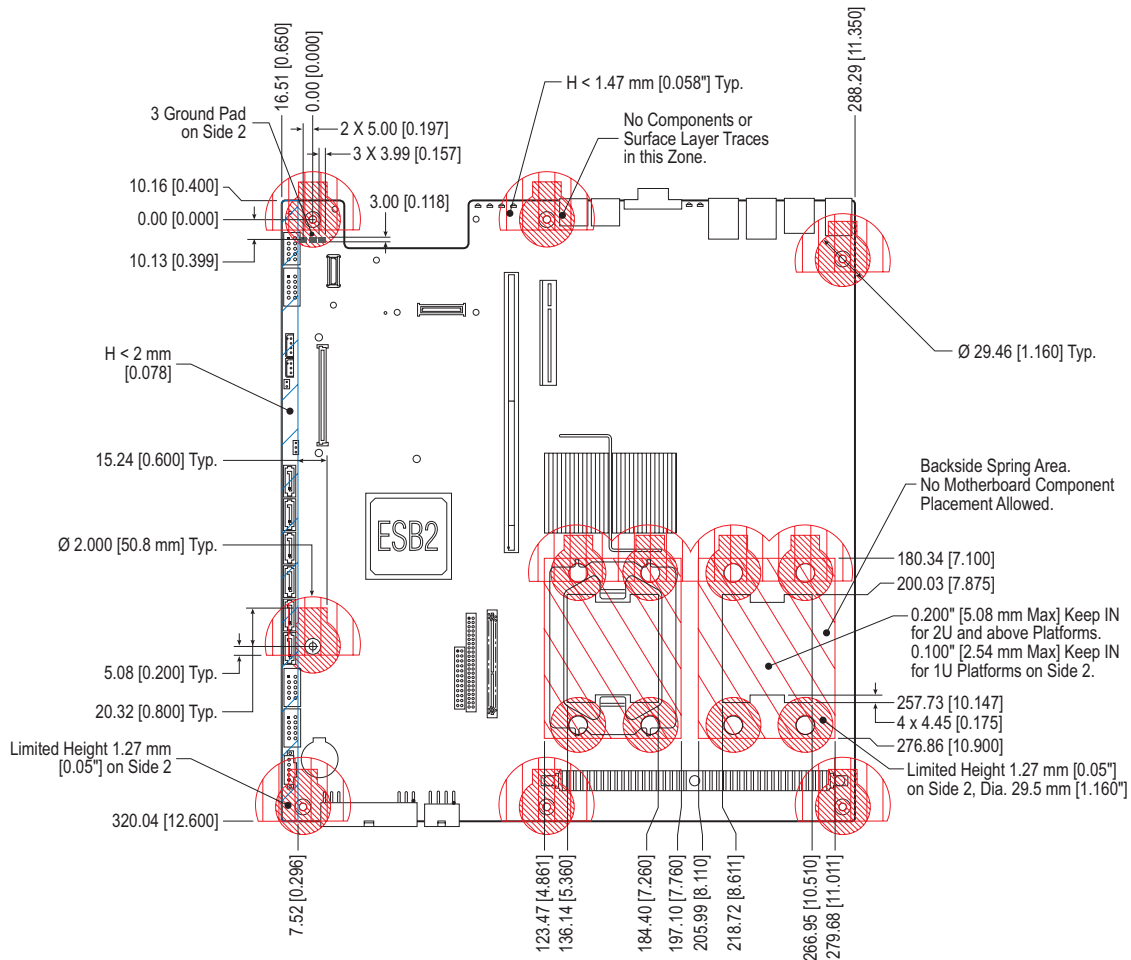
TP02292

Figure 5. Intel® Server Board S5000PAL / S5000XAL – Hole and Component Positions (2 of 2)



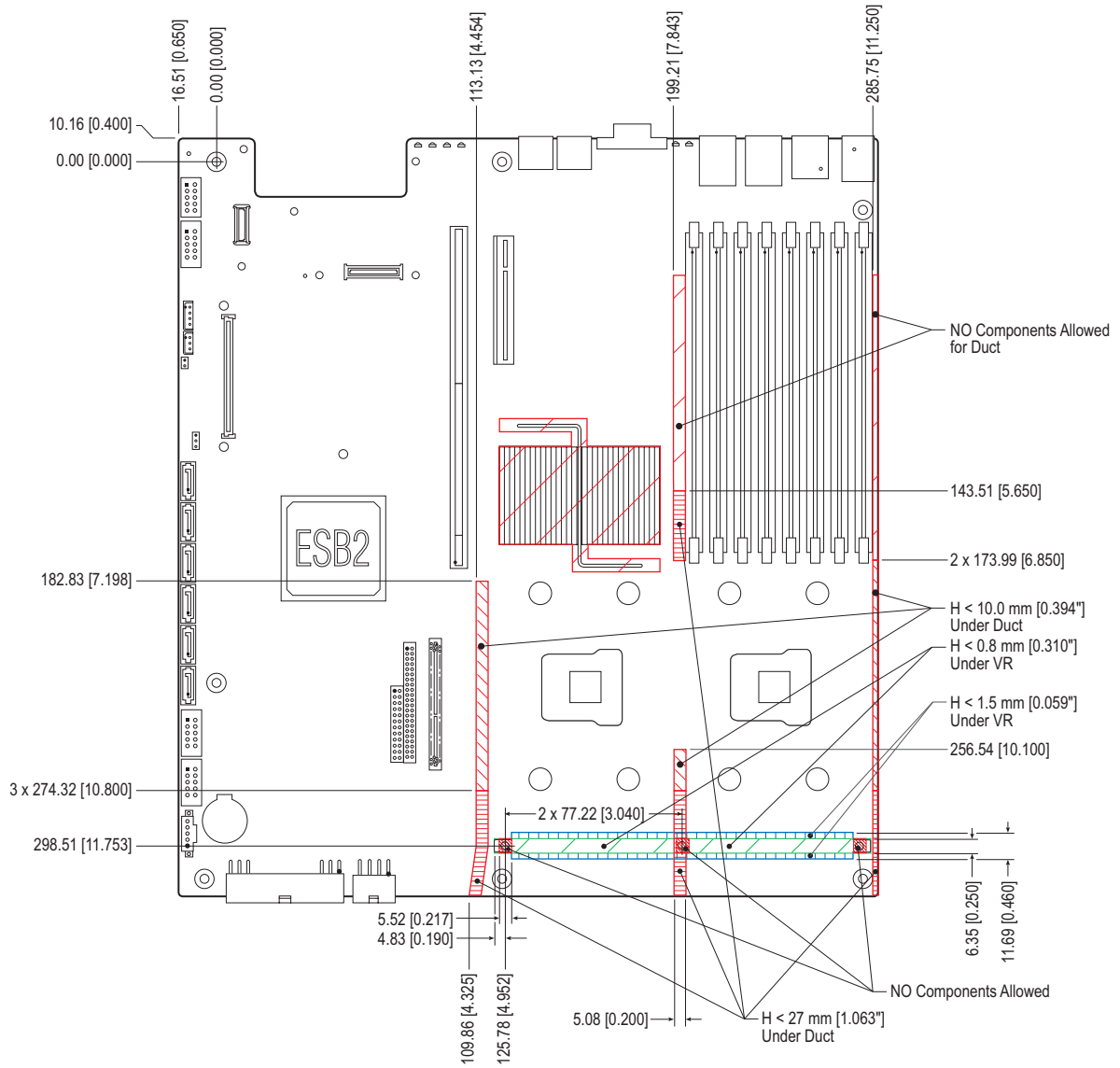
TP02293

Figure 6. Intel® Server Board S5000PAL / S5000XAL – Restricted Areas on Side 1



TP02294

Figure 7. Intel® Server Board S5000PAL / S5000XAL – Restricted Areas on Side 2



TP02295

Figure 8. Intel® Server Board S5000PAL / S5000XAL - Primary Side Duct and VR Restrictions

3. Functional Architecture

The architecture and design of the Intel® Server Board S5000PAL / S5000XAL is based on the Intel® 5000 Chipset Family. The chipset is designed for systems based on the Dual-Core Intel® Xeon® processor 5000 sequence with system bus speeds of 667 MHz, 1066 MHz, and 1333 MHz. The chipset is made up of two main components: the Memory Controller Hub (MCH) for the host bridge and the ESB-2 I/O controller hub for the I/O subsystem. This chapter provides a high-level description of the functionality associated with each chipset component and the architectural blocks that make up this server board. For more in depth detail of the functionality for each of the chipset components and each of the functional architecture blocks, see the *Intel® S5000 Server Board Family Datasheet*.

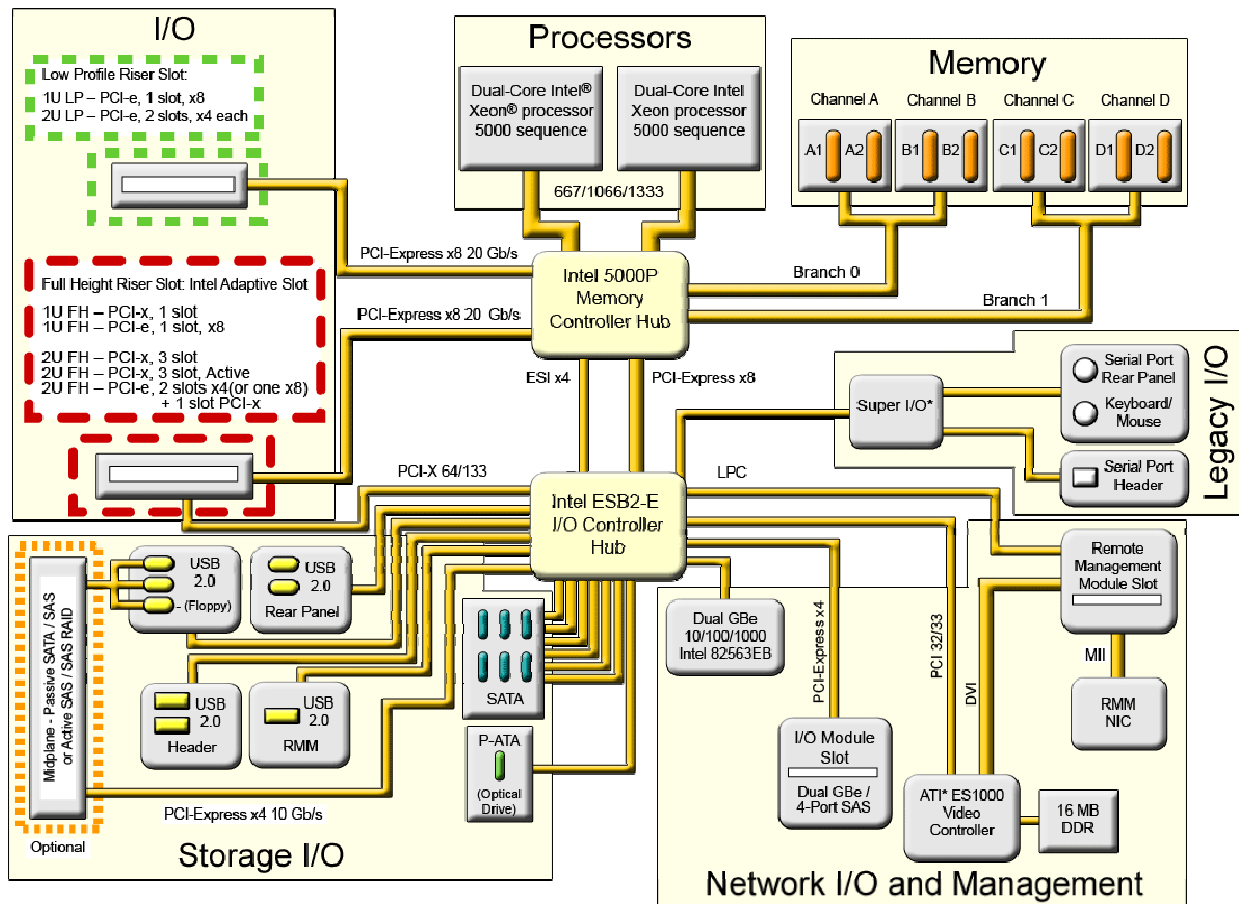


Figure 9. Server Board Functional Block Diagram

Note: The diagram above uses the Intel® 5000P MCH as a general reference designator for both MCH components supported on this server board.

3.1 Intel® 5000P and 5000X Memory Controller Hubs (MCH)

This section will describe the general functionality of the memory controller hub as it is implemented on this server board. Depending on the version of the server board in use, it may support either the Intel® 5000P MCH or the Intel® 5000X MCH. Features that are unique to a particular MCH will be so referenced.

The Memory Controller Hub (MCH) is a single 1432 pin FCBGA package which includes the following core platform functions:

- System Bus Interface for the processor sub-system
- Memory Controller
- PCI Express* Ports including the Enterprise South Bridge Interface (ESI)
- FBD Thermal Management
- SMBUS Interface

Additional information about MCH functionality can be obtained from the *Intel® S5000 Series Chipsets Server Board Family Datasheet*, the *Intel® 5000P Memory Controller Hub External Design Specification (Yellow Cover)*, or the *Intel® 5000X Memory Controller Hub External Design Specification (Yellow Cover)*.

Note: Yellow Cover documents can only be obtained under NDA with Intel and ordered through an Intel representative.

3.1.1 System Bus Interface

The MCH is configured for symmetric multi-processing across two independent front side bus interfaces that connect to the Dual-Core Intel® Xeon® processors 5000 sequence. Each front side bus on the MCH uses a 64-bit wide 1066 or 1333 MHz data bus. The 1333 MHz data bus is capable of transferring data at up to 10.66 GB/s. The MCH supports a 36-bit wide address bus, capable of addressing up to 64 GB of memory. The MCH is the priority agent for both front side bus interfaces, and is optimized for one processor on each bus.

3.1.2 Processor Support

The server board supports one or two Dual-Core Intel® Xeon® processors 5000 sequence, with system bus speeds of 667 MHz, 1066 MHz, and 1333 MHz, and core frequencies starting at 2.67 GHz. Previous generations of the Intel® Xeon® processor are not supported on this server board.

Note: Only Dual-Core Intel® Xeon® processors 5000 sequence, that support system bus speeds of 667 MHz, 1066 MHz, and 1333 MHz are supported on this server board. See the following table for a list of supported processors.

Dual-Core Intel® Xeon® processors 5000 sequence will encompass the following:

Table 1. Processor Support Matrix

Processor Family	System Bus Speed	Core Frequency	Cache	Watts	Support
Intel® Xeon® processor	533 MHz	All			No
Intel® Xeon® processor	800 MHz	All			No
Dual-Core Intel® Xeon® processor 5030	667 MHz	2.67 GHz	2x 2 MB	95	Yes
Dual-Core Intel® Xeon® processor 5050	667 MHz	3.0 GHz	2x 2 MB	95	Yes
Dual-Core Intel® Xeon® processor 5060	1066 MHz	3.2 GHz	2x 2 MB	130	Yes
Dual-Core Intel® Xeon® processor 5063	1066 MHz	3.2 GHz	2x 2 MB	95	Yes
Dual-Core Intel® Xeon® processor 5080	1066 MHz	3.73 GHz	2x 2 MB	130	Yes
Dual-Core Intel® Xeon® processor 5110	1066 MHz	1.60 GHz	4MB shared	65	Yes
Dual-Core Intel® Xeon® processor 5120	1066 MHz	1.87 GHz	4MB shared	65	Yes
Dual-Core Intel® Xeon® processor 5130	1333 MHz	2 GHz	4MB shared	65	Yes
Dual-Core Intel® Xeon® processor 5140	1333 MHz	2.33 GHz	4MB shared	65	Yes
Dual-Core Intel® Xeon® processor 5150	1333 MHz	2.67 GHz	4MB shared	65	Yes
Dual-Core Intel® Xeon® processor 5160	1333 MHz	3 GHz	4MB shared	80	Yes

3.1.2.1 Processor Population Rules

When two processors are installed, both must be of identical revision, core voltage, and bus/core speed. Mixed processor steppings is supported. However, the stepping of one processor cannot be greater than one stepping back of the other. When only one processor is installed, it must be in the socket labeled CPU1. The other socket must be empty.

The board is designed to provide up to 130A of current per processor. Processors with higher current requirements are not supported.

No terminator is required in the second processor socket when using a single processor configuration.

3.1.2.2 Common Enabling Kit (CEK) Design Support

The server board complies with Intel's Common Enabling Kit (CEK) processor mounting and heat sink retention solution. The server board ships with a CEK spring snapped onto the underside of the server board, beneath each processor socket. The heat sink attaches to the CEK, over the top of the processor and the thermal interface material (TIM). See the figure below for the stacking order of the chassis, CEK spring, server board, TIM, and heat sink.

The CEK spring is removable, allowing for the use of non-Intel heat sink retention solutions.

Note: The processor heat sink and CEK spring shown in the following diagram are for reference purposes only. The actual processor heat sink and CEK solutions compatible with this generation server board may be of a different design.

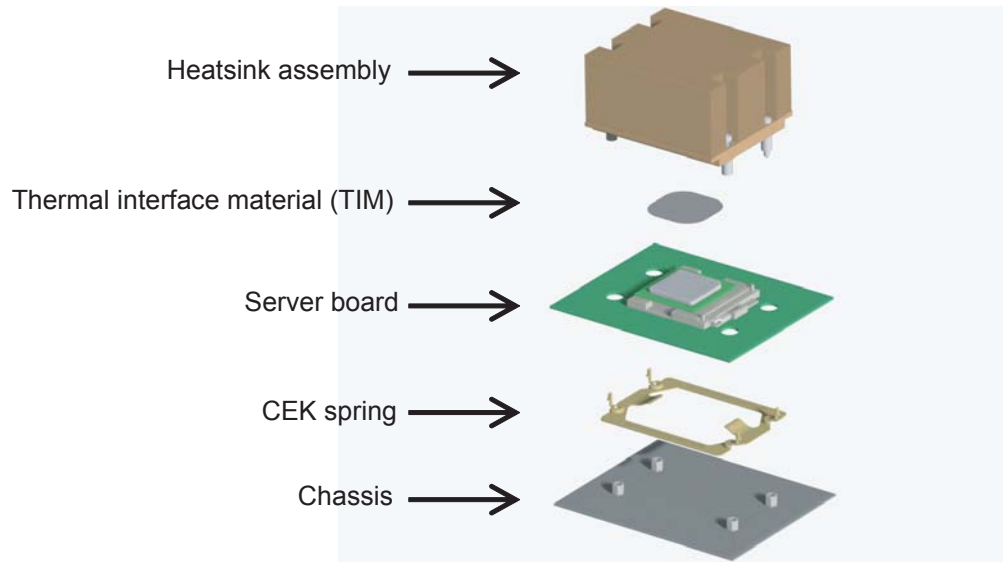
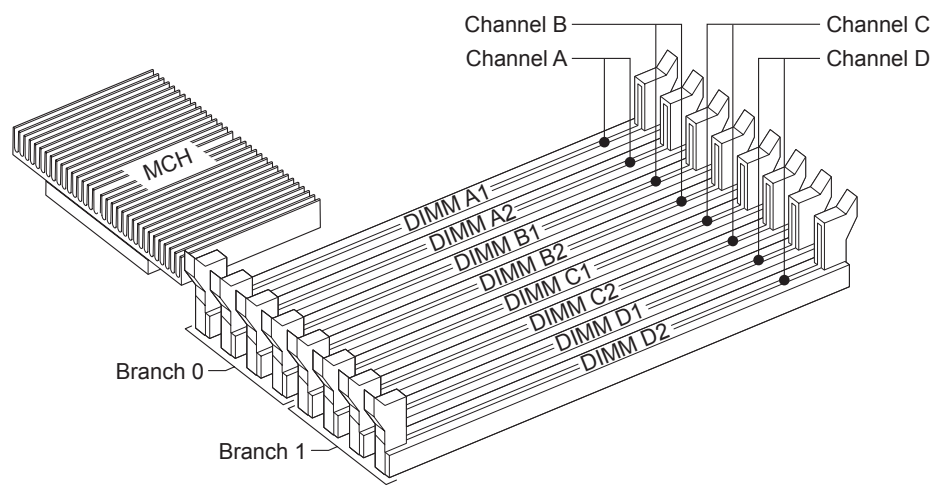


Figure 10. CEK Processor Mounting

3.1.3 Memory Sub-system

On the Intel® Server Board S5000PAL / S5000XAL, the MCH provides four channels of Fully Buffered DIMM (FB-DIMM) memory. Each channel can support up to 2 Dual Ranked FB-DIMM DDR2 DIMMs. FB-DIMM memory channels are organized in to two branches for support of RAID 1 (mirroring). The MCH can support up to 8 DIMMs or a maximum memory size of 32 GB physical memory in non-mirrored mode and 16 GB physical memory in a mirrored configuration. The read bandwidth for each FB-DIMM channel is 4.25 GB/s for DDR2 533 FB-DIMM memory which gives a total read bandwidth of 17 GB/s for four FB-DIMM channels. Thus, this provides 8.5 GB/s of write memory bandwidth for four FB-DIMM channels. The read bandwidth for each FB-DIMM channel is 5.3GB/s for DDR2 667 FB-DIMM memory which gives a total read bandwidth of 21GB/s for four FB-DIMM channels. Thus, this provides 10.7 GB/s of write memory bandwidth for four FB-DIMM channels. The total bandwidth is based on read bandwidth thus the total bandwidth is 17 GB/s for 533 and 21.0 GB/s for 667.

On the Intel® Server Board S5000PAL / S5000XAL, a pair of channels becomes a branch where Branch 0 consists of channels A and B, and Branch 1 consists of channels C and D. FBD memory channels are organized into two branches for support of RAID 1(mirroring).



TP02299

Figure 11. Memory Layout

To boot the system, the system BIOS on the server board uses a dedicated I²C bus to retrieve DIMM information needed to program the MCH memory registers. The following table provides the I²C addresses for each DIMM slot.

Table 2. I²C Addresses for Memory Module SMB

Device	Address
DIMM A1	0xA0
DIMM A2	0xA2
DIMM B1	0xA0
DIMM B2	0xA2
DIMM C1	0xA0
DIMM C2	0xA2
DIMM D1	0xA0
DIMM D2	0xA2

3.1.3.1 Memory RASUM Features¹

The MCH supports several memory RASUM (Reliability, Availability, Serviceability, Usability, and Manageability) features. These features include the Intel® x4 Single Device Data Correction (Intel® x4 SDDC) for memory error detection and correction, Memory Scrubbing, Retry on Correctable Errors, Memory Built In Self Test, DIMM Sparing, and Memory Mirroring. See the *Intel® S5000 Series Chipsets Server Board Family Datasheet* for more information describing these features.

3.1.3.2 Supported Memory

The server board supports up to eight DDR2-533 or DDR2-667 Fully Buffered DIMMs (FBD memory). The following tables show the maximum memory configurations supported using the specified memory technology.

Table 3. Maximum 8 DIMM System Memory Configuration – x8 Single Rank

DRAM Technology x8 Single Rank	Maximum Capacity Mirrored Mode	Maximum Capacity Non-Mirrored Mode
256 Mb	1 GB	2 GB
512 Mb	2 GB	4 GB
1024 Mb	4 GB	8 GB
2048 Mb	8 GB	16 GB

Table 4. Maximum 8 DIMM System Memory Configuration – x4 Dual Rank

DRAM Technology x4 Dual Rank	Maximum Capacity Mirrored Mode	Maximum Capacity Non-Mirrored Mode
256 Mb	4 GB	8 GB
512 Mb	8 GB	16 GB
1024 Mb	16 GB	32 GB
2048 Mb	16 GB	32 GB

Note: DDR2 DIMMs that are not fully buffered are NOT supported on this server board. See the *Intel® Server Board S5000PAL / S5000XAL Tested Memory List* for a complete list of supported memory for this server board.

3.1.3.3 DIMM Population Rules and Supported DIMM Configurations

DIMM population rules depend on the operating mode of the memory controller, which is determined by the number of DIMMs installed. DIMMs must be populated in pairs. DIMM pairs are populated in the following DIMM slot order: A1 & B1, C1 & D1, A2 & B2, C2 & D2. DIMMs within a given pair must be identical with respect to size, speed, and organization. However, DIMM capacities can be different between different DIMM pairs.

For example, a valid mixed DIMM configuration may have 512MB DIMMs installed in DIMM Slots A1 & B1, and 1GB DIMMs installed in DIMM slots C1 & D1.

Intel supported DIMM configurations for this server board are shown in the following table.

	Supported and Validated configuration : Slot is populated
	Supported but not validated configuration : Slot is populated
	Slot is not populated

Mirroring: Y = Yes. Indicates that configuration supports Memory Mirroring.
 Sparing: Y(x) = Yes. Indicates that configuration supports Memory Sparing.
 Where x = 0 : Sparing supported on Branch0 only
 1 : Sparing supported on Branch1 only
 0,1 : Sparing supported on both branches

Branch 0				Branch 1				Mirroring Possible	Sparing Possible
Channel A		Channel B		Channel C		Channel D			
DIMM_A1	DIMM_A2	DIMM_B1	DIMM_B2	DIMM_C1	DIMM_C2	DIMM_D1	DIMM_D2		
									Y (0)
								Y	
									Y (0)
								Y	Y (0, 1)

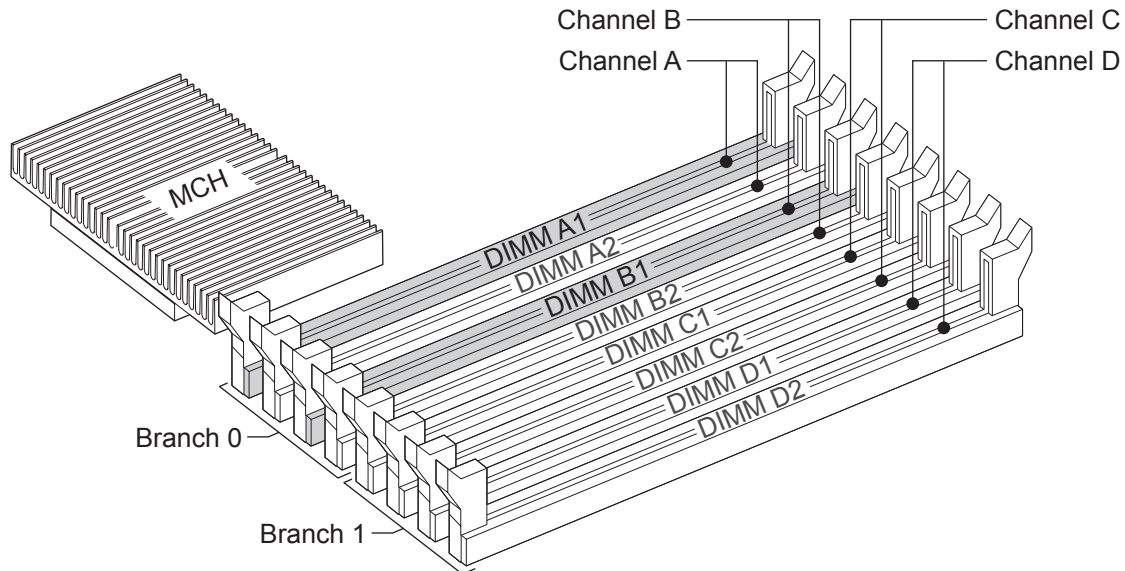
Notes:

- Single channel mode is only tested and supported with a 512MB x8 FBDIMM installed in DIMM Slot A1.
- The supported memory configurations must meet population rules defined above.
- **For best performance, the number of DIMMs installed should be balanced across both memory branches. For Example: a four DIMM configuration will perform better than a two DIMM configuration and should be installed in DIMM Slots A1, B1, C1, and D1. An eight DIMM configuration will perform better than a six DIMM configuration.**
- Although mixed DIMM capacities between channels is supported, Intel does not validate DIMMs in mixed DIMM configurations.

3.1.3.3.1 Minimum Non-Mirrored Mode Configuration

The server board is capable of supporting a minimum of one DIMM installed. However, for system performance reasons, Intel's recommendation is that at least 2 DIMMs be installed.

The following diagram shows the recommended minimum DIMM memory configuration. Populated DIMM slots are shown in **Grey**.



TP02300

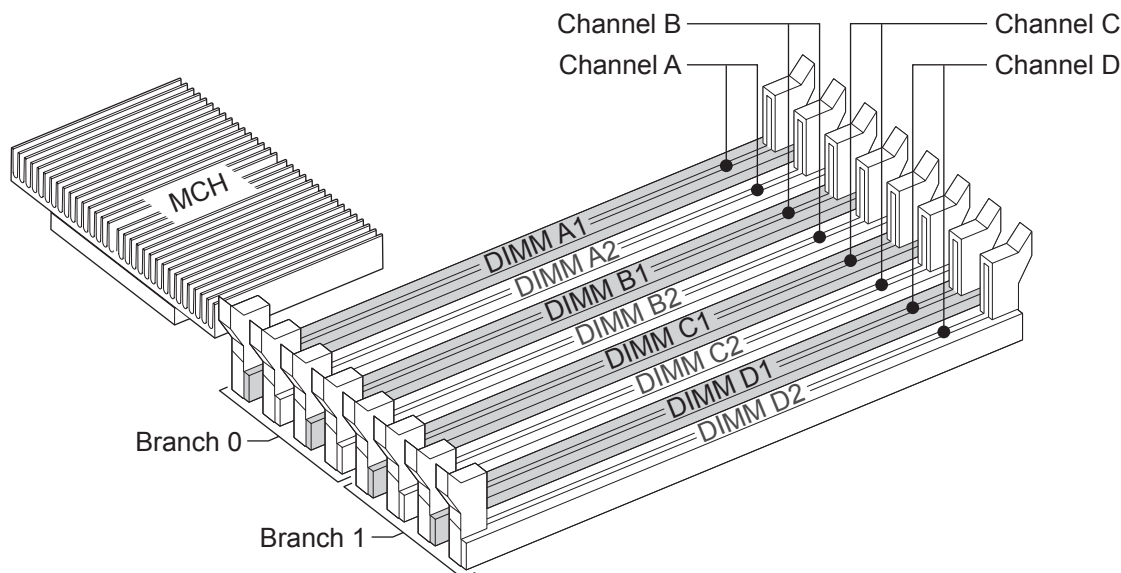
Figure 12. Recommended Minimum Two DIMM Memory Configuration

Note: The server board supports single DIMM mode operation. Intel will only validate and support this configuration with a single 512MB x8 FBDIMM installed in DIMM slot A1.

3.1.3.4 Non-mirrored mode memory upgrades

The minimum memory upgrade increment is two DIMMs per branch. The DIMMs must cover the same slot position on both channels. DIMMs pairs must be identical with respect to size, speed, and organization. DIMMs that cover adjacent slot positions do not need to be identical.

When adding two DIMMs to the configuration shown in Figure 12, the DIMMs should be populated in DIMM slots C1 and D1 as shown in the following diagram. Populated DIMM slots are shown in **Grey**.



TP02301

Figure 13. Recommended Four DIMM Configuration

Functionally, DIMM slots A2 and B2 could also have been populated instead of DIMM slots C1 and D1. However, your system will not achieve equivalent performance. Figure 13 shows the supported DIMM configuration that is recommended because it allows both memory branches from the MCH to operate independently and simultaneously. FBD bandwidth is doubled when both branches operate in parallel.

3.1.3.4.1 Mirrored Mode Memory Configuration

When operating in mirrored mode, both branches operate in lock step. In mirrored mode, branch 1 contains a replicate copy of the data in branch 0. The minimum DIMM configuration to support memory mirroring is four DIMMs, populated as shown in Figure 13 above. All four DIMMs must be identical with respect to size, speed, and organization.

To upgrade a four DIMM mirrored memory configuration, four additional DIMMs must be added to the system. All four DIMMs in the second set must be identical to the first with the exception of speed. The MCH will adjust to the lowest speed DIMM.

3.1.3.4.2 DIMM Sparing Mode Memory Configuration

The MCH provides DIMM sparing capabilities. Sparing is a RAS feature that involves configuring a DIMM to be placed in reserve so it can be used to replace a DIMM that fails. DIMM sparing occurs within a given bank of memory and is not supported across branches.

There are two supported Memory Sparing configurations.

3.1.3.4.2.1 Single Branch Mode Sparing

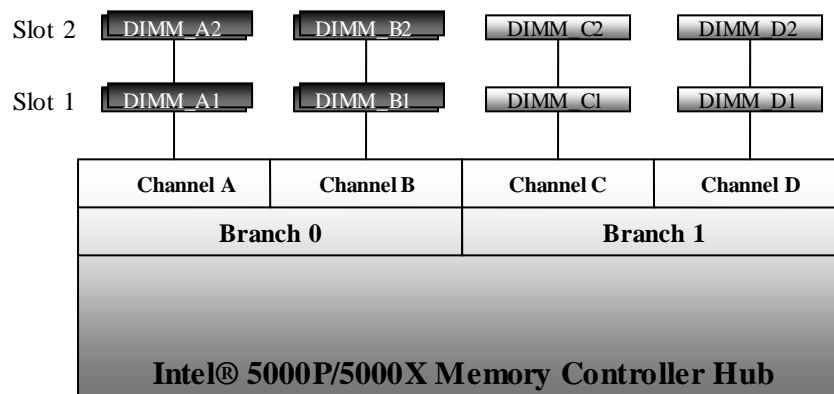


Figure 14. Single Branch Mode Sparing DIMM Configuration

- DIMM_A1 and DIMM_B1 must be identical in organization, size and speed.
- DIMM_A2 and DIMM_B2 must be identical in organization, size and speed.
- DIMM_A1 and DIMM_A2 need not be identical in organization, size and speed.
- DIMM_B1 and DIMM_B2 need not be identical in organization, size and speed.
- Sparing should be enabled in BIOS setup.
- BIOS will configure Rank Sparing Mode.
- The larger of the pairs {DIMM_A1, DIMM_B1} and {DIMM_A2, DIMM_B2} will be selected as the spare pair unit.

3.1.3.4.2.2 Dual Branch Mode Sparing

Dual branch mode sparing requires that all eight DIMM slots be populated and must comply with the following population rules.

- DIMM_A1 and DIMM_B1 must be identical in organization, size and speed.
- DIMM_A2 and DIMM_B2 must be identical in organization, size and speed.
- DIMM_C1 and DIMM_D1 must be identical in organization, size and speed.
- DIMM_C2 and DIMM_D2 must be identical in organization, size and speed.
- DIMM_A1 and DIMM_A2 need not be identical in organization, size and speed.
- DIMM_B1 and DIMM_B2 need not be identical in organization, size and speed.
- DIMM_C1 and DIMM_C2 need not be identical in organization, size and speed.
- DIMM_D1 and DIMM_D2 need not be identical in organization, size and speed.
- Sparing should be enabled in BIOS setup.
- BIOS will configure Rank Sparing Mode.
- The larger of the pairs {DIMM_A1, DIMM_B1} and {DIMM_A2, DIMM_B2} and {DIMM_C1, DIMM_D1} and {DIMM_C2, DIMM_D2} will be selected as the spare pair units.

3.1.4 Snoop Filter (5000X MCH only)

The 5000X version of the MCH includes a snoop filter. Depending on the application of the server, this feature can be used to enhance the performance of the server by eliminating unnecessary traffic on the system bus. By removing the excess traffic from the snooped bus, the full bandwidth is available for other operations.

3.2 ESB-2 IO Controller

The ESB-2 is a multi-function device that provides four distinct functions: an IO Controller, a PCI-X* Bridge, a Gigabit Ethernet Controller, and a Baseboard Management Controller (BMC). Each function within the ESB-2 has its own set of configuration registers. Once configured, each appears to the system as a distinct hardware controller.

A primary role of the ESB-2 is to provide the gateway to all PC-compatible I/O devices and features. The server board uses the following ESB-2 features:

- PCI-X* bus interface
- Six Channel SATA interface w/SATA Busy LED Control
- Dual GbE MAC
- Baseboard Management Controller (BMC)
- Single ATA interface, with Ultra DMA 100 capability
- Universal Serial Bus 2.0 (USB) interface
- Removable Media Drives
- LPC bus interface
- PC-compatible timer/counter and DMA controllers
- APIC and 8259 interrupt controller
- Power management
- System RTC
- General purpose I/O

This section describes the function of most of the listed features as they pertain to this server board. For more detail information, see the *Intel® S5000 Series Chipsets Server Board Family Datasheet* or the *Intel® Enterprise South Bridge-2 External Design Specification* (Yellow Cover)

3.2.1 PCI Sub-system

The primary I/O buses for the server board are PCI, PCI Express*, and PCI-X*, with six independent PCI bus segments. The PCI buses comply with the *PCI Local Bus Specification*, Revision 2.3. The table below lists the characteristics of the PCI bus segments. Details about each bus segment follow the table.

Table 5. PCI Bus Segment Characteristics

PCI Bus Segment	Voltage	Width	Speed	Type	On-board Device Support
PCI32 ESB-2	3.3V	32 bit	33MHz	PCI	Used internally for video controller
PXA ESB-2	3.3V/5.0V	64 bit	133MHz	PCI-X*	Full height riser slot, up to three slots on riser card
PE1 ESB-2 PCIe* Port2	3.3V	x4	10Gb/S	PCIe*	Used for Intel chassis for mid-plane IOP
PE2 ESB-2 PCIe Port3	3.3V	x4	10Gb/S	PCIe	Mezzanine connector for Intel® I/O Expansion Module
PE4, PE5 BNB PCIe Ports 4,5	3.3V	x8	20Gb/S	PCIe	Low profile riser slot, up to two x4 slots on 2U riser, or one x8 slot on 1U riser.
PE6, PE7 BNB PCIe Ports 6,7	3.3V	x8	20Gb/S	PCIe	Full height riser slot, up to two x4 slots on riser or one x8

3.2.1.1 PCI32: 32-bit, 33-MHz PCI Bus Segment

All 32-bit, 33-MHz PCI I/O is directed through the ESB-2 ICH6. The 32-bit, 33-MHz PCI segment created by the ESB-2-ICH6 is known as the PCI32 segment. The PCI32 segment supports the following embedded devices:

- 2D Graphics Accelerator: ATI* ES1000 Video Controller

3.2.1.2 PXA: 64-bit, 133MHz PCI-X* Bus Segment

One 64-bit PCI-X* bus segment is directed through the ESB-2 ICH6. This PCI-X segment, PXA, can support up to three add-in cards on a riser card plugged into the full height riser card slot (J4F1).

3.2.1.3 PE1: One x4 PCI Express* Bus Segment

One x4 PCI Express* bus segment is directed through the ESB-2. This PCI Express segment, PE1, supports the optional Active SAS Midplane IOP as used in supported Intel chassis for this server board.

3.2.1.4 PE2: One x4 PCI Express* Bus Segment

One x4 PCI Express* bus segment is directed through the ESB-2. This PCI Express segment, PE2, supports one x4 PCI Express segment to the proprietary Intel® I/O Expansion Module mezzanine connector (J3B1).

3.2.1.5 PE4, PE5: Two x4 PCI Express* Bus Segments

Two x4 PCI Express* bus segments are directed through the MCH. These PCI Express segments, PE4 and PE5, support one x8 or two x4 PCI Express segments to the low profile riser slot (J5B1).

3.2.1.6 PE6, PE7: Two x4 PCI Express* Bus Segments

Two x4 PCI Express* bus segments are directed through the MCH. These PCI Express segments, PE6 and PE7, support one x8 or two x4 PCI Express segments to the full height riser slot (J4F1).

3.2.1.7 PCI Riser Slots

The server board has two riser slots capable of supporting riser cards for both 1U and 2U system configurations. Because of board placement resulting in different pin orientations, and expanded technology support associated with the full-height riser, the riser slots are not the same and require different riser cards.

The low profile riser slot (J5B1) utilizes a 98-pin connector. It is capable of supporting one x8 (1U) or two x4 (2U) low profile PCI Express* add-in cards. The x8 PCI Express* bus can support bus speeds of up to 20 Gb/S. The following table provides the supported bus throughput for the given riser card used and the number of add-in cards installed.

Low Profile Riser	1 add-in card populated	2 add-in cards populated
1U – 1 add-in card slot	x8 or x4	NA
2U – 2 add-in card slots	x4	x4

Note: There are no population rules for installing a single low profile add-in card in the 2U LP riser card; a single add in card can be installed in either PCI Express* slot. While each slot can accommodate a x8 card, each slot will only support x4 bus speeds.

The full height riser slot (J4F1) implements Intel® Adaptive Slot Technology. This 280-pin connector is capable of supporting riser cards that meet either the PCI-X* or PCI Express* technology specifications. The following tables show the maximum bus speed supported with different add-in card populations for each supported riser card.

Full Height PCI-X* (Passive) Riser	1 add-in card populated	2 add-in cards populated	3 add-in cards populated
1U – 1 add-in card slot	Up to 133MHz	NA	NA
2U – 3 add-in card slots	Up to 100MHz in top PCI slot	Up to 100MHz using top and middle slots	66MHz

Note: For the 2U PCI-X* (passive) riser card, add-in cards should be installed starting with the top slot first, followed by the middle, and then the bottom. Any add-in card populated in the bottom PCI slot will cause the bus to operate at 66MHz.

Full Height PCI-X* (Active) Riser	1 add-in card populated	2 add-in cards populated	3 add-in cards populated
2U – 3 add-in card slots	Up to 133MHz	Up to 133MHz	Up to 133MHz

Note: Each PCI slot on the 2U PCI-X* (active) riser card operates on an independent PCI bus. Therefore, using an add-in card that operates below 133MHz will not affect the bus speed of the other PCI slots.

Full Height PCI Express* Riser	1 add-in card populated	2 add-in cards populated	3 add-in cards populated
1U – 1 add-in card slot	x4 or x8	NA	NA
2U – 3 add-in card slots	Single PCIe* x4 in either slot or x8 in middle slot Or PCI-X* – Up to 133MHz in bottom slot	Single PCIe* – x4 in either slot or x8 in middle slot and PCI-X* – Up to 133MHz Or Dual PCIe – x4	Dual PCIe* – x4 And PCI-X* – Up to 133MHz

3.2.2 Serial ATA Support

The ESB-2 has an integrated Serial ATA (SATA) controller that supports independent DMA operation on six ports and supports data transfer rates of up to 3.0 Gb/s. The six SATA ports on the server board are numbered SATA-0 thru SATA-5. The SATA ports can be enabled/disabled and/or configured by accessing the BIOS Setup Utility during POST.

3.2.2.1 Intel® Embedded Server RAID Technology II Support

The onboard storage capability of this server board includes support for Intel® Embedded Server RAID Technology which provides three standard software RAID levels: data stripping (RAID Level 0), data mirroring (RAID Level 1), and data stripping with mirroring (RAID Level 10). For higher performance, data stripping can be used to alleviate disk bottlenecks by taking advantage of the dual independent DMA engines that each SATA port offers. Data mirroring is used for data security. Should a disk fail, a mirrored copy of the failed disk is brought on-line. There is no loss of either PCI resources (request/grant pair) or add-in card slots.

With the addition of an optional Intel RAID Activation Key, Intel® Embedded Server RAID Technology is also capable of providing fault tolerant data stripping (software RAID Level 5), such that if a SATA hard drive should fail, the lost data can be restored on a replacement drive from the other drives that make up the RAID 5 pack.

See Figure 1. Components & Connector Location Diagram for the location of Intel RAID Activation Key connector location.

Note: Availability of the Intel RAID Activation Key to support software RAID 5 will be deferred until after product launch of this server board.

Intel® Embedded Server RAID Technology functionality requires the following items:

- Intel® ESB-2 IO Controller Hub
- Intel® Embedded Server RAID Technology Option ROM
- Intel® Application Accelerator RAID Edition drivers, most recent revision
- At least two SATA hard disk drives

Intel® Embedded Server RAID Technology is not available in the following configurations:

- The SATA controller in compatible mode
- Intel® Embedded Server RAID Technology has been disabled

3.2.2.2 Intel® Embedded Server RAID Technology Option ROM

The Intel® Embedded Server RAID Technology for SATA Option ROM provides a pre-OS user interface for the Intel® Embedded Server RAID Technology implementation and provides the ability for an Intel® Embedded Server RAID Technology volume to be used as a boot disk as well as to detect any faults in the Intel® Embedded Server RAID Technology volume(s) attached to the Intel® RAID controller.

3.2.3 Parallel ATA (PATA) Support

The integrated IDE controller of the ESB-2 ICH6 provides one IDE channel. It redefines signals on the IDE cable to allow both host and target throttling of data and transfer rates of up to 100MB/s. For this server board, the IDE channel was designed to provide Slim-line Optical Drive support to the platform. The BIOS initializes and supports ATAPI devices such as CDROM, CD-RW and DVD. The IDE channel is accessed through a single high density 44-pin connector ((J3G1) which provides both power and IO signals. The ATA channel can be configured and enabled or disabled by accessing the BIOS Setup Utility during POST.

Note: The IDE connector on this server board is NOT a standard 40 IDE connector. Instead, this connector has an additional 4 power pins over and above the standard 40 I/O pins. The design intent of this connector is to provide support for a slim-line optical drive only.

3.2.4 USB 2.0 Support

The USB controller functionality integrated into ESB-2 provides the server board with the interface for up to eight USB 2.0 ports. Two external connectors are located on the back edge of the server board. One internal 2x5 header is provided, capable of supporting two optional USB 2.0 ports. Three USB ports are routed through the bridge board connector providing optional USB support for a system Control Panel or other USB requirements. An additional USB port is dedicated to the Intel® Remote Management Module (Intel® RMM) connector.

3.3 Video Support

The server board provides an ATI* ES1000 PCI graphics accelerator, along with 16MB of video DDR SDRAM and support circuitry for an embedded SVGA video sub-system. The ATI ES1000 chip contains an SVGA video controller, clock generator, 2D engine, and RAMDAC in a 359-pin BGA. One 4Mx16x4 bank DDR SDRAM chip provides 16MB of video memory.

The SVGA sub-system supports a variety of modes, up to 1024 x 768 resolution in 8 / 16 / 32bpp modes under 2D. It also supports both CRT and LCD monitors up to a 100 Hz vertical refresh rate.

Video is accessed using a standard 15-pin VGA connector found on the back edge of the server board. Video signals are also made available through the 120-pin bridgeboard connector which provides signals for an optional video connector to be present on the platform's control panel. Video is routed to both the rear video connector and a control panel video connector. Video is present at both connectors simultaneously and cannot be disabled at either connector individually. Hot plugging the video while the system is still running is supported.

On-board video can be disabled using the BIOS Setup Utility or when an add-in video card is installed. System BIOS also provides the option for dual video operation when an add-in video card is configured in the system.

3.3.1.1 Video Modes

The ATI ES1000 chip supports all standard IBM* VGA modes. The following table shows the 2D modes supported for both CRT and LCD.

Table 6. Video Modes

2D Mode	Refresh Rate (Hz)	2D Video Mode Support		
		8 bpp	16 bpp	32 bpp
640x480	60, 72, 75, 85, 90, 100, 120, 160, 200	Supported	Supported	Supported
800x600	60, 70, 72, 75, 85, 90, 100, 120, 160	Supported	Supported	Supported
1024x768	60, 70, 72, 75, 85, 90, 100	Supported	Supported	Supported
1152x864	43, 47, 60, 70, 75, 80, 85	Supported	Supported	Supported
1280x1024	60, 70, 74, 75	Supported	Supported	Supported
1600x1200	52	Supported	Supported	Supported

3.3.1.2 Video Memory Interface

The memory controller sub-system of the ES1000 arbitrates requests from the direct memory interface, the VGA graphics controller, the drawing co-processor, the display controller, the video scalar, and the hardware cursor. Requests are serviced in a manner that ensures display integrity and maximum CPU/co-processor drawing performance.

The server board supports a 16MB (4Meg x 16-bit x 4 banks) DDR SDRAM device for video memory.

3.3.1.3 Dual Video

The BIOS supports single and dual video modes. The dual video mode is enabled by default.

- In single mode (Dual Monitor Video = Disabled), the on-board video controller is disabled when an add-in video card is detected.
- In dual mode (On-board Video = Enabled, Dual Monitor Video = Enabled), the on-board video controller is enabled and will be the primary video device. The external video card will be allocated resources and is considered the secondary video device. BIOS Setup provides user options to configure the feature as follows.

On-board Video	Enabled Disabled	
Dual Monitor Video	Enabled Disabled	Shaded if on-board video is set to "Disabled"

3.4 Network Interface Controller (NIC)

Network interface support is provided from the built in Dual GbE MAC features of the ESB-2 in conjunction with the Intel® 82563EB compact Physical Layer Transceiver (PHY). Together, they provide the server board with support for dual LAN ports designed for 10/100/1000 Mbps operation.

The 82563EB device is based upon proven PHY technology integrated into the Intel® Gigabit Ethernet Controllers. The physical layer circuitry provides a standard IEEE 802.3 Ethernet interface for 1000BASE-T, 100BASE-TX, and 10BASE-T applications (802.3, 802.3u, and 802.3ab). The 82563EB device is capable of transmitting and receiving data at rates of 1000 Mbps, 100 Mbps, or 10 Mbps

Each Network Interface Controller (NIC) drives two LEDs located on each network interface connector. The link/activity LED (to the right of the connector) indicates network connection when on, and Transmit/Receive activity when blinking. The speed LED (to the left of the connector) indicates 1000-Mbps operation when amber, 100-Mbps operation when green, and 10-Mbps when off. The table below provides an overview of the LEDs.

Table 7. NIC2 Status LED

LED Color	LED State	NIC State
Green/Amber (Left)	Off	10 Mbps
	Green	100 Mbps
	Amber	1000 Mbps
Green (Right)	On	Active Connection
	Blinking	Transmit / Receive activity

3.4.1 Intel® I/O Acceleration Technology

Intel® I/O Acceleration Technology moves network data more efficiently through Dual-Core Intel® Xeon® processor 5000 sequence-based servers for improved application responsiveness across diverse operating systems and virtualized environments. Intel® I/OAT improves network application responsiveness by unleashing the power of Dual-Core Intel® Xeon® processors 5000 sequence through more efficient network data movement and reduced system overhead. Intel multi-port network adapters with Intel® I/OAT provide high-performance I/O for server consolidation and virtualization via stateless network acceleration that seamlessly scales across multiple ports and virtual machines. Intel® I/OAT provides safe and flexible network acceleration through tight integration into popular operating systems & virtual machine monitors, avoiding the support risks of 3rd-party network stacks and preserving existing network requirements such as teaming and failover.

3.4.2 MAC Address Definition

Each Intel® Server Board S5000PAL / S5000XAL has four MAC addresses assigned to it at the Intel factory. During the manufacturing process, each server board will have a white MAC address sticker placed on the board. The sticker will display the MAC address in both bar code and alpha numeric formats. The printed MAC address is assigned to NIC 1 on the server board. NIC 2 is assigned the NIC 1 MAC address + 1.

Two additional MAC addresses are assigned to the Baseboard Management Controller (BMC) embedded in the ESB-2. These MAC addresses are used by the BMC's embedded network stack to enable IPMI remote management over LAN. BMC LAN Channel 1 is assigned the NIC1 MAC address + 2, and BMC LAN Channel 2 is assigned the NIC1 MAC address + 3.

3.5 Super I/O

Legacy I/O support is provided by using a National Semiconductor* PC87427 Super I/O device. This chip contains all of the necessary circuitry to support the following functions:

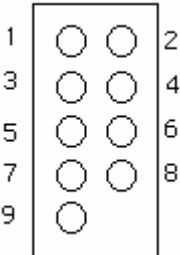
- GPIOs
- Two serial ports
- Keyboard and mouse support
- Wake up control
- System health support

3.5.1.1 Serial Ports

The server board provides two serial ports: an external RJ45 serial port, and an internal DH10 serial header.

Serial A is an optional port accessed through a 9-pin internal DH-10 header. A standard DH10 to DB9 cable can be used to direct the Serial A port to the rear of a chassis. The Serial A interface follows the standard RS232 pin-out as defined in the following table.

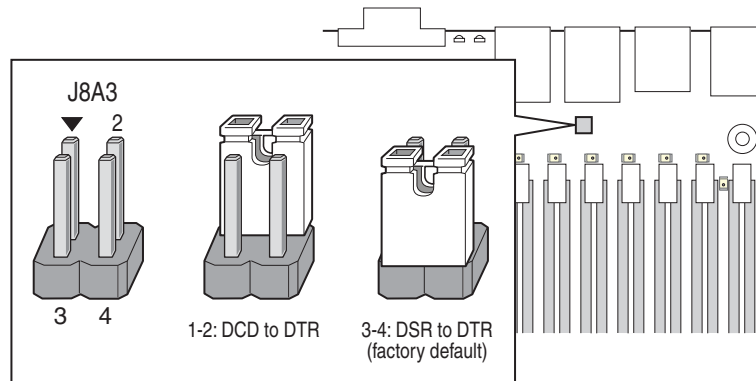
Table 8. Serial A Header Pin-out

Pin	Signal Name	Serial Port A Header Pin-out
1	DCD	
2	DSR	
3	RX	
4	RTS	
5	TX	
6	CTS	
7	DTR	
8	RI	
9	GND	

The rear RJ45 Serial B port is a fully functional serial port that can support any standard serial device. Using an RJ45 connector for a serial port allows direct support for serial port concentrators, which typically use RJ45 connectors and are widely used in the high-density server market. For server applications that use a serial concentrator to access the system management features of the server board, a standard 8-pin CAT-5 cable from the serial concentrator is plugged directly into the rear RJ45 serial port.

To allow support for either of two serial port configuration standards, a jumper block located directly behind the rear RJ45 serial port must be configured appropriately according to the desired standard. For serial concentrators that require a DCD signal, the jumper block must be configured with the serial port jumper over pins 1 and 2. For serial concentrators that require a DSR signal (Default), the jumper block must be configured with the serial port jumper over pins 3 and 4. Pin 1 on the jumper is identified by “*”.

Note: By default, the rear RJ45 serial port is configured to support a DSR signal. This configuration is compatible with the Cisco* standard.



TP02303

Figure 15. Serial Port Configuration Jumper Location

Pins	What happens at system reset...
1-2	Serial port is configured for DCD to DTR
3-4	Serial port is configured for DSR to DTR (default)

For server applications that require a DB9 serial connector, an 8-pin RJ45-to-DB9 adapter must be used. The following table provides the pin-out required for the adapter to provide RS232 support. A standard DH10-to-DB9 cable and 8-pin RJ45 to DB9 DCD and DSR adapters are available from Intel in the Serial Port Accessory Kit, product code: AXXRJ45DB92.

Table 9. Rear Serial B Port Adapter Pin-out

RJ45	Signal	Abbreviation	DB9
1	Request to Send	RTS	7
2	Data Terminal Ready	DTR	4
3	Transmitted Data	TD	3
4	Signal Ground	SGND	5
5	Ring Indicator	RI	9
6	Received Data	RD	2
7	DCD or DSR	DCD/DSR	1 or 6 (see note)
8	Clear To Send	CTS	8

Note: The RJ45-to-DB9 adapter should match the configuration of the serial device used. One of two pin-out configurations is used, depending on whether the serial device requires a DSR or DCD signal. The final adapter configuration should also match the desired pin-out of the RJ45 connector, as it can also be configured to support either DSR or DCD.

3.5.1.2 Floppy Disk Controller

The server board does not support a floppy disk controller (FDC) interface. However, the system BIOS does recognize USB floppy devices.

3.5.1.3 Keyboard and Mouse Support

Dual stacked PS/2 ports, located on the back edge of the server board, are provided for keyboard and mouse support. Either port can support a mouse or keyboard. Neither port supports hot plugging.

3.5.1.4 Wake-up Control

The super I/O contains functionality that allows various events to power-on and power-off the system.

3.5.1.5 System Health Support

The super I/O provides an interface via GPIOs for BIOS and Server Management Firmware to activate the Diagnostic LEDs, the FRU fault indicator LEDs for processors, DIMMs, fans and the system status LED. Refer to Figure 2. Light Guided Diagnostic LED Location Diagram for the location of the LEDs on the baseboard.

The super I/O also provides PWM fan control to the system fans, monitors tach and presence signals for the system fans and monitors baseboard and control panel temperature.

4. Platform Management

The platform management sub-system on the server board is based on the integrated Baseboard Management Controller (BMC) features of the ESB-2. The on board platform management subsystem consists of communication buses, sensors, system BIOS, and server management firmware. The following diagram provides an overview of the Server Management Bus (SMBUS) architecture used on this server board.

See Appendix B for onboard sensor data.

For more detailed platform management information, see the *Intel® S5000 Server Board Family Datasheet*.

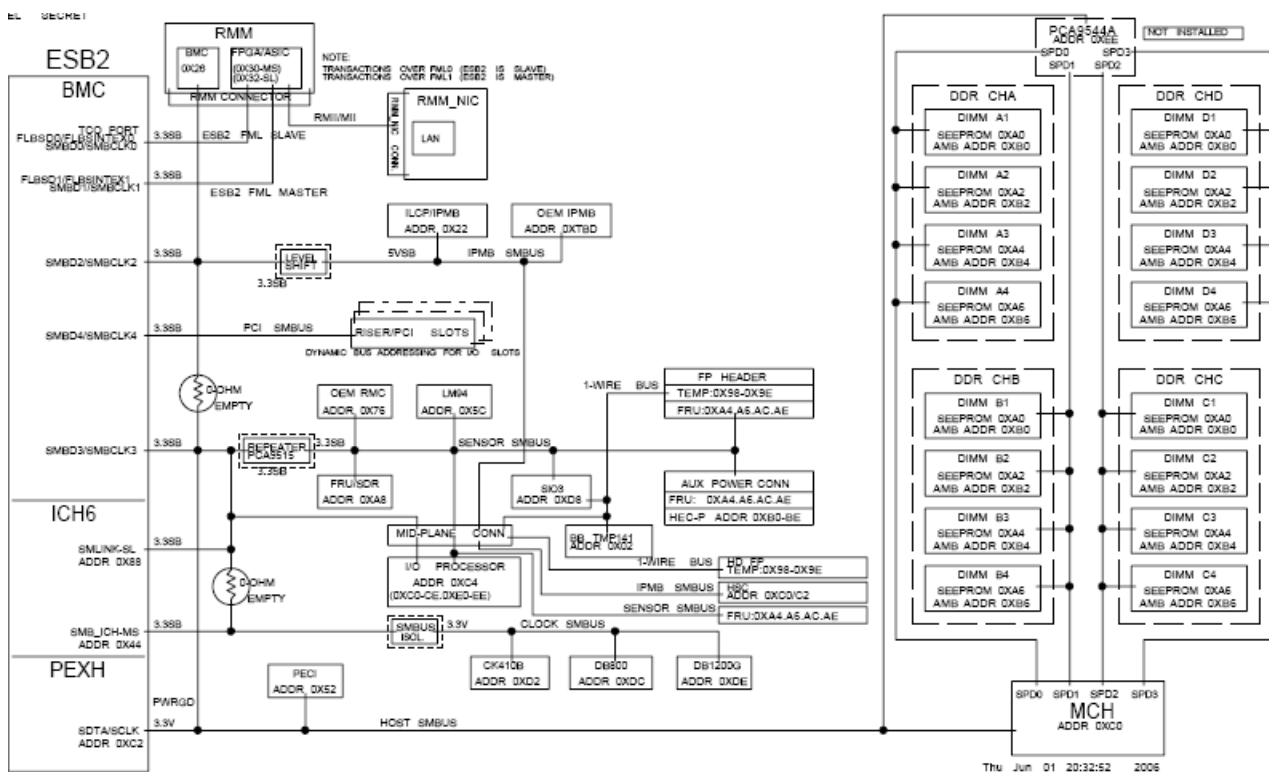
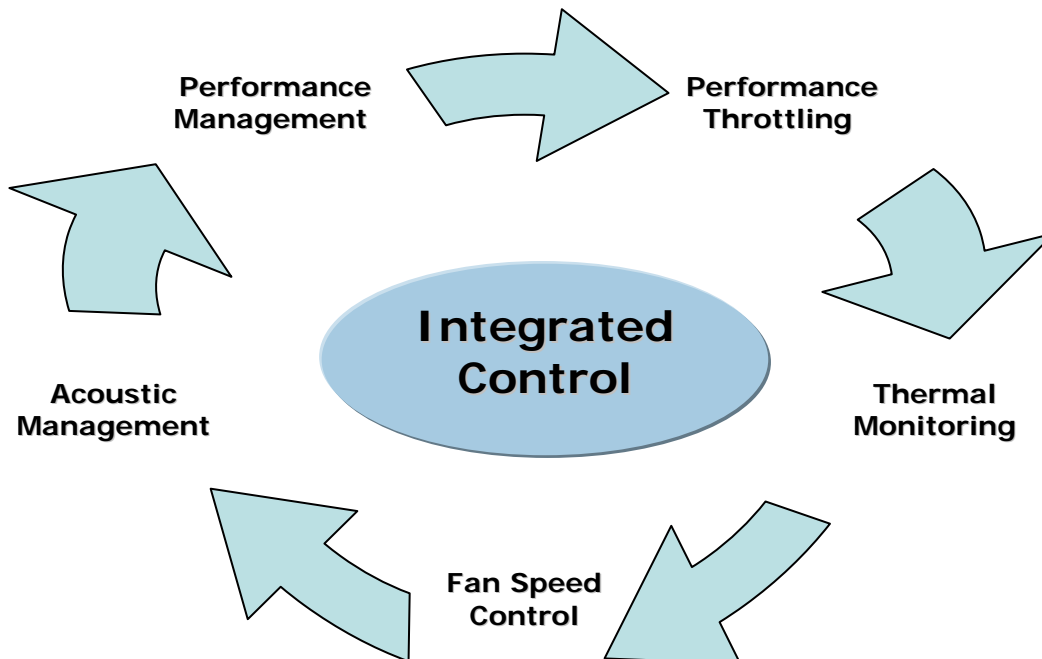


Figure 16. SMBUS Block Diagram

4.1 Platform Control

This server board has embedded platform control which is capable of automatically adjusting system performance and acoustic levels.



4.1.1 Overview

Platform control optimizes system performance and acoustics levels through:

- Performance Management
- Performance Throttling
- Thermal Monitoring
- Fan Speed Control
- Acoustics Management

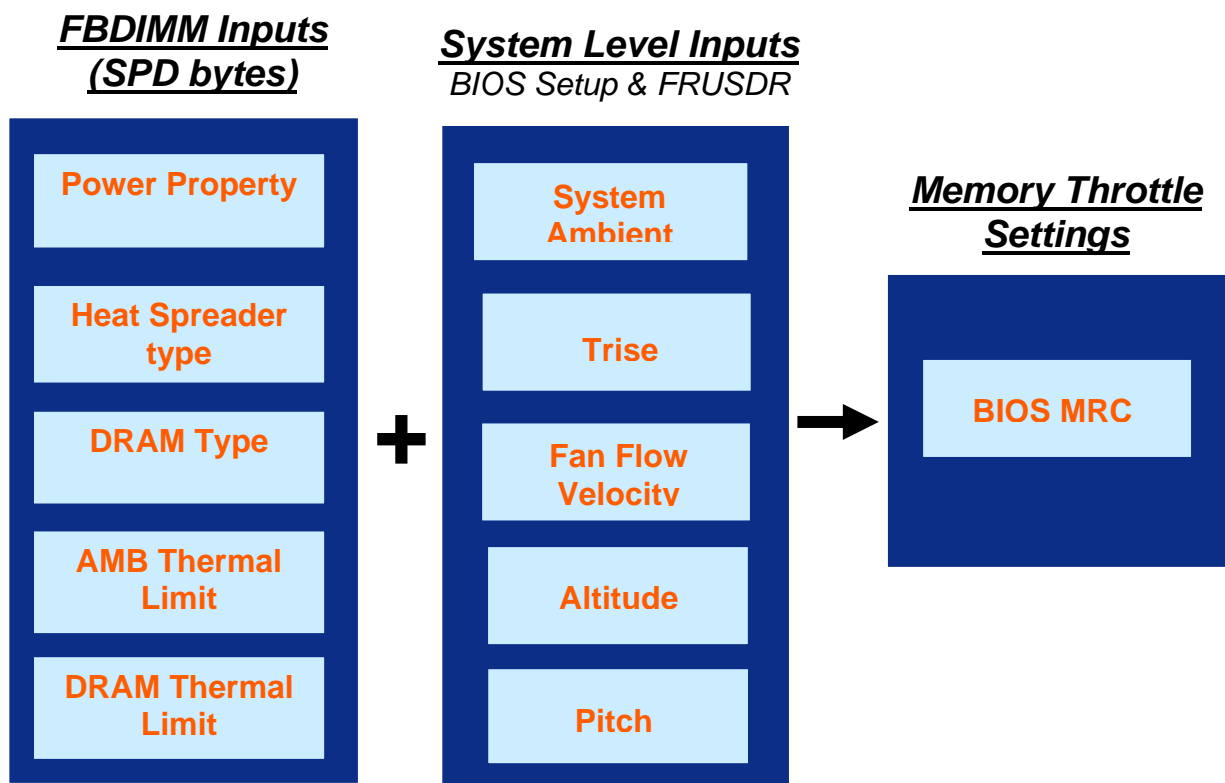
The platform components used to implement platform control include:

- Baseboard Management Controller functions of the ESB-2
- LM94 Sensor Monitoring Chip
- Platform Sensors
- Variable Speed System Fans
- System BIOS
- BMC Firmware
- Sensor Data Records as loaded by the FRUSDR Utility
- FBDIMM type
- Processor type

4.1.2 FBDIMM Open Loop Throughput Throttling

Memory throttling is a feature of the Intel 5000 sequence chipsets to prevent FBDIMM memory from overheating. If the performance of the installed FBDIMMs approaches their supported thermal limit for a given platform, system BIOS will initiate memory throttling which manages memory performance by limiting bandwidth to the DIMMs, therefore capping the power consumption and preventing the DIMMs from overheating. Memory throttling can be minimized by operating your platform in “Performance Mode” (default) which changes the system Fan Control profile to run the system fans at higher speeds. Running the platform in “Acoustics Mode” will cause the system fans to run slower to meet the acoustic limits for the given platform.

System BIOS utilizes a Memory Reference Code (MRC) throttling algorithm to maximize memory bandwidth for a given configuration when memory throttling is initialized. The MRC code relies on Serial Presence Detect (SPD) data read from the installed DIMMs as well as system level data as set through BIOS Setup Options and the FRUSDR Utility.



4.1.3 Fan Speed Control

System fan speed is controlled by the Baseboard Management Controller (BMC) functions of the ESB-2 chip. During normal system operation, the BMC will retrieve information from BIOS and monitor several platform thermal sensors to determine the required fan speeds.

In order to provide the proper fan speed control for a given system configuration, the BMC must have the appropriate platform data programmed. Platform configuration data is programmed using the FRUSDR Utility during the system integration process and by the system BIOS during run time.

4.1.3.1 System Configuration Using the FRUSDR Utility

The Field Replaceable Unit & Sensor Data Record Update Utility (FRUSDR utility) is a program used to write platform specific configuration data to NVRAM on the server board. It allows the User to select which supported chassis (Intel or Non-Intel) and platform chassis configuration is being used. Based on the input provided, the FRUSDR writes sensor data specific to the configuration to NVRAM for the BMC controller to read each time the system is powered on.

4.1.3.2 Fan Speed Control from BMC and BIOS Inputs

Using the data programmed to NVRAM by the FRUSDR utility, the BMC is configured to monitor and control the appropriate platform sensors and system fans each time the system is powered on. After power-on, the BMC uses additional data provided to it by System BIOS to determine how the system fans should be controlled.

The BIOS provides data to the BMC telling it which fan profile the platform is setup for, Acoustics Mode or Performance Mode. The BIOS uses the parameters retrieved from the thermal sensor data records (SDR), the fan profile setting from BIOS setup, and the altitude setting from BIOS setup to configure the system for memory throttling and fan speed control. If the BIOS fails to get the thermal SDRs, then it will use the Memory Reference Code (MRC) default settings for the memory throttling settings.

The <F2> BIOS Setup Utility provides options to set the fan profile or operating mode the platform will operate under. Each operating mode has a predefined profile for which specific platform targets are configured, which in turn determines how the system fans operate to meet those targets. Platform profile targets are determined by which type of platform is selected when running the FRUSDR utility and by BIOS settings configured using the <F2> BIOS Setup Utility.

4.1.3.3 Configuring the Fan Profile Using the BIOS Setup Utility

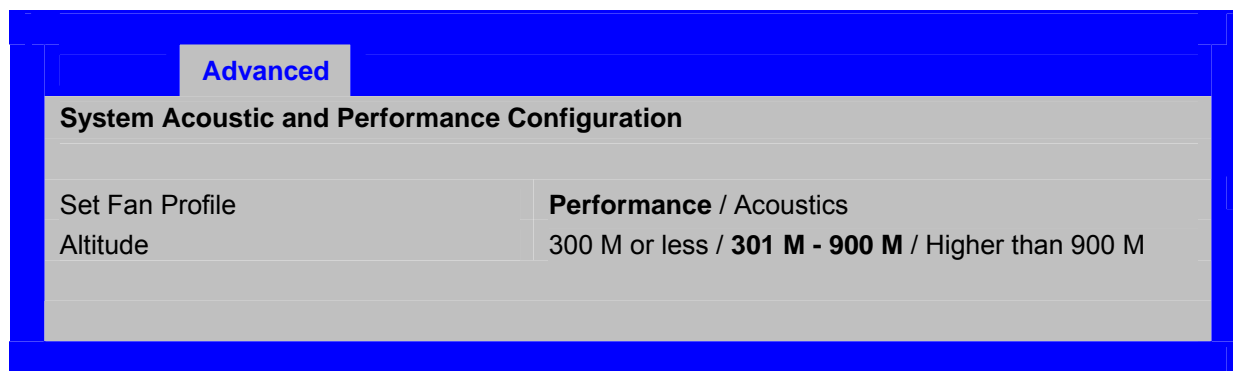
The BIOS uses options set in the <F2> BIOS Setup Utility to determine what fan profile the system should operate under. These options include “SET FAN PROFILE” and “ALTITUDE”.

The “SET FAN PROFILE” option can be set to either the “Performance” mode (Default), or “Acoustics” mode. See the following sections for detail describing the difference between each mode. Changing the fan profile to Acoustics mode may affect system performance.

The “ALTITUDE” option is used to determine appropriate memory performance settings based on the different cooling capability at different altitudes. At high altitude, memory performance must be reduced to compensate for thinner air. Be advised, selecting an Altitude option to a setting that does not meet the operating altitude of the server may limit the system fans ability to provide adequate cooling to the memory. If the air flow is not sufficient to meet the needs of the server even after throttling has occurred, the system may shut down due to excessive platform thermals.

By default, the Altitude option is set to 301Meters – 900 Meters which is believed to cover the majority of the operating altitudes for these server platforms.

The following Diagrams show which BIOS Setup Utility menu is used to configure the desired Fan Profile.



Setup Item	Option	Help Text	Comments
Set Fan Profile	Performance Acoustic	Select the fan control profile that will be used to cool the system.	Performance mode favors using fans over throttling memory bandwidth to cool the system.
Altitude	300 M or less 301 M - 900 M Higher than 900 M	300 M or less (<= 980ft): Provides the best performance option for servers operating at or near sea level. 301 M – 900 M (980ft - 2950ft): Provides the best performance option for servers operating at moderate altitudes above sea level. Higher than 900 M (>2950ft): Provides the best performance option for servers operating at high elevations above sea level.	

Note: Fan speed control for non-Intel chassis, as configured after running the FRUSDR utility and selecting the Non-Intel Chassis option, is limited to only the CPU fans. The BMC only requires the processor thermal sensor data to determine how fast to operate these fans. The remaining system fans will operate at 100% operating limits due to unknown variables associated with the given chassis and its fans. Therefore, regardless of whether the system is configured for Performance Mode or Acoustics Mode, the system fans will always run at 100% operating levels providing for maximum airflow. In this scenario the Performance and Acoustic mode settings only affects the allowable performance of the memory (higher BW for the Performance mode).

4.1.3.4 Performance Mode (Default)

With the platform running in Performance mode (default), several platform control algorithm variables are set to enhance the platform's capability of operating at maximum performance targets for the given system. In doing so, the platform is programmed with higher fan speeds at lower external temperatures. This will result in a louder acoustic level than is targeted for the given platform, but the increased airflow of this operating mode will greatly reduce possible memory throttling from occurring and will reduce dynamic fan speed changes based on processor utilization.

4.1.3.5 Acoustics Mode

With the platform running in Acoustics mode, several platform control algorithm variables are set to ensure acoustic targets are not exceeded for specified Intel platforms. In this mode, the platform is programmed to set the fans at lower speeds when the processor does not require additional cooling due to high utilization / power consumption. Memory throttling will be utilized to ensure that the memory thermal limits are not exceeded.

5. Connector / Header Locations and Pin-outs

5.1 Board Connector Information

The following section provides detailed information regarding all connectors, headers and jumpers on the server board. Table 10 lists all connector types available on the board and the corresponding reference designators printed on the silkscreen.

Table 10. Board Connector Matrix

Connector	Quantity	Reference Designators	Connector Type	Pin Count
Power supply	3	J3K4 J3K3 J1K1	CPU Power Main Power P/S Aux	8 24 5
CPU	2	J8G1, J5G1	CPU Sockets	771
Main Memory	8	J7B1,J7B2,J8B1,J8B2,J8B3,J9B1,J9B2, J9B3	DIMM Sockets	240
Full Height Riser	1	J4F1	Card Edge	280
Low Profile Riser	1	J5B1	Card Edge	98
Bridge Board Connector	1	J4G1	Card Edge	120
RMM	1	J1C5	Mezzanine	120
RMM NIC	1	J1B2	Mezzanine	30
Intel® I/O Expansion Module	1	J3B1	Mezzanine	50
SATA RAID Key	1	J1E4	Key Holder	3
IDE (I/O + Power)	1	J3G1	Shrouded Header	44
Front System Fans #1 & #2	2	J3K1, J3K2	Header	4
Rear System Fans #3 & #4	2	J7A2, J7A1	Header	4
CPU Fans	2	J5K1, J9K1	Header	4
Battery	1	BT1J1	Battery Holder	3
Keyboard/Mouse	1	J9A1	PS2, stacked	12
Rear USB	2	J5A1, J6A2	External	4
Serial Port A	1	J1B1	Header	9
Serial Port B	1	J9A2	External, RJ45	10
Video connector	1	J6A1	External, D-Sub	15
LAN connector 10/100/1000	2	JA8A1, JA8A2	External LAN connector with built-in magnetic	14
SSI Control Panel	1	J3H2	Header	24
Internal USB	1	J1J1	Header	10
Intrusion detect	2	J1C4	Header	2
Serial ATA	6	J1H1,J1G2,J1G1,J1F2,J1F1,J1E3	Header	7
LCP / AUX IPMB	1	J1C2	Header	4
IPMB	1	J1C3	Header	3

Connector	Quantity	Reference Designators	Connector Type	Pin Count
System Recovery Setting Jumpers	4	J1D1, J1D2, J1D3, J3H1	Jumper	3

5.2 Power Connectors

The main power supply connection is obtained using an SSI compliant 2x12 pin connector (J3K3). In addition, there are two additional power related connectors; one SSI compliant 2x4 pin power connector (J3K4) providing support for additional 12V, and one SSI compliant 1x5 pin connector (J1K1) providing I²C monitoring of the power supply. The following tables define the connector pin-outs.

Table 11. Power Connector Pin-out (J3K3)

Pin	Signal	Color	Pin	Signal	Color
1	+3.3Vdc	Orange	13	+3.3Vdc	Orange
2	+3.3Vdc	Orange	14	-12Vdc	Blue
3	GND	Black	15	GND	Black
4	+5Vdc	Red	16	PS_ON#	Green
5	GND	Black	17	GND	Black
6	+5Vdc	Red	18	GND	Black
7	GND	Black	19	GND	Black
8	PWR_OK	Gray	20	RSVD_(-5V)	White
9	5VSB	Purple	21	+5Vdc	Red
10	+12Vdc	Yellow	22	+5Vdc	Red
11	+12Vdc	Yellow	23	+5Vdc	Red
12	+3.3Vdc	Orange	24	GND	Black

Table 12. 12V Power Connector Pin-out (J3K4)

Pin	Signal	Color
1	GND	Black
2	GND	Black
3	GND	Black
4	GND	Black
5	+12Vdc	Yellow/Black
6	+12Vdc	Yellow/Black
7	+12Vdc	Yellow/Black
8	+12Vdc	Yellow/Black

Table 13. Power Supply Signal Connector Pin-out (J1K1)

Pin	Signal	Color
1	SMB_CLK_ESB_FP_PWR_R	Orange
2	SMB_DAT_ESB_FP_PWR_R	Black
3	SMB_ALRT_3_ESB_R	Red
4	3.3V SENSE-	Yellow
5	3.3V SENSE+	Green

5.3 System Management Headers

5.3.1 Intel® Remote Management Module (RMM) Connector

A 120-pin Intel® RMM Connector (J1C5) is included on the server board for sole support of the optional Intel® Remote Management Module. There is no support for third party ASMI cards on this server board.

Note: This connector is NOT compatible for use with Intel® Server Management Module Professional Edition (Product Code AXXIMMPRO) or the Intel® Server Management Module Advanced Edition (Product Code AXXIMMADV).

Table 14. Intel® RMM Connector Pin-out (J1C5)

Pin	Signal Name	Pin	Signal Name
1	Reserved - NC	2	GND
3	ESB_PLT_RST_G1_N	4	Reserved - NC
5	GND	6	Reserved - NC
7	Reserved - NC	8	GND
9	Reserved - NC	10	GND
11	GND	12	Reserved - NC
13	GND	14	IRQ_SERIAL_R
15	USB_ESB_P7P	16	GND
17	USB_ESB_P7N	18	GND
19	GND	20	Reserved - NC
21	P3V3	22	Reserved - NC
23	LPC_LAD<0>	24	GND
25	LPC_LAD<1>	26	LPC_FRAME_N
27	P3V3	28	LPC_LAD<2>
29	LPC_LCLK	30	LPC_LAD<3>
31	P3V3	32	P3V3
33	SMB_1_3V3SB_MS_DAT	34	SMB_IPMB_3V3SB_DAT
35	SMB_1_3V3SB_SL_DAT	36	SMB_IPMB_3V3SB_CLK
37	SMB_1_3V3SB_MS_CLK	38	SMB_0_3V3SB_MS_CLK
39	SMB_1_3V3SB_INT	40	SMB_0_3V3SB_INT
41	P3V3_AUX	42	SMB_0_3V3SB_MS_DAT
43	SPB_IMM_DSR_N	44	SMB_0_3V3SB_SL_DAT
45	SPB_IMM_RTS_N	46	P3V3_AUX
47	SPB_IMM_CTS_N	48	FM_IMM_PRESENT_N
49	SPB_IMM_DCD_N	50	SPB_IMM_DTR_N
51	SPB_RI_N	52	SPB_IMM_SIN
53	SPB_IMM_SOUT	54	P3V3_AUX
55	P3V3_AUX	56	V_LCDDATA7
57	V_LCDCNTL3	56	V_LCDDATA6
59	P3V3_AUX	60	V_LCDDATA5
61	Reserved - NC	62	V_LCDDATA4
63	Reserved - NC	64	V_LCDDATA3
65	GND	66	V_LCDCNTL1
67	V_LCDCNTL0	68	GND

Pin	Signal Name	Pin	Signal Name
69	Reserved - NC	70	V_LCDDATA15
71	GND	72	V_LCDDATA714
73	V_LCDDATA23	74	V_LCDDATA13
75	V_LCDDATA22	76	V_LCDDATA12
77	V_LCDDATA21	78	V_LCDDATA11
79	V_LCDDATA20	80	GND
81	V_LCDDATA19	82	V_LCDCNTL2
83	GND	84	V_DVO_DDC_SDA
85	FM_MAN_LAN_TYPE1	86	V_DVO_DDC_SCL
87	FM_MAN_LAN_TYPE1	88	RST_PS_PWRGD
89	Reserved - NC	90	Reserved - NC
91	Reserved - NC	92	Reserved - NC
93	MII_MDC_RMII_SPARE	94	Reserved - NC
95	MII_COL_RMIIB_RXER	96	GND
97	GND	98	MII_CRX_RMIIIB_CRX
99	MII_TXER_RMIIB_TXEN	100	MII_TXCLK_RMIIIB_RXCLK
101	MII_MDIO_RMIIB_PRESENT	102	GND
103	GND	104	MII_TXD3_RMIIIB_TXD1
105	MII_RXD3_RMIIIB_RXD1	106	MII_TXD2_RMIIIB_TXD0
107	MII_RXD2_RMIIIB_RXD0	108	GND
109	GND	110	MII_TXD1_RMIIA_TXD1
111	MII_RXD1_RMIIA_RXD1	112	MII_TXD0_RMIIA_TXD0
113	MII_RXD0_RMIIA_RXD0	114	GND
115	GND	116	MII_TXEN_RMIIA_TXEN
117	MII_RXCLK	118	MII_RXER_RMIIA_TXER
119	MII_RXDV_RMIIA_CRX	120	GND

5.3.2 Intel® RMM NIC Connector

The server board provides an internal 30-pin mezzanine style connector (J1B2) to accommodate a proprietary form factor RMM NIC module. The following table details the pin-out of the RMM NIC module connector.

Table 15. 30-pin Intel® RMM NIC Module Connector Pin-out (J1B2)

Pin	Signal Name	Pin	Signal Name
1	FM_MAN_LAN_TYPE2	2	MII_MDC_RMII_SPARE
3	FM_MAN_LAN_TYPE1	4	MII_COL_RMIIB_RXER
5	GND	6	GND
7	MII_TXCLK_RMIIIB_RXCLK	8	MII_TXER_RMIIB_TXEN
9	MII_CRX_RMIIIB_CRX	10	MII_MDIO_RMIIB_PRESENT
11	GND	12	GND
13	MII_TXD2_RMIIIB_TXD0	14	MII_RXD3_RMIIIB_RXD1
15	MII_TXD1_RMIIA_TXD1	16	MII_RXD3_RMIIIB_RXD0
17	GND	18	GND
19	MII_TXD3_RMIIIB_TXD1	20	MII_RXD1_RMIIA_RXD1
21	MII_TXD0_RMIIA_TXD0	22	MII_RXD0_RMIIA_RXD0
23	GND	24	GND
25	MII_TXEN_RMIIA_TXEN	26	MII_RXCLK

Pin	Signal Name	Pin	Signal Name
27	P3V3_AUX	28	P3V3_AUX
29	MII_RXER_RMIIA_RXER	30	MII_RXDV_RMIIA_CRS

5.3.3 LCP/AUX IPMB Header

Table 16. LPC/AUX IPMB Header Pin-out (J1C2)

Pin	Signal Name	Description
1	SMB_IPMB_5VSB_DAT	BMC IMB 5V Standby Data Line
2	GND	Ground
3	SMB_IPMB_5VSB_CLK	BMC IMB 5V Standby Clock Line
4	P5V_STBY	+5V Standby Power

5.3.4 IPMB Header

Table 17. IPMB Header Pin-out (J1C3)

Pin	Signal Name	Description
1	SMB_IPMB_5VSB_DAT	BMC IMB 5V Standby Data Line
2	GND	
3	SMB_IPMB_5VSB_CLK	BMC IMB 5V Standby Clock Line

5.4 Riser Card Slots

The server board has two riser card slots. The full height riser slot (J4F1) utilizes Intel® Adaptive Slot Technology. It is capable of supporting riser cards that support either the PCI-X* or PCI Express* full height / full length add-in cards. The low profile riser slot (J5B1) supports riser cards that support low profile PCI Express* add-in cards. The following tables show the pin-out for these riser slots.

Table 18. Low-profile Riser Slot Pin-out (J5B1)

Pin Side B	PCI Spec Signal	Pin Side A	PCI Spec Signal
1	P12V	1	
2	P12V	2	P12V
3	P12V	3	P12V
4	GND	4	GND
5	SMB_PCI3V3SB_CLK	5	PD_LP_TCK
6	SMB_PCI3V3SB_DAT	6	PU_LP_TDI
7	GND	7	FP_CHASSIS_INTRU
8	P3V3	8	PU_LP_TMS
9	PD_LPTRST_N	9	P3V3
10	P3V3_AUX	10	P3V3
11	PE_WAKE_N	11	PE_RST_LP_N
12	P3V3	12	GND
13	GND	13	CLK_100M_LP_PCIE_SLOT1_P
14	PE4_MCH_TXP_C <3..0> 0	14	CLK_100M_LP_PCIE_SLOT1_N
15	PE4_MCH_TXN_C <3..0> 0	15	GND
16	GND	16	PE4_MCH_RXP <3..0> 0
17		17	PE4_MCH_RXN <3..0> 0

Pin Side B	PCI Spec Signal	Pin Side A	PCI Spec Signal
18	GND	18	GND
19	PE4_MCH_TXP_C <3..0> 1	19	P3V3
20	PE4_MCH_TXN_C <3..0> 1	20	GND
21	GND	21	PE4_MCH_RXP <3..0> 1
22	GND	22	PE4_MCH_RXN <3..0> 1
23	PE4_MCH_TXP_C <3..0> 2	23	GND
24	PE4_MCH_TXN_C <3..0> 2	24	GND
25	GND	25	PE4_MCH_RXP <3..0> 2
26	GND	26	PE4_MCH_RXN <3..0> 2
27	PE4_MCH_TXP_C <3..0> 3	27	GND
28	PE4_MCH_TXN_C <3..0> 3	28	GND
29	GND	29	PE4_MCH_RXP <3..0> 3
30	P3V3	30	PE4_MCH_RXN <3..0> 3
31		31	GND
32	GND	32	CLK_100M_LP_PCIE_SLOT2_P
33	PE5_MCH_TXP_C <3..0> 0	33	CLK_100M_LP_PCIE_SLOT2_N
34	PE5_MCH_TXN_C <3..0> 0	34	GND
35	GND	35	PE5_MCH_RXP <3..0> 0
36	GND	36	PE5_MCH_RXN <3..0> 0
37	PE5_MCH_TXP_C <3..0> 1	37	GND
38	PE5_MCH_TXN_C <3..0> 1	38	GND
39	GND	39	PE5_MCH_RXP <3..0> 1
40	GND	40	PE5_MCH_RXN <3..0> 1
41	PE5_MCH_TXP_C <3..0> 2	41	GND
42	PE5_MCH_TXN_C <3..0> 2	42	GND
43	GND	43	PE5_MCH_RXP <3..0> 2
44	GND	44	PE5_MCH_RXN <3..0> 2
45	PE5_MCH_TXP_C <3..0> 3	45	GND
46	PE5_MCH_TXN_C <3..0> 3	46	GND
47	GND	47	PE5_MCH_RXP <3..0> 3
48	FM_LP_RISER_TYPE1	48	PE5_MCH_RXN <3..0> 3
49	FM_LP_RISER_TYPE0	49	GND

Table 19. Full-height Riser Slot Pin-out (J4F1)

Pin-Side B	PCI Spec Signal	Pin-Side A	PCI Spec Signal
140	12V	140	12V
139	12V	139	12V
138	Ground	138	GND
137	-12V	137	3.3VAux
136	12V	136	Wake#
135	GND	135	12V
134	REFCLK2+	134	3.3V
133	REFCLK2+	133	PERST_N
132	GND	132	GND
131	GND	131	REFCLK1+

Pin-Side B	PCI Spec Signal	Pin-Side A	PCI Spec Signal
130	HSOp(0)	130	REFCLK1+
129	HSOn(0)	129	GND
128	GND	128	HSIp(0)
127	GND	127	HSIn(0)
126	HSOp(1)	126	GND
125	HSOn(1)	125	GND
124	GND	124	HSIp(1)
123	GND	123	HSIn(1)
122	HSOp(2)	122	GND
121	HSOn(2)	121	GND
120	GND	120	HSIp(2)
119	GND	119	HSIn(2)
118	HSOp(3)	118	GND
117	HSOn(3)	117	GND
116	GND	116	HSIp(3)
115	GND	115	HSIn(3)
114	HSOp(4)	114	GND
113	HSOn(4)	113	GND
112	GND	112	HSIp(4)
111	GND	111	HSIn(4)
110	HSOp(5)	110	GND
109	HSOn(6)	109	GND
108	GND	108	HSIp(5)
107	GND	107	HSIn(5)
106	HSOp(6)	106	GND
105	HSOn(6)	105	GND
104	GND	104	HSIp(6)
103	GND	103	HSIn(6)
102	HSOp(7)	102	GND
101	HSOn(7)	101	GND
100	GND	100	HSIp(7)
99	+5V	99	HSIn(7)
98	INTB#	98	GND
97	INTD#	97	ZCR_PRSNT_L
96	+5V	96	+5V
95	Reserved	95	+5V
94	+5V	94	ZCR_MSKID_L
93	IOP INTA	93	+5V
92	IOP INTB	92	INTA#
91	GND	91	INTC#
90	CLK3	90	GND
89	GND	89	REQ3#
88	CLK2	88	GND
87	GND	87	GNT3#
86	REQ2#	86	GND
85	GND	85	RST#
84	Reserved	84	GND

Pin-Side B	PCI Spec Signal	Pin-Side A	PCI Spec Signal
83	GND	83	Reserved
	KEY		KEY
	KEY		KEY
82	Reserved	82	+5V
81	GND	81	Reserved
80	CLK1	80	GND
79	Ground	79	GNT2#
78	REQ1#	78	+3.3V
77	+3.3V	77	GNT1#
76	PME2#	76	Ground
75	AD[31]	75	PME1#
74	AD[29]	74	PME3#
73	Ground	73	AD[30]
72	AD[27]	72	+3.3V
71	AD[25]	71	AD[28]
70	+3.3V	70	AD[26]
69	C/BE[3]#	69	Ground
68	AD[23]	68	AD[24]
67	Ground	67	RSVRD
66	AD[21]	66	+3.3V
65	AD[19]	65	AD[22]
64	+3.3V	64	AD[20]
63	AD[17]	63	Ground
62	C/BE[2]#	62	AD[18]
61	Ground	61	AD[16]
60	IRDY#	60	+3.3V
59	+3.3V	59	FRAME#
58	DEVSEL#	58	Ground
57	PCI-XCAP	57	TRDY#
56	LOCK#	56	Ground
55	PERR#	55	STOP#
54	+3.3V	54	+3.3V
53	SERR#	53	SMBD
52	+3.3V	52	SMBCLK
51	C/BE[1]#	51	Ground
50	AD[14]	50	PAR
49	Ground	49	AD[15]
48	AD[12]	48	+3.3V
47	AD[10]	47	AD[13]
46	M66EN	46	AD[11]
45	Ground	45	Ground
44	Ground	44	AD[09]
43	AD[08]	43	C/BE[0]#
42	AD[07]	42	+3.3V
41	+3.3V	41	AD[06]
40	AD[05]	40	AD[04]
39	AD[03]	39	Ground

Pin-Side B	PCI Spec Signal	Pin-Side A	PCI Spec Signal
38	Ground	38	AD[02]
37	AD[01]	37	AD[00]
36	+3.3V	36	+3.3V
35	ACK64#	35	REQ64#
34	+5V	34	+5V
33	+5V	33	+5V
32	Reserved	32	+5V
31	Ground	31	C/BE[7]#
30	C/BE[6]#	30	C/BE[5]#
29	C/BE[4]#	29	Ground
28	Ground	28	PAR64
27	AD[63]	27	AD[62]
26	AD[61]	26	3.3V
25	3.3V	25	AD[60]
24	AD[59]	24	AD[58]
23	AD[57]	23	Ground
22	Ground	22	AD[56]
21	AD[55]	21	AD[54]
20	AD[53]	20	3.3V
19	Ground	19	AD[52]
18	AD[51]	18	AD[50]
17	AD[49]	17	Ground
16	3.3V	16	AD[48]
15	AD[47]	15	AD[46]
14	AD[45]	14	Ground
13	Ground	13	AD[44]
12	AD[43]	12	AD[42]
KEY		KEY	
KEY		KEY	
11	AD[41]	11	3.3V
10	Ground	10	AD[40]
9	AD[39]	9	AD[38]
8	AD[37]	8	Ground
7	3.3V	7	AD[36]
6	AD[35]	6	AD[34]
5	AD[33]	5	Ground
4	Ground	4	AD[32]
3	Type1	3	PXH_RST_N
2	Type0	2	Ground
1	Size	1	PXH_PWROK

5.5 SSI Control Panel Connector

The server board provides a 24-pin SSI control panel connector (J3H2) for use with non-Intel chassis. The following table provides the pin-out for this connector.

Table 20. Front Panel SSI Standard 24-pin Connector Pin-out (J3H2)

Pin	Signal Name	Pin	Signal Name
1	P3V3_STBY	2	P3V3_STBY
3	Key	4	P5V_STBY
5	FP_PWR_LED_L	6	FP_ID_LED_L
7	P3V3	8	FP_STATUS_LED1_R
9	HDD_LED_ACT_R	10	FP_STATUS_LED2_R
11	FP_PWR_BTN_L	12	LAN_ACT_A_L
13	GND	14	LAN_LINKA_L
15	Reset Button	16	PS_I2C_3VSB_SDA
17	GND	18	PS_I2C_3VSB_SCL
19	FP_ID_BTN_L	20	FP_CHASSIS_INTRU
21	TEMP_SENSOR	22	LAN_ACT_B_L
23	FP_NMI_BTN_L	24	LAN_LINKB_L

5.6 Bridge Board Connector

For use in supported Intel® Server Chassis, the server board provides a 120-pin high-density bridge board connector (J4G1) to route control panel, mid-plane, and backplane signals from the server board to the specified system board. The following table provides the pin-outs for this connector.

Table 21. 120-pin Bridgeboard Connector Pin-out (J4G1)

Pin	Signal Name	Pin	Signal Name
A1	SMB_HOST_3V3_CLK	B1	GND
A2	SMB_HOST_3V3_DAT	B2	PE1_ESB_TXN_C<3>
A3	FM_BRIDGE_PRESENT_N	B3	PE1_ESB_TXP_C<3>
A4	GND	B4	GND
A5	PE1_ESB_RXN_C<3>	B5	PE_WAKE_N
A6	PE1_ESB_RXP_C<3>	B6	GND
A7	GND	B7	PE1_ESB_TXN_C<2>
A8	FM_FAN_D_PRSNT6	B8	PE1_ESB_TXP_C<2>
A9	GND	B9	GND
A10	PE1_ESB_RXN_C<2>	B10	FM_FAN_D_PRSNT5
A11	PE1_ESB_RXP_C<2>	B11	GND
A12	GND	B12	PE1_ESB_TXN_C<1>
A13	FM_FAN_D_PRSNT4	B13	PE1_ESB_TXP_C<1>
A14	GND	B14	GND
A15	PE1_ESB_RXN_C<1>	B15	RST_MP_PWRGD
A16	PE1_ESB_RXP_C<1>	B16	GND
A17	GND	B17	PE1_ESB_TXN_C<0>
A18	FM_RAID_PRESENT	B18	PE1_ESB_TXP_C<0>

Pin	Signal Name	Pin	Signal Name
A19	GND	B19	GND
A20	PE1_ESB_RXN_C<0>	B20	FM_RAID_MODE
A21	PE1_ESB_RXP_C<0>	B21	GND
A22	GND	B22	CLK_100M_SRLAKE_N
A23	FM_FAN_D_PRSNT1	B23	CLK_100M_SRLAKE_P
A24	FM_FAN_D_PRSNT3	B24	GND
A25	FM_FAN_D_PRSNT2	B25	SGPIO_DATAOUT1_R
A26	GND	B26	SGPIO_DATAOUT0_R
A27	USB_ESB_P4P	B27	SGPIO_LOAD_R
A28	USB_ESB_P4N	B28	SGPIO_CLOCK_N
A29	GND	B29	GND
A30	USB_ESB_OC_N<4>	B30	USB_ESB_P2P
A31	USB_ESB_OC_N<3>	B31	USB_ESB_P2N
A32	GND	B32	GND
A33	USB_ESB_P3P	B33	USB_ESB_OC_N<2>
A34	USB_ESB_P3N	B34	NIC1_LINK_LED_N
A35	GND	B35	NIC1_ACT_LED_N
A36	FP_NMI_BTN_N	B36	LED_STATUS_GREEN_R1
KEY		KEY	
A37	BMC_RST_BTN_N	B37	NIC2_LINK_LED_N
A38	FP_PWR_BTN_N	B38	NIC2_ACT_LED_N
A39	FP_ID_BTN	B39	LED_STATUS_AMBER_R1
A40	GND	B40	GND
A41	SMB_IPMB_5VSB_SDA	B41	SMB_SN_3V3SB_DAT_BUF
A42	SMB_IPMB_5VSB_CLK	B42	SMB_SN_3V3SB_CLK_BUF
A43	GND	B43	GND
A44	LED_HDD_ACTIVITY_N	B44	V_IO_HSYNC2_BUF_FP
A45	P3V3	B45	V_IO_VSYNC2_BUF_FP
A46	FP_PWR_LED_N_R	B46	GND
A47	P3V3_STBY	B47	V_IO_BLUE_CONN_FP
A48	FP_ID_LED_R1_N	B48	V_IO_GREEN_CONN_FP
A49	FM_SIO_TEMP_SENSOR	B49	V_IO_RED_CONN_FP
A50	LED_FAN3_FAULT	B50	GND
A51	LED_FAN2_FAULT	B51	LED_FAN10_FAULT
A52	LED_FAN1_FAULT	B52	LED_FAN5_FAULT
A53	FAN_PWM_CPU1	B53	LED_FAN4_FAULT
A54	GND	B54	FAN_IO_PWM
A55	FAN_PWM_CPU2	B55	GND
A56	PCI_FAN_TACH9	B56	PCI_FAN_TACH10
A57	FAN_TACH7	B57	FAN_TACH8
A58	FAN_TACH5	B58	FAN_TACH6
A59	FAN_TACH3_H7	B59	FAN_TACH4_H7
A60	FAN_TACH1_H7	B60	FAN_TACH2_H7

5.7 I/O Connector Pinout Definition

5.7.1 VGA Connector

The following table details the pin-out definition of the VGA connector (J6A1).

Table 22. VGA Connector Pin-out (J6A1)

Pin	Signal Name	Description
1	V_IO_R_CONN	Red (analog color signal R)
2	V_IO_G_CONN	Green (analog color signal G)
3	V_IO_B_CONN	Blue (analog color signal B)
4	TP_VID_CONN_B4	No connection
5	GND	Ground
6	GND	Ground
7	GND	Ground
8	GND	Ground
9	TP_VID_CONN_B9	No Connection
10	GND	Ground
11	TP_VID_CONN_B11	No connection
12	V_IO_DDCDAT	DDCDAT
13	V_IO_HSYNC_CONN	HSYNC (horizontal sync)
14	V_IO_VSYNC_CONN	VSYNC (vertical sync)
15	V_IO_DDCCLK	DDCCLK

5.7.2 NIC Connectors

The server board provides two RJ45 NIC connectors oriented side by side on the back edge of the board (JA8A1, JA8A2). The pin-out for each connector is identical and is defined in the following table.

Table 23. RJ-45 10/100/1000 NIC Connector Pin-out (JA8A1, JA8A2)

Pin	Signal Name
1	GND
2	P1V8_NIC
3	NIC_A_MDI3P
4	NIC_A_MDI3N
5	NIC_A_MDI2P
6	NIC_A_MDI2N
7	NIC_A_MDI1P
8	NIC_A_MDI1N
9	NIC_A_MDI0P
10	NIC_A_MDI0N
11 (D1)	NIC_LINKA_1000_N (LED)
12 (D2)	NIC_LINKA_100_N (LED)
13 (D3)	NIC_ACT_LED_N
14	NIC_LINK_LED_N
15	GND
16	GND

5.7.3 IDE Connector

The server board includes an IDE connector to access the single IDE channel from the ESB-2 IO controller hub. The design intent for this connector is to provide IDE support for a single slim-line optical drive, such as CDROM or DVD. The connector is not a standard 40-pin IDE connector, instead it has 44 pins providing support for both power and IO signals. The pin-out for this connector is defined in the following table.

Table 24. 44-pin IDE Connector Pin-out (J3G1)

Pin	Signal Name	Pin	Signal Name
1	ESB_PLT_RST_IDE_N	2	GND
3	RIDE_DD_7	4	RIDE_DD_8
5	RIDE_DD_6	6	RIDE_DD_9
7	RIDE_DD_5	8	RIDE_DD_10
9	RIDE_DD_4	10	RIDE_DD_11
11	RIDE_DD_3	12	RIDE_DD_12
13	RIDE_DD_2	14	RIDE_DD_13
15	RIDE_DD_1	16	RIDE_DD_14
17	RIDE_DD_0	18	RIDE_DD_15
19	GND	20	KEY
21	RIDE_DDREQ	22	GND
23	RIDE_DIOW_N	24	GND
25	RIDE_DIOR_N	26	GND
27	RIDE_PIORDY	28	GND
29	RIDE_DDACK_N	30	GND
31	IRQ_IDE	32	TP_PIDE_32
33	RIDE_DA1	34	IDE_PRI_CBLSNS
35	RIDE_DA0	36	RIDE_DA2
37	RIDE_DCS1_N	38	RIDE_DCS3_N
39	LED_IDE_N	40	GND
41	P5V	42	P5V
43	GND	44	GND

5.7.4 Intel® I/O Expansion Module Connector

The server board provides an internal 50-pin mezzanine style connector (J3B1) to accommodate proprietary form factor Intel® I/O Expansion Modules, which expand the IO capabilities of the server board without sacrificing an add-in slot from the riser cards. There are three planned IO modules for use on this server board: external 4 port SAS, dual Gb NIC, and Infiniband*. For more detail on the supported IO modules, please refer to the *Intel® Server Board S5000PAL / S5000XAL IO Module Hardware Specification*. The following table details the pin-out of the Intel® I/O Expansion Module connector.

Table 25. 50-pin Intel® I/O Expansion Module Connector Pin-out (J3B1)

Pin	Signal Name	Pin	Signal Name
1	P3V3_AUX	2	P3V3_AUX
3	PE_RST_G2_PM_N	4	GND
5	GND	6	PE2_ESB_RXP_C<0>
7	GND	8	PE2_ESB_RXN_C<0>
9	PE2_ESB_TXP_C<0>	10	GND
11	PE2_ESB_TXN_C<0>	12	GND
13	GND	14	PE2_ESB_RXP_C<1>
15	GND	16	PE2_ESB_RXN_C<1>
17	PE2_ESB_TXP_C<2>	18	GND
19	PE2_ESB_TXN_C<2>	20	GND
21	GND	22	PE2_ESB_RXP_C<2>
22	GND	24	PE2_ESB_RXN_C<2>
25	PE2_ESB_TXP_C<1>	26	GND
27	PE2_ESB_TXN_C<1>	28	GND
29	GND	30	PE2_ESB_RXP_C<3>
31	GND	32	PE2_ESB_RXN_C<3>
33	PE2_ESB_TXP_C<0>	34	GND
35	PE2_ESB_TXN_C<0>	36	GND
37	GND	38	CLK_100M_LP_PCIE_SLOT3_P
39	GND	40	CLK_100M_LP_PCIE_SLOT3_N
41	PE_WAKE_N	42	GND
43	P3V3	44	P3V3
45	P3V3	46	P3V3
47	P3V3	48	P3V3
49	P3V3	50	P3V3

5.7.5 SATA Connectors

The server board provides six SATA (Serial ATA) connectors: SATA-0 (J1H1), SATA-1 (J1G2), SATA-2 (J1G1), SATA-3 (J1F2), SATA-4 (J1F1), and SATA-5 (J1E3), for use with an internal SATA backplane. The pin configuration for each connector is identical and is defined in the following table.

Table 26. SATA Connector Pin-out (J1H1, J1G2, J1G1, J1F2, J1E3)

Pin	Signal Name	Description
1	GND	GND1
2	SATA#_TX_P_C	Positive side of transmit differential pair
3	SATA#_TX_N_C	Negative side of transmit differential pair
4	GND	GND2
5	SATA#_RX_N_C	Negative side of Receive differential pair
6	SATA#_RX_P_C	Positive side of Receive differential pair
7	GND	GND3

5.7.6 Serial Port Connectors

The server board provides one external RJ45 Serial 'B' port (J9A2) and one internal 9-pin Serial 'A' port header (J1B1). The following tables define the pin-outs for each.

Table 27. External RJ-45 Serial 'B' Port Pin-out (J9A2)

Pin	Signal Name	Description
1	SPB_RTS	RTS (request to send)
2	SPB_DTR	DTR (Data terminal ready)
3	SPB_OUT_N	TXD (Transmit data)
4	GND	Ground
5	SPB_RI	RI (Ring Indicate)
6	SPB_SIN_N	RXD (receive data)
7	SPB_DSR_DCD	Data Set Ready / Data Carrier Detect ¹
8	SPB_CTS	CTS (clear to send)

Note:

¹ A jumper block on the server board will determine whether DSR or DCD is routed to pin 7. The board will have the jumper block configured with DSR enabled at production.

Table 28. Internal 9-pin Serial 'A' Header Pin-out (J1B1)

Pin	Signal Name	Description
1	SPA_DCD	DCD (carrier detect)
2	SPA_DSR	DSR (data set ready)
3	SPA_SIN_L	RXD (receive data)
4	SPA_RTS	RTS (request to send)
5	SPA_SOUT_N	TXD (Transmit data)
6	SPA_CTS	CTS (clear to send)
7	SPA_DTR	DTR (Data terminal ready)
8	SPA_RI	RI (Ring Indicate)
9	GND	Ground

5.7.7 Keyboard and Mouse Connector

Two stacked PS/2 ports (J9A1) are provided to support both a keyboard and a mouse. Either PS/2 port can support a mouse or keyboard. The following table details the pin-out of the PS/2 connector.

Table 29. Stacked PS/2 Keyboard and Mouse Port Pin-out (J9A1)

Pin	Signal Name	Description
1	KB_DATA_F	Keyboard Data
2	TP_PS2_2	Test point – keyboard
3	GND	Ground
4	P5V_KB_F	Keyboard / mouse power
5	KB_CLK_F	Keyboard Clock
6	TP_PS2_6	Test point – keyboard / mouse
7	MS_DAT_F	Mouse Data
8	TP_PS2_8	Test point – keyboard / mouse
9	GND	Ground

Pin	Signal Name	Description
10	P5V_KB_F	Keyboard / mouse power
11	MS_CLK_F	Mouse Clock
12	TP_PS2_12	Test point – keyboard / mouse
13	GND	Ground
14	GND	Ground
15	GND	Ground
16	GND	Ground
17	GND	Ground

5.7.8 USB 2.0 Connectors

The following table details the pin-out of the external USB connectors (J5A1, J6A2) found on the back edge of the server board.

Table 30. External USB Connector Pin-out (J5A1, J6A2)

Pin	Signal Name	Description
1	USB_OC#_FB_1	USB_PWR
2	USB_P#N_FB_2	DATAL0 (Differential data line paired with DATAH0)
3	USB_P#N_FB_2	DATAH0 (Differential data line paired with DATAL0)
4	GND	Ground

One 2x5 header on the server board (J1J1) provides an option to support an additional two USB 2.0 ports. The pin-out of the connector is detailed in the following table.

Table 31. Internal USB Connector Pin-out (J1J1)

Pin	Signal Name	Description
1	P5V_USB2_VBUS0	USB Power (Ports 0,1)
2	P5V_USB2_VBUS1	USB Power (Ports 0,1)
3	USB_ESB_P0N_CONN	USB Port 0 Negative Signal
4	USB_ESB_P1N_CONN	USB Port 0 Positive Signal
5	USB_ESB_P0P_CONN	USB Port 1 Negative Signal
6	USB_ESB_P1P_CONN	USB Port 1 Positive Signal
7	Ground	
8	Ground	
9	--	No Pin
10	TP_USB_ESB_NC	TEST POINT

5.8 Fan Headers

The server board incorporates three system fan circuits which support a total of six SSI compliant 4-pin fan connectors. Two fan connectors are designated as processor cooling fans, CPU1 Fan (J9K1) and CPU2 Fan (J5K1). These connectors can support CPU fans that draw a maximum of 1.2 Amps each. Two system fan connectors can be found towards the front edge of the server board, System Fan 1 (J3K1), System Fan 2 (J3K2). These connectors are capable of supporting a maximum fan load of 3.5 Amps each. Two additional system fan connectors can be found near the back edge of the server board, System Fan 3(J7A1) and System Fan 4 (J7A2). These two connectors are capable of supporting a maximum fan load of 2.5 Amps per connector. With the proper Sensor Data Record (SDR) installed, Server Management software can monitor all system fans in use.

The pin configuration for each fan connector is identical and is defined in the following table.

Table 32. SSI Fan Connector Pin-out (J9K1,J5K1,J3K1,J3K2,J7A2,J7A1)

Pin	Signal Name	Type	Description
1	Ground	GND	GROUND is the power supply ground
2	12V	Power	Power supply 12V
3	Fan Tach	Out	FAN_TACH signal is connected to the BMC to monitor the fan speed
4	Fan PWM	In	FAN_PWM signal to control fan speed

Note: Intel Corporation server baseboards support peripheral components and contain a number of high-density VLSI and power delivery components that need adequate airflow to cool. Intel's own chassis are designed and tested to meet the intended thermal requirements of these components when the fully integrated system is used together. It is the responsibility of the system integrator that chooses not to use Intel developed server building blocks to consult vendor datasheets and operating parameters to determine the amount of air flow required for their specific application and environmental conditions. Intel Corporation can not be held responsible if components fail or the server board does not operate correctly when used outside any of their published operating or non-operating limits

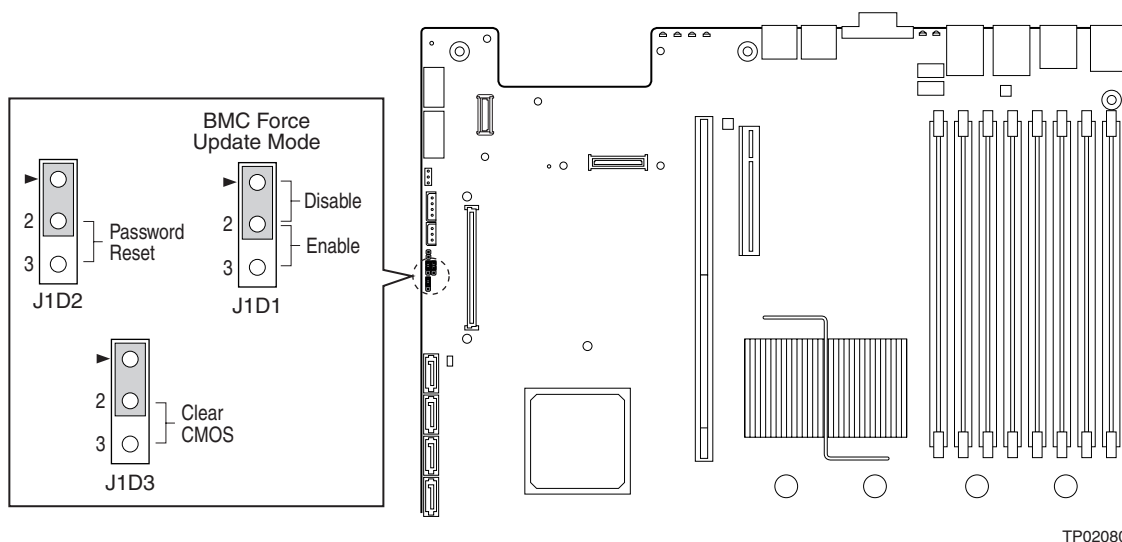
6. Jumper Block Settings

The server board has several 2-pin and 3-pin jumper blocks that can be used to configure, protect, or recover specific features of the server board. Pin 1 on each jumper block is denoted by an “*” or “▼”.

6.1 Recovery Jumper Blocks

Table 33. Recovery Jumpers (J1D1, J1D2, J1D3)

Jumper Name	Pins	What happens at system reset...
J1D1: BMC Force Update	1-2	BMC Firmware Force Update Mode – Disabled (Default)
	2-3	BMC Firmware Force Update Mode – Enabled
J1D2: Password Clear	1-2	These pins should have a jumper in place for normal system operation. (Default)
	2-3	If these pins are jumpered, administrator and user passwords will be cleared immediately. These pins should not be jumpered for normal operation.
J1D3: CMOS Clear	1-2	These pins should have a jumper in place for normal system operation. (Default)
	2-3	If these pins are jumpered, the CMOS settings will be cleared immediately. These pins should not be jumpered for normal operation



TP02080

Figure 17. Recovery Jumper Blocks (J1D1, J1D2, J1D3)

6.1.1 CMOS Clear and Password Reset Usage Procedure

The CMOS Clear (J1D3) and Password Reset (J1D2) recovery features are designed so that the desired operation can be achieved with minimal system down time. The usage procedure for these two features has changed from previous generation Intel® Server Boards. The following procedure outlines the new usage model.

CMOS Clear Procedure:

1. Power down the server; do not remove AC power.
2. Open the server and move the jumper from the default operating position (pins 1-2) to the “clear” position (pins 2-3).
3. Wait 5 seconds.
4. Move the jumper back to the default position (pins 1-2).
5. Close the server system and power up the server.
6. CMOS is now cleared and can be reset by going into the BIOS setup.

Password Reset Procedure:

1. Power down the server; do not remove AC power.
2. Open the server and move the jumper from the default operating position (pins 1-2) to the “reset” position (pins 2-3).
3. Power up the server.
4. The password is now cleared.
5. Power down the server; do not remove AC power.
6. Move the jumper back to the default position (pins 1-2) and close the server system.
7. The password can be reset by going into the BIOS setup.

Note: Removing AC power before performing the CMOS clear operation will cause the system to automatically power up and immediately power down, after the procedure is followed and AC power is re-applied. Should this occur, remove the AC power cord again, wait 30 seconds, and re-install the AC power cord. Power up system and proceed to the <F2> BIOS Setup Utility to reset desired settings.

6.1.2 BMC Force Update Procedure

When performing a standard BMC firmware update procedure, the update utility places the BMC into an update mode, allowing the firmware to load safely onto the flash device. In the unlikely event that the BMC firmware update process fails due to the BMC not being in the proper update state, the server board provides a BMC Force Update jumper (J1D1) which will force the BMC into the proper update state. The following procedure should be following in the event the standard BMC firmware update process fails.

- Power down the server and remove AC power.
- Open the server and move the jumper from the default operating position (pins 1-2) to the “enabled” position (pins 2-3).
- Close the server system and reconnect AC power and power up the server.
- Perform the standard BMC firmware update procedure as documented in README.TXT file that is included in the given BMC Firmware Update package.
- After successful completion of the firmware update process, the firmware update utility may generate an error stating that the BMC is still in update mode.
- Power down and remove AC power.
- Open the server and move the jumper from the “enabled” position (pins 2-3) to the “disabled” position (pins 1-2).
- Close the server system and reconnect AC power and power up the server.

Note: Normal BMC functionality is disabled with the force BMC update jumper set to the “enabled” position. The server should never be run with the BMC force update jumper set in this position and should only be used when the standard firmware update process fails. This jumper should remain in the default – disabled position when the server is running normally.

6.2 BIOS Select Jumper

The jumper block at J3H1, located just to the left of the SSI control panel header, is used to select which BIOS image the system will boot to. Pin 1 on the jumper is identified with a ‘▼’. This jumper should only be moved if you wish to force the BIOS to boot to the secondary bank which may hold a different version of BIOS.

The rolling BIOS feature of the baseboard will automatically alternate the Boot BIOS to the secondary bank in the event the BIOS image in the primary bank is corrupted and cannot boot for any reason.

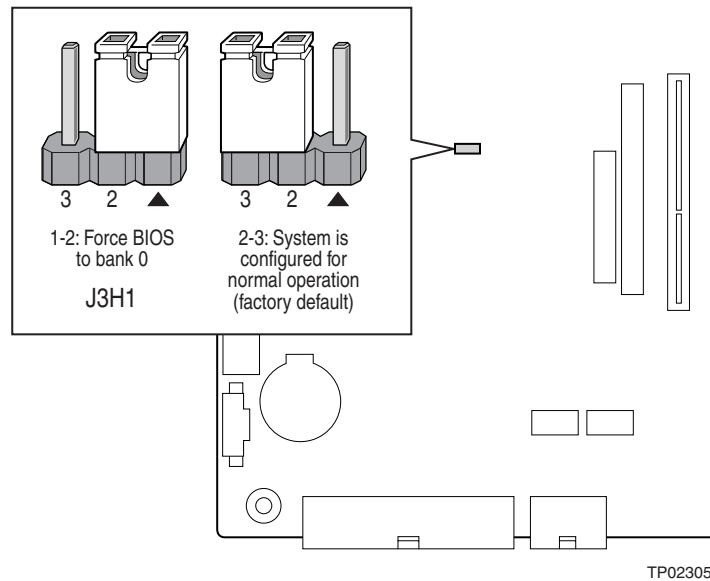


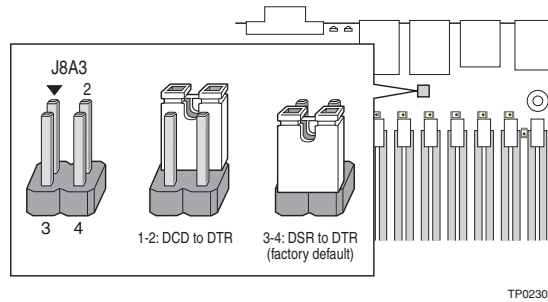
Figure 18. BIOS Select Jumper (J3H1)

Pins	What happens at system reset...
1-2	Force BIOS to bank 0
2-3	System is configured for normal operation (Default)

Note: When performing a BIOS update procedure, the BIOS select jumper must be set to its default position (pins 2-3).

6.3 External RJ45 Serial Port Jumper Block

The jumper block J8A3, located directly behind the external RJ45 serial port, is used to configure either a DSR or a DCD signal to the connector.



TP02303

Figure 19. External RJ45 Serial Port Configuration Jumper

7. Light Guided Diagnostics

The server board has several on-board diagnostic LEDs to assist in troubleshooting board level issues. This section shows where each LED is located and provides a high level usage description. For a more detailed description of what drives the diagnostic LED operation, refer to the *Intel® S5000 Series Chipsets Server Board Family Datasheet*.

7.1 5-Volt Standby LED

Several server management features of this server board require that a 5 volt stand-by voltage be supplied from the power supply. Some of the features and components that require this voltage be present when the system is “Off” include the BMC within the ESB-2, onboard NICs, and optional Intel® RMM.

The LED located just below the system recovery jumper block labeled “5V STBY” is illuminated when AC power is applied to the platform and 5 Volt standby voltage is supplied to the server board by the power supply.

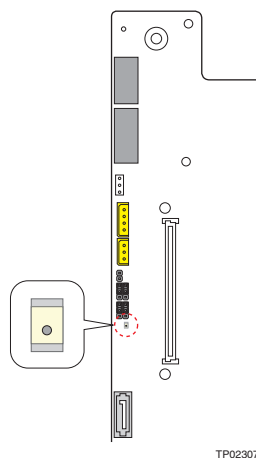


Figure 20. 5V Standby Status LED Location

7.2 System ID LED and System Status LED

The server board provides LEDs for both System ID and System Status.

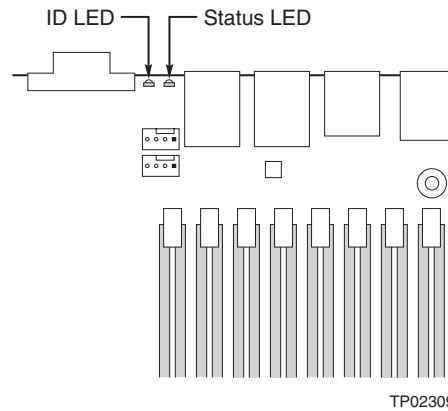


Figure 21. System ID LED and System Status LED Locations.

The blue “System ID” LED can be illuminated using either of two mechanisms.

- By pressing the System ID Button on the system control panel the ID LED will display a solid blue color, until the button is pressed again.
- By issuing the appropriate hex IPMI “Chassis Identify” value, the ID LED will either blink blue for 15 seconds and turn off or will blink indefinitely until the appropriate hex IPMI Chassis Identify value is issued to turn it off.

The bi-color System Status LED will operate as follows:

Color	State	Criticality	Description
Off	N/A	Not ready	AC power off
Green / Amber	Alternating Blink	Not ready	Pre DC Power On – 15-20 second BMC Initialization when AC is applied to the server. Control Panel buttons are disabled until BMC initialization is complete.
Green	Solid on	System OK	System booted and ready.
Green	Blink	Degraded	System degraded <ul style="list-style-type: none"> • Unable to use all of the installed memory (more than one DIMM installed). • Correctable errors over a threshold of 10 and migrating to a spare DIMM (memory sparing). This indicates that the user no longer has spared DIMMs indicating a redundancy lost condition. Corresponding DIMM LED should light up. • In mirrored configuration, when memory mirroring takes place and system loses memory redundancy. This is not covered by (2). • Redundancy loss such as power-supply or fan. This does not apply to non-redundant sub-systems. • PCI-e link errors • CPU failure / disabled – if there are two processors and one of them fails • Fan alarm – Fan failure. Number of operational fans should be more than minimum number needed to cool the system • Non-critical threshold crossed – Temperature and voltage
Amber	Blink	Non-critical	Non-fatal alarm – system is likely to fail <ul style="list-style-type: none"> • Critical voltage threshold crossed • VRD hot asserted • Minimum number of fans to cool the system not present or failed • In non-sparing and non-mirroring mode if the threshold of ten correctable errors is crossed within the window
Amber	Solid on	Critical, non-recoverable	Fatal alarm – system has failed or shutdown <ul style="list-style-type: none"> • DIMM failure when there is one DIMM present, no good memory present • Run-time memory uncorrectable error in non-redundant mode • IERR signal asserted • Processor 1 missing • Temperature (CPU ThermTrip, memory TempHi, critical threshold crossed) • No power good – power fault • Processor configuration error (for instance, processor stepping mismatch)

7.2.1 System Status LED – BMC Initialization

When the AC power is first applied to the system and 5V-STBY is present, the BMC controller on the server board requires 15-20 seconds to initialize. During this time, the system status LED will blink, alternating between amber and green, and the power button functionality of the control panel is disabled preventing the server from powering up. Once BMC initialization has completed, the status LED will stop blinking and the power button functionality is restored and can be used to turn on the server.

7.3 DIMM Fault LEDs

The server board provides a memory fault LED for each DIMM slot. The DIMM fault LED is illuminated when the system BIOS disables the specified DIMM after it reaches a specified number of given failures or if specific critical DIMM failures are detected. See the *Intel® S5000 Series Chipsets Server Board Family Datasheet* for more details.

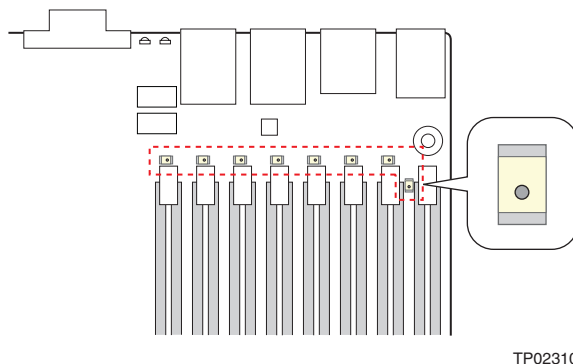


Figure 22. DIMM Fault LED Locations

7.4 Processor Fault LED

The server board provides a Processor Fault LED for each of the two processor sockets. These LEDs will illuminate when a CPU is disabled or a CPU configuration error is detected.

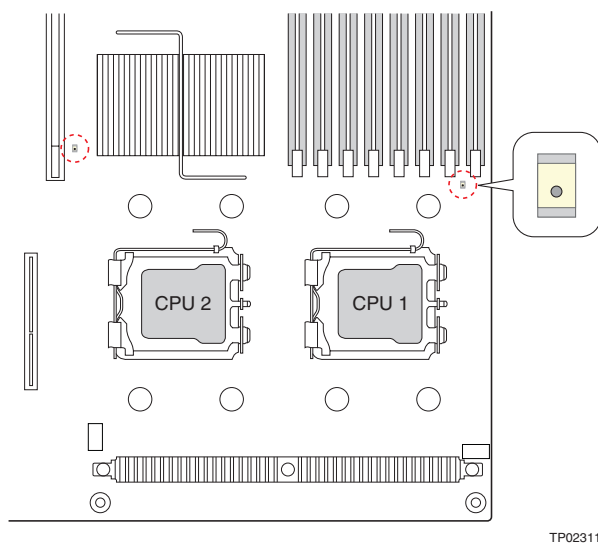


Figure 23. Processor Fault LED Location

7.5 Post Code Diagnostic LEDs

During the system boot process, BIOS executes a number of platform configuration processes, each of which is assigned a specific hex POST code number. As each configuration routine is started, BIOS will display the given POST code to the POST code diagnostic LEDs found on the back edge of the server board. To assist in troubleshooting a system hang during the POST process, the diagnostic LEDs can be used to identify the last POST process to be executed. See Appendix C for a complete description of how these LEDs are read, and for a list of all supported POST codes.

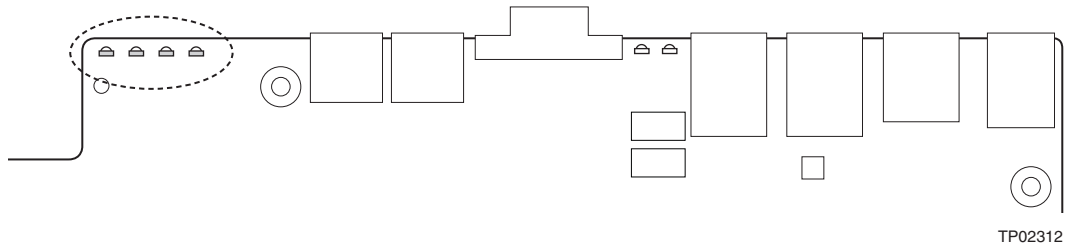


Figure 24. POST Code Diagnostic LED Location

8. Power and Environmental Specifications

8.1 Intel® Server Board S5000PAL / S5000XAL Design Specifications

Operation of the server board at conditions beyond those shown in the following table may cause permanent damage to the system. Exposure to absolute maximum rating conditions for extended periods may affect system reliability.

Table 34: Server Board Design Specifications

Operating Temperature	0° C to 55° C ¹ (32° F to 131° F)												
Non-Operating Temperature	-40° C to 70° C (-40° F to 158° F)												
DC Voltage	± 5% of all nominal voltages												
Shock (Unpackaged)	Trapezoidal, 50 g, 170 inches/sec												
Shock (Packaged)	<table> <tr> <td>< 20 lbs</td> <td>36 inches</td> </tr> <tr> <td>≥ 20 to < 40</td> <td>30 inches</td> </tr> <tr> <td>≥ 40 to < 80</td> <td>24 inches</td> </tr> <tr> <td>≥ 80 to < 100</td> <td>18 inches</td> </tr> <tr> <td>≥100 to < 120</td> <td>12 inches</td> </tr> <tr> <td>≥120</td> <td>9 inches</td> </tr> </table>	< 20 lbs	36 inches	≥ 20 to < 40	30 inches	≥ 40 to < 80	24 inches	≥ 80 to < 100	18 inches	≥100 to < 120	12 inches	≥120	9 inches
< 20 lbs	36 inches												
≥ 20 to < 40	30 inches												
≥ 40 to < 80	24 inches												
≥ 80 to < 100	18 inches												
≥100 to < 120	12 inches												
≥120	9 inches												
Vibration (Unpackaged)	5 Hz to 500 Hz 3.13 g RMS random												

Note:

¹ Chassis design must provide proper airflow to avoid exceeding the Dual-Core Intel® Xeon® processor 5000 sequence maximum case temperature.

Disclaimer Note: Intel Corporation server boards support add-in peripherals and contain a number of high-density VLSI and power delivery components that need adequate airflow to cool. Intel ensures through its own chassis development and testing that when Intel server building blocks are used together, the fully integrated system will meet the intended thermal requirements of these components. It is the responsibility of the system integrator who chooses not to use Intel developed server building blocks to consult vendor datasheets and operating parameters to determine the amount of air flow required for their specific application and environmental conditions. Intel Corporation cannot be held responsible, if components fail or the server board does not operate correctly when used outside any of their published operating or non-operating limits.

8.2 Server Board Power Requirements

This section provides power supply design guidelines for a system using the Intel® Server Board S5000PAL / S5000XAL, including voltage and current specifications, and power supply on/off sequencing characteristics. The following diagram shows the power distribution implemented on this server board.

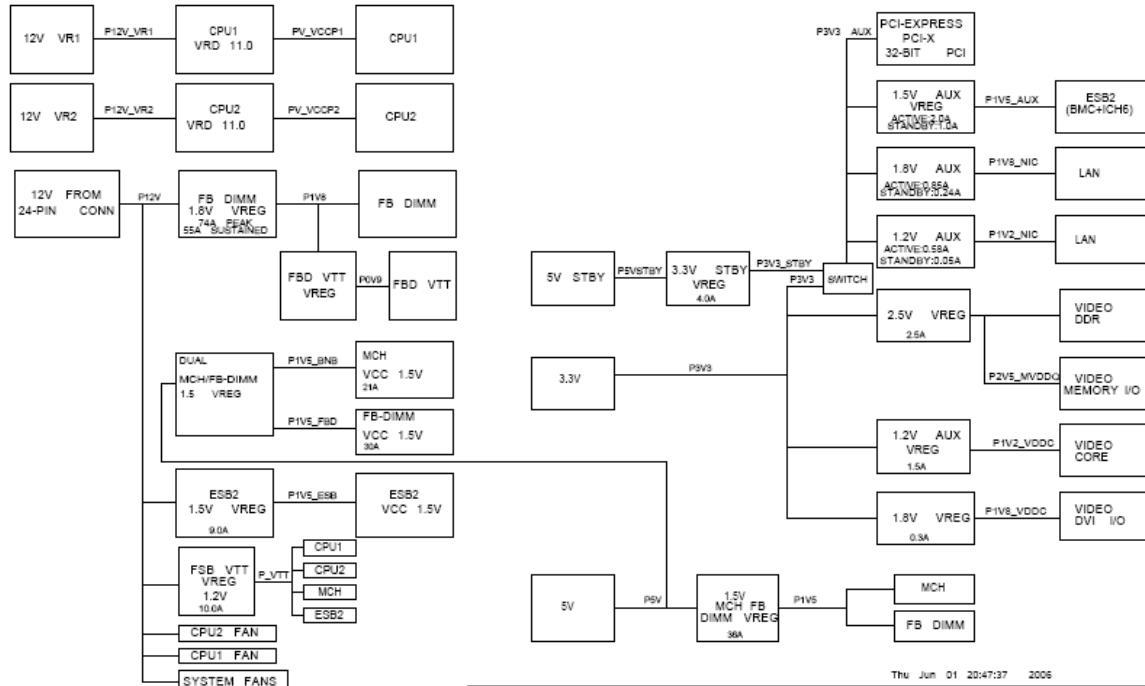


Figure 25. Power Distribution Block Diagram

8.2.1 Processor Power Support

The server board supports the Thermal Design Point (TDP) guideline for Dual-Core Intel® Xeon® processors 5000 sequence. The Flexible Motherboard Guidelines (FMB) has also been followed to help determine the suggested thermal and current design values for anticipating future processor needs. The following table provides maximum values for I_{CC}, TDP power and T_{CASE} for the Dual-Core Intel® Xeon® processor 5000 sequence family.

Table 35. Dual-Core Intel® Xeon® Processor 5000 Sequence TDP Guidelines per processor

TDP Power	Max TCASE	I _{CC} MAX
130 W	70° C	150 A

Note: These values are for reference only. The *Dual-Core Intel® Xeon® processor 5000 sequence Datasheet* contains the actual specifications for the processor. If the values found in the *Dual-Core Intel® Xeon® processor 5000 sequence Datasheet* are different than those published here, the *Dual-Core Intel® Xeon® processor 5000 sequence Datasheet* values will supersede these, and should be used.

8.2.2 Power Supply Output Requirements

This section is for reference purposes only. Its intent is to provide guidance to system designers for determining a proper power supply for use with this server board. The contents of this section specify the power supply requirements Intel used to develop a power supply for its 1U server platform.

The combined power of all outputs shall not exceed the rated output power of the power supply. The power supply must meet both static and dynamic voltage regulation requirements for the minimum loading conditions.

Table 36. 600W Load Ratings

Voltage	Minimum Continuous	Maximum Continuous	Peak
+3.3 V	1.5 A	10 A	
+5 V	1.0 A	20 A	
+12 V1	0.5 A	16 A	18 A
+12 V2	0.5 A	16 A	18 A
+12 V3	0.5 A	16 A	
+12 V4	0.5 A	16 A	
-12 V	0 A	0.5 A	
+5 VSB	0.1 A	3.0 A	3.5 A

1. Maximum continuous total DC output power should not exceed 600W.
2. Peak load on the combined 12 V output shall not exceed 49A.
3. Maximum continuous load on the combined 12 V output shall not exceed 44A.
4. Peak total DC output power should not exceed 650W.
5. Peak power and current loading shall be supported for a minimum of 12 seconds.
6. Combined 3.3V and 5V power shall not exceed 100W.

8.2.3 Turn On No Load Operation

At power on the system shall present a no load condition to the power supply. In this no load state the voltage regulation limits for the 3.3V and 5V are relaxed to +/-10% and the +12V rails relaxed to +10/-8%. When operating loads are applied the voltages must regulated to there normal limits.

Table 37: No load operating range

Voltage	Minimum Continuous	Maximum Continuous	Peak
+3.3 V	0 A	7 A	
+5 V	0 A	5 A	
+12 V1	0 A	5 A	7 A
+12 V2	0 A	5 A	7 A
+12 V3	0 A	6 A	
+12 V4	0 A	5 A	
-12 V	0 A	0.5 A	
+5 VSB	0.1 A	3.0 A	3.5 A

8.2.4 Grounding

The grounds of the pins of the power supply output connector provide the power return path. The output connector ground pins shall be connected to safety ground (power supply enclosure). **This grounding should be well designed to ensure passing the maximum allowed Common Mode Noise levels.**

The power supply shall be provided with a reliable protective earth ground. All secondary circuits shall be connected to protective earth ground. Resistance of the ground returns to chassis shall not exceed 1.0 mΩ. This path may be used to carry DC current.

8.2.5 Standby Outputs

The 5VSB output shall be present when an AC input greater than the power supply turn on voltage is applied.

8.2.6 Remote Sense

The power supply has remote sense return (ReturnS) to regulate out ground drops for all output voltages: +3.3V, +5V, +12V1, +12V2, +12V3, -12V, and 5VSB. The power supply uses remote sense (3.3VS) to regulate out drops in the system for the +3.3V output. The +5V, +12V1, +12V2, +12V3, -12V and 5VSB outputs only use remote sense referenced to the ReturnS signal. The remote sense input impedance to the power supply must be greater than 200 Ω on 3.3VS and 5VS; this is the value of the resistor connecting the remote sense to the output voltage internal to the power supply. Remote sense must be able to regulate out a minimum of a 200 mV drop on the +3.3V output. The remote sense return (ReturnS) must be able to regulate out a minimum of a 200 mV drop in the power ground return. The current in any remote sense line shall be less than 5 mA to prevent voltage sensing errors. The power supply must operate within specification over the full range of voltage drops from the power supply's output connector to the remote sense points.

8.2.7 Voltage Regulation

The power supply output voltages must stay within the following voltage limits when operating at steady state and dynamic loading conditions. These limits include the peak-peak ripple/noise.

Table 38. Voltage Regulation Limits

PARAMETER	TOLERANCE	MIN	NOM	MAX	UNITS
+ 3.3V	- 5% / +5%	+3.14	+3.30	+3.46	V _{rms}
+ 5V	- 5% / +5%	+4.75	+5.00	+5.25	V _{rms}
+ 12V1,2,3,4	- 5% / +5%	+11.40	+12.00	+12.60	V _{rms}
- 12V	- 5% / +9%	-10.80	-12.00	-13.20	V _{rms}
+ 5VSB	- 5% / +5%	+4.75	+5.00	+5.25	V _{rms}

8.2.8 Dynamic Loading

The output voltages shall remain within limits for the step loading and capacitive loading specified in the table below. The load transient repetition rate shall be tested between 50 Hz and 5 kHz at duty cycles ranging from 10%-90%. The load transient repetition rate is only a test specification. The Δ step load may occur anywhere within the MIN load to the MAX load conditions.

Table 39. Transient Load Requirements

Output	Δ Step Load Size (See note 2)	Load Slew Rate	Test capacitive Load
+3.3V	5.0A	0.25 A/ μ sec	250 μ F
+5V	6.0A	0.25 A/ μ sec	400 μ F
12V1+12V2+12V3+12V4	28.0A	0.25 A/ μ sec	2200 μ F ^{1,2}
+5VSB	0.5A	0.25 A/ μ sec	20 μ F

Notes:

- 1) Step loads on each 12V output may happen simultaneously.
- 2) The +12V should be tested with 2200 μ F evenly split between the four +12V rails.

8.2.9 Capacitive Loading

The power supply shall be stable and meet all requirements with the following capacitive loading ranges.

Table 40. Capacitive Loading Conditions

Output	MIN	MAX	Units
+3.3V	250	6,800	μ F
+5V	400	4,700	μ F
+12V1,2,3,4	500 each	11,000	μ F
-12V	1	350	μ F
+5VSB	20	350	μ F

8.2.10 Closed-Loop Stability

The power supply shall be unconditionally stable under all line/load/transient load conditions including capacitive load ranges. A minimum of: **45 degrees phase margin** and **-10dB-gain margin** is required. Closed-loop stability must be ensured at the maximum and minimum loads as applicable.

8.2.11 Common Mode Noise

The common mode noise on any output shall not exceed **350 mV pk-pk** over the frequency band of 10Hz to 30MHz.

1. The measurement shall be made across a 100 Ω resistor between each of the DC outputs, including ground, at the DC power connector and chassis ground (power subsystem enclosure).
2. The test set-up shall use an FET probe such as Tektronix* model P6046 or equivalent.

8.2.12 Ripple / Noise

The maximum allowed ripple/noise output of the power supply is defined in the following table. This is measured over a bandwidth of 0Hz to 20MHz at the power supply output connectors. A 10 μ F tantalum capacitor in parallel with a 0.1 μ F ceramic capacitor are placed at the point of measurement.

Table 41. Ripple and Noise

+3.3V	+5V	+12V1/2/3/4	-12V	+5VSB
50mVp-p	50mVp-p	120mVp-p	120mVp-p	50mVp-p

8.2.13 Soft Starting

The power supply shall contain a control circuit which provides a monotonic soft start for its outputs without overstress of the AC line or any power supply components at any specified AC line or load conditions. There is no requirement for rise time on the 5 V standby, but the turn on/off shall be monotonic.

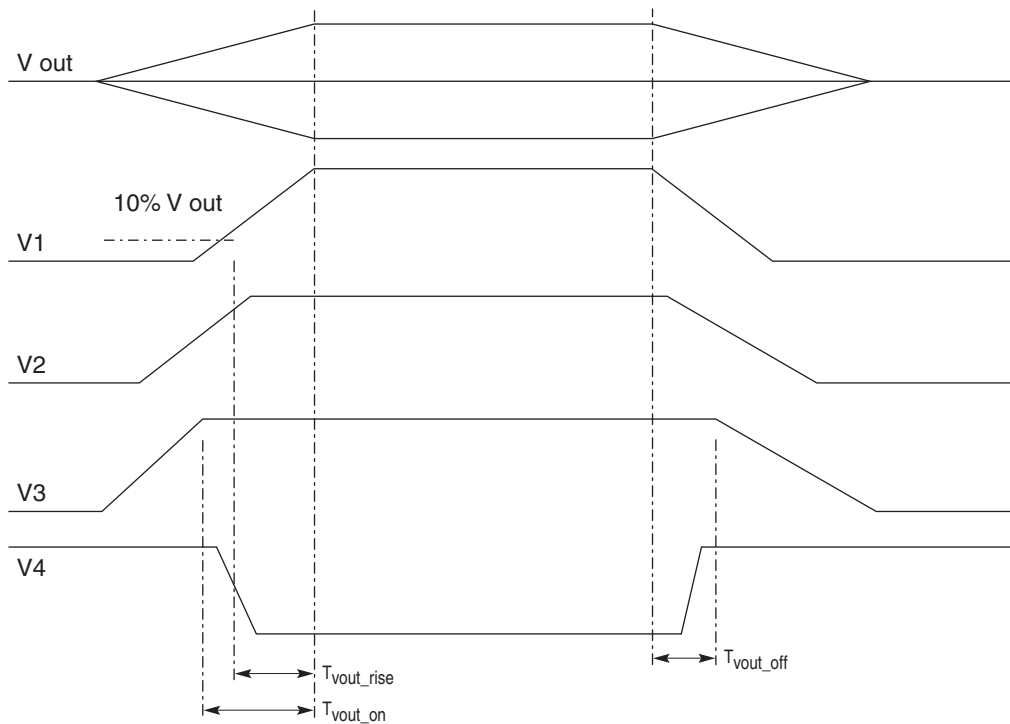
8.2.14 Timing Requirements

These are the timing requirements for the power supply operation. The output voltages must rise from 10% to within regulation limits ($T_{\text{vout_rise}}$) within 5 to 70 ms, except for 5VSB; it is allowed to rise from 1.0 to 25 ms. **All outputs must rise monotonically.** Each output voltage shall reach regulation within 50 ms ($T_{\text{vout_on}}$) of each other during turn on of the power supply. Each output voltage shall fall out of regulation within 400 msec ($T_{\text{vout_off}}$) of each other during turn off. The following diagrams show the timing requirements for the power supply being turned on and off via the AC input with PSON held low, and the PSON signal with the AC input applied.

Table 42. Output Voltage Timing

Item	Description	MIN	MAX	UNITS
T_{vout_rise}	Output voltage rise time from each main output.	5.0 *	70 ¹	msec
T_{vout_on}	All main outputs must be within regulation of each other within this time.		50	msec
T_{vout_off}	All main outputs must leave regulation within this time.		400	msec

¹ The 5VSB output voltage rise time shall be from 1.0ms to 25.0ms

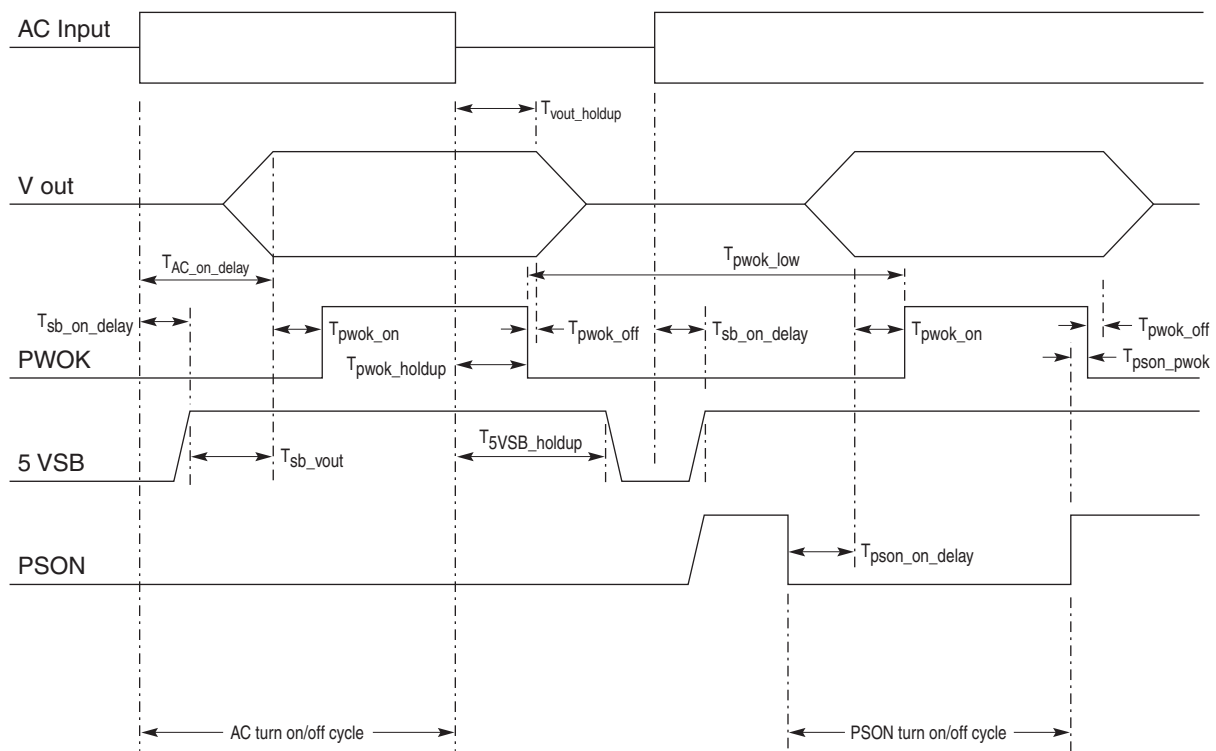


TP02313

Figure 26. Output Voltage Timing

Table 43. Turn On/Off Timing

Item	Description	MIN	MAX	UNITS
$T_{sb_on_delay}$	Delay from AC being applied to 5VSB being within regulation.		1500	msec
$T_{ac_on_delay}$	Delay from AC being applied to all output voltages being within regulation.		2500	msec
T_{vout_holdup}	Time all output voltages stay within regulation after loss of AC. Measured at 60% of maximum load.	21		msec
T_{pwok_holdup}	Delay from loss of AC to de-assertion of PWOK. Measured at 60% of maximum load.	20		msec
$T_{pson_on_delay}$	Delay from PSON# active to output voltages within regulation limits.	5	400	msec
T_{pson_pwok}	Delay from PSON# de-active to PWOK being de-asserted.		50	msec
T_{pwok_on}	Delay from output voltages within regulation limits to PWOK asserted at turn on.	100	500	msec
T_{pwok_off}	Delay from PWOK de-asserted to output voltages (3.3V, 5V, 12V, -12V) dropping out of regulation limits.	1		msec
T_{pwok_low}	Duration of PWOK being in the de-asserted state during an off/on cycle using AC or the PSON signal.	100		msec
T_{sb_vout}	Delay from 5VSB being in regulation to O/Ps being in regulation at AC turn on.	50	1000	msec
T_{5VSB_holdup}	Time the 5VSB output voltage stays within regulation after loss of AC.	70		msec



TP02314

Figure 27. Turn On/Off Timing (Power Supply Signals)

8.2.15 Residual Voltage Immunity in Standby Mode

The power supply shall be immune to any residual voltage placed on its outputs (typically a leakage voltage through the system from standby output) up to 500 mV. There shall be no additional heat generated, nor stress of any internal components with this voltage applied to any individual output, and all outputs simultaneously. It also should not trip the power supply protection circuits during turn on.

Residual voltage at the power supply outputs for a no load condition shall not exceed 100 mV when AC voltage is applied and the PSON# signal is de-asserted.

9. Regulatory and Certification Information






9.1 Product Regulatory Compliance

Intended Application – This product was evaluated as Information Technology Equipment (ITE), which may be installed in offices, schools, computer rooms, and similar commercial type locations. The suitability of this product for other product categories and environments (such as: medical, industrial, telecommunications, NEBS, residential, alarm systems, test equipment, etc.), other than an ITE application, may require further evaluation. This is an FCC Class A device. Integration of it into a Class B chassis does not result in a Class B device.

The following table references Server Board Compliance and markings that may appear on the product. Markings below are typical markings however, may vary or be different based on how certification is obtained.

Note: Certifications Emissions requirements are to Class A

9.1.1 Product Safety & Electromagnetic (EMC) Compliance

Compliance Regional Description	Compliance Reference	Compliance Reference Marking Example
Australia / New Zealand	AS/NZS 3548 (Emissions)	 N232
Canada / USA	CSA 60950 – UL 60950 (Safety) Industry Canada ICES-003 (Emissions)	 CANADA ICES-003 CLASS A CANADA NMB-003 CLASSE A
CENELEC Europe	Low Voltage Directive 93/68/EEC; EMC Directive 89/336/EEC EN55022 (Emissions) EN55024 (Immunity) CE Declaration of Conformity	
International	CB Certification – IEC60950 CISPR 22 / CISPR 24	None Required
Korea	RRL Certification MIC Notice No. 1997-41 (EMC) & 1997-42 (EMI)	 인증번호: CPU-Model Name (A)
Taiwan	BSMI CNS13438	 D33025

警告使用者：
這是甲類的資訊產品，在居住的環境中使用時，可能會造成射頻干擾，在這種情況下，使用者會被要求採取某些適當的對策

9.2 Electromagnetic Compatibility Notices

9.2.1 FCC Verification Statement (USA)

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Intel Corporation
5200 N.E. Elam Young Parkway
Hillsboro, OR 97124-6497
Phone: 1-800-628-8686

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and the receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Any changes or modifications not expressly approved by the grantee of this device could void the user's authority to operate the equipment. The customer is responsible for ensuring compliance of the modified product.

All cables used to connect to peripherals must be shielded and grounded. Operation with cables, connected to peripherals that are not shielded and grounded may result in interference to radio and TV reception.

9.2.2 ICES-003 (Canada)

Cet appareil numérique respecte les limites bruits radioélectriques applicables aux appareils numériques de Classe B prescrites dans la norme sur le matériel brouilleur: "Appareils Numériques", NMB-003 édictée par le Ministre Canadien des Communications.

English translation of the notice above:

This digital apparatus does not exceed the Class B limits for radio noise emissions from digital apparatus set out in the interference-causing equipment standard entitled "Digital Apparatus," ICES-003 of the Canadian Department of Communications.

9.2.3 Europe (CE Declaration of Conformity)

This product has been tested in accordance too, and complies with the Low Voltage Directive (73/23/EEC) and EMC Directive (89/336/EEC). The product has been marked with the CE Mark to illustrate its compliance.

9.2.4 BSMI (Taiwan)

The BSMI Certification Marking and EMC warning is located on the outside rear area of the product.

警告使用者：
 這是甲類的資訊產品，在居住的環境中使用時，
 可能會造成射頻干擾，在這種情況下，使用者會
 被要求採取某些適當的對策

9.2.5 RRL (Korea)

Following is the RRL certification information for Korea.






1. 기기의 명칭(모델명) :
2. 인증번호 :
3. 인증받은 자의 상호 :
4. 제조년월일 :
5. 제조자/제조국가 :





English translation of the notice above:

1. Type of Equipment (Model Name): On License and Product
2. Certification No.: On RRL certificate. Obtain certificate from local Intel representative
3. Name of Certification Recipient: Intel Corporation
4. Date of Manufacturer: Refer to date code on product
5. Manufacturer/Nation: Intel Corporation/Refer to country of origin marked on product

9.3 Product Ecology Compliance

Intel has a system in place to restrict the use of banned substances in accordance with world wide product ecology regulatory requirements. The following is Intel's product ecology compliance criteria.

Compliance Regional Description	Compliance Reference	Compliance Reference Marking Example
California	California Code of Regulations, Title 22, Division 4.5; Chapter 33: Best Management Practices for Perchlorate Materials.	Special handling may apply. See www.dtsc.ca.gov/hazardouswaste/perchlorate This notice is required by California Code of Regulations, Title 22, Division 4.5; Chapter 33: Best Management Practices for Perchlorate Materials. This product / part include a battery which contains Perchlorate material.
China	<p>China RoHS Administrative Measures on the Control of Pollution Caused by Electronic Information Products” (EIP) #39. Referred to as China RoHS. Mark requires to be applied to retail products only. Mark used is the Environmental Friendly Use Period (EFUP). Number represents years.</p>	
	<p>China Recycling (GB18455-2001) Mark requires to be applied to be retail product only. Marking applied to bulk packaging and single packages. Not applied to internal packaging such as plastics, foams, etc.</p>	
Intel Internal Specification	All materials, parts and subassemblies must not contain restricted materials as defined in Intel's Environmental Product Content Specification of Suppliers and Outsourced Manufacturers – http://supplier.intel.com/ehs/environmental.htm	None Required
Europe	<p>European Directive 2002/95/EC - Restriction of Hazardous Substances (RoHS) Threshold limits and banned substances are noted below. Quantity limit of 0.1% by mass (1000 PPM) for: Lead, Mercury, Hexavalent Chromium, Polybrominated Biphenyls Diphenyl Ethers (PBB/PBDE) Quantity limit of 0.01% by mass (100 PPM) for: Cadmium</p>	None Required
Germany	<p>German Green Dot Applied to Retail Packaging Only for Boxed Boards</p>	

Compliance Regional Description	Compliance Reference	Compliance Reference Marking Example
Intel Internal Specification	All materials, parts and subassemblies must not contain restricted materials as defined in Intel's Environmental Product Content Specification of Suppliers and Outsourced Manufacturers – http://supplier.intel.com/ehs/environmental.htm	None Required
International	ISO11469 - Plastic parts weighing >25gm are intended to be marked with per ISO11469. Recycling Markings – Fiberboard (FB) and Cardboard (CB) are marked with international recycling marks. Applied to outer bulk packaging and single package.	>PC/ABS<   Corrugated Recycles
Japan	Japan Recycling Applied to Retail Packaging Only for Boxed Boards	 内袋 

9.4 Other Markings

Compliance Description	Compliance Reference	Compliance Reference Marking Example
Country of Origin	Logistic Requirements Applied to products to indicate where product was made.	Made in XXXX

Appendix A: Integration and Usage Tips

- When adding or removing components or peripherals from the server board, AC power must be removed. With AC power plugged into the server board, 5-volt standby is still present even though the server board is powered off.
- When two processors are installed, both must be of identical revision, core voltage, and bus/core speed. Mixed processor steppings is supported. However, the stepping of one processor can not be greater than one stepping back of the other.
- Processors must be installed in order. CPU 1 is located near the edge of the server board and must be populated to operate the board.
- On the back edge of the server board are four diagnostic LEDs which display a sequence of red, green, or amber POST codes during the boot process. If the server board hangs during POST, the LEDs will display the last POST event run before the hang.
- Only Fully Buffered DIMMs (FBD) are supported on this server board. For a list of supported memory for this server board, see the *Intel® Server Board S5000PAL / S5000XAL Tested Memory List*.
- For a list of Intel supported operating systems, add-in cards, and peripherals for this server board, see the *Intel® Server Board S5000PAL / S5000XAL Tested Hardware and OS List*.
- Only Dual-Core Intel® Xeon® processors 5000 sequence, with system bus speeds of 667/1066/1333 MHz are supported on this server board. Previous generation Intel® Xeon® processors are not supported.
- For best performance, the number of DIMMs installed should be balanced across both memory branches. For example: a four DIMM configuration will perform better than a two DIMM configuration and should be installed in DIMM Slots A1, B1, C1, and D1. An eight DIMM configuration will perform better than a six DIMM configuration.
- There are no population rules for installing a single low profile add-in card in the 2U LP riser card; a single add-in card can be installed in either PCI Express* slot. While each slot can accommodate a x8 card, each slot will only support x4 bus speeds.
- For the 2U PCI-X* (passive) riser card, add-in cards should be installed starting with the top slot first, followed by the middle, and then the bottom. Any add-in card populated in the bottom PCI slot will cause the bus to operate at 66MHz.
- Each PCI slot on the 2U PCI-X* (active) riser card operates on an independent PCI bus. Therefore, using an add-in card that operates below 133MHz will not affect the bus speed of the other PCI slots.
- The IDE connector on this server board is NOT a standard 40-pin IDE connector. Instead, this connector has an additional 4 power pins over and above the standard 40 I/O pins. The design intent of this connector is to provide support for a slim-line optical drive only.
- Removing AC Power before performing the CMOS clear operation will cause the system to automatically power up and immediately power down after the procedure is followed and AC power is re-applied. Should this occur, remove the AC power cord again, wait 30 seconds, and re-install the AC power cord. Power up system and proceed to the <F2> BIOS setup utility to reset desired settings.
- Normal BMC functionality is disabled with the force BMC update jumper set to the “enabled” position (pins 2-3). The server should never be run with the BMC force update jumper set in this position and should only be used when the standard firmware update process fails. This jumper should remain in the default (disabled) position (pins 1-2) when the server is running normally.
- When performing a BIOS update procedure, the BIOS select jumper must be set to its default position (pins 2-3).
- When AC power is applied to the server, a 25-30 second delay is necessary to initialize the BMC. During this initialization period, the Power Button functionality is disabled.

Appendix B: BMC Sensor Tables

This appendix lists the sensor identification numbers and information regarding the sensor type, name, supported thresholds, assertion and de-assertion information, and a brief description of the sensor purpose. See the *Intelligent Platform Management Interface Specification, Version 1.5*, for sensor and event/reading-type table information.

- **Sensor Type**

The Sensor Type references the values enumerated in the *Sensor Type Codes* table in the IPMI specification. It provides the context in which to interpret the sensor, e.g., the physical entity or characteristic that is represented by this sensor.

- **Event / Reading Type**

The Event/Reading Type references values from the *Event/Reading Type Code Ranges* and *Generic Event/Reading Type Codes* tables in the *IPMI specification*. Note that digital sensors are a specific type of discrete sensors, which have only two states.

- **Event Offset/Triggers**

Event Thresholds are 'supported event generating thresholds' for threshold types of sensors.

- [u,l][nr,c,nc] upper nonrecoverable, upper critical, upper noncritical, lower nonrecoverable, lower critical, lower noncritical
- uc, lc upper critical, lower critical

Event Triggers are 'supported event generating offsets' for discrete type sensors. The offsets can be found in the *Generic Event/Reading Type Codes* or *Sensor Type Codes* tables in the IPMI specification, depending on whether the sensor event/reading type is generic or a sensor specific response.

- **Assertion / De-assertion Enables**

Assertion and de-assertion indicators reveal the type of events the sensor can generate:

- As: Assertions
- De: De-assertion

- **Readable Value / Offsets**

- Readable Value indicates the type of value returned for threshold and other non-discrete type sensors.
- Readable Offsets indicate the offsets for discrete sensors that are readable via the *Get Sensor Reading* command. Unless otherwise indicated, all event triggers are readable, i.e., *Readable Offsets* consists of the reading type offsets that do not generate events.

- **Event Data**

This is the data that is included in an event message generated by the associated sensor. For threshold-based sensors, the following abbreviations are used:

- R: Reading value
- T: Threshold value

- **Rearm Sensors**
 - The rearm is a request for the event status for a sensor to be rechecked and updated upon a transition between good and bad states. Rearming the sensors can be done manually or automatically. This column indicates the type supported by the sensor. The following abbreviations are used in the comment column to describe a sensor:
 - A: Auto-rearm
 - M: Manual rearm
- **Default Hysteresis**
 - Hysteresis setting applies to all thresholds of the sensor. This column provides the count of hysteresis for the sensor, which can be 1 or 2 (positive or negative Hysteresis).
- **Criticality**
 - Criticality is a classification of the severity and nature of the condition. It also controls the behavior of the Control Panel Status LED.
- **Standby**
 - Some sensors operate on standby power. These sensors may be accessed and / or generate events when the main (system) power is off, but AC power is present.

Table 44. BMC Sensors

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
Power Unit Status	01h	All	Power Unit 09h	Sensor Specific 6Fh	Power down Power cycle A/C lost	OK	As	–	Trig Offset	A	X
					Soft power control failure Power unit failure	Critical					
					Predictive failure	Non-Critical					
Power Unit Redundancy	02h	Chassis-specific	Power Unit 09h	Generic 0Bh	Redundancy regained Non-red: suff res from redund	OK	As	–	Trig Offset	A	X
					Redundancy lost Redundancy degraded	Degraded					
					Non-red: suff from insuff	OK					
					Non-red: insufficient	Critical					
					Redun degrade from full Redun degrade from non-redundant	OK					

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
Watchdog	03h	All	Watchdog 2 23h	Sensor Specific 6Fh	Timer expired, status only Hard reset Power down Power cycle Timer interrupt	OK	As	–	Trig Offset	A	X
Platform Security Violation	04h	All	Platform Security Violation Attempt 06h	Sensor Specific 6Fh	Secure mode violation attempt Out-of-band access password violation	OK	As	–	Trig Offset	A	X
Physical Security	05h	Chassis Intrusion is chassis-specific	Physical Security 05h	Sensor Specific 6Fh	Chassis intrusion LAN leash lost 1	OK	As and De	–	Trig Offset	A	X
FP Diag Interrupt (NMI)	07h	All	Critical Interrupt 13h	Sensor Specific 6Fh	Front panel NMI / diagnostic interrupt Bus uncorrectable error	OK	As	–	Trig Offset	A	–
System Event Log	09h	All	Event Logging Disabled 10h	Sensor Specific 6Fh	Log area reset / cleared	OK	As	–	Trig Offset	A	X
Session Audit	0Ah	All	Session Audit 2Ah	Sensor Specific 6Fh	00h – Session activation 01h – Session deactivation	OK	As	–	As defined by IPMI	A	X

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
System Event ('System Event')	0Bh	All	System Event 12h	Sensor Specific 6Fh	00 – System reconfigured 04 – PEF action	OK	As	–	Trig Offset	A	X
BB +1.2V Vtt	10h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB+1.9V NIC Core	11h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	X
BB +1.5V AUX	12h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB +1.5V	13h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB +1.8V	14h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB +3.3V	15h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB +3.3V STB	16h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	X
BB +1.5V ESB	17h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	X
BB +5V	18h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB +1.2V NIC	19h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB +12V AUX	1Ah	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB 0.9V	1Bh	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
BB Vbat	1Eh	All	Voltage 02h	Digital Discrete 05h	01h – Limit exceeded	Critical	As and De	–	R, T	A	X

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
BB Temp	30h	All	Temperature 01h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	X
Front Panel Temp	32h	All	Temperature 01h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	X
BNB Temp	33h	All	Temperature 01h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
Fan 1A	50h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 2A	51h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 3A	52h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 4A	53h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 5A	54h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Tach Fan (not used on this server)	55h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 1B	56h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 2B	57h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 3B	58h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 4B	59h	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–
Fan 5B	5Ah	Chassis-specific	Fan 04h	Threshold 01h	[l] [c,nc]	Threshold defined	As and De	Analog	R, T	M	–

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
Fan 1 Present	60h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 2 Present	61h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 3 Present	62h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 4 Present	63h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 5 Present	64h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 6 Present	65h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 7 Present	66h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 8 Present	67h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 9 Present	68h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan 10 Present	69h	Chassis-specific	Fan 04h	Generic 08h	Device present	OK	As and De	–	T	A	–
Fan Redundancy	6Fh	Chassis-specific	Fan 04h	Generic 0Bh	Redundancy regained	OK	As	–	Trig Offset	A	X
					Redundancy lost Redundancy degraded	Degraded					
					Non-red: suff res from redund Non-red: suff from insuff	OK					

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
					Non-red: insufficient	Critical					
					Redun degrade from full	OK					
					Redun degrade from non- redundant						
Power Supply Status 1	70h	Chassis-specific	Power Supply 08h	Sensor Specific 6Fh	Presence	OK	As and De	-	Trig Offset	A	X
					Failure	Critical					
					Predictive fail	Non-Critical					
					A/C lost	Critical					
					Configuration error	Non-Critical					
Power Supply Status 2	71h	Chassis-specific	Power Supply 08h	Sensor Specific 6Fh	Presence	OK	As and De	-	Trig Offset	A	X
					Failure	Critical					
					Predictive fail	Non-Critical					
					A/C lost	Critical					
					Configuration error	Non-Critical					
Power Nozzle Power Supply 1	78h	Chassis-specific	Current 03h	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	R, T	A	-
Power Nozzle Power Supply 2	79h	Chassis-specific	Current 03h	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	R, T	A	-
Power Gauge V1 rail (+12v) Power Supply 1	7Ah	Chassis-specific	Current 03h	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	R, T	A	-

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
Power Gauge V1 rail (+12v) Power Supply 2	7Bh	Chassis-specific	Current 03h	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
Power Gauge (aggregate power) Power Supply 1	7Ch	Chassis-specific	Other Units 0Bh	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
Power Gauge (aggregate power) Power Supply 2	7Dh	Chassis-specific	Other Units 0Bh	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
System ACPI Power State	82h	All	System ACPI Power State 22h	Sensor Specific 6Fh	S0 / G0 S1 S3 S4 S5 / G2 G3 mechanical off	OK	As	–	Trig Offset	A	X
Button	84h	All	Button 14h	Sensor Specific 6Fh	Power button Reset button	OK	As	–	Trig Offset	A	X
SMI Timeout	85h	All	SMI Timeout F3h	Digital Discrete 03h	01h – State asserted	Critical	As and De	–	Trig Offset	A	–

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
Sensor Failure	86h	All	Sensor Failure F6h	OEM Sensor Specific 73h	I ² C device not found I ² C device error detected I ² C bus timeout	OK	As	–	Trig Offset	A	X
NMI Signal State	87h	All	OEM C0h	Digital Discrete 03h	01h – State asserted	OK	–	01h	–	–	–
SMI Signal State	88h	All	OEM C0h	Digital Discrete 03h	01h – State asserted	OK	–	01h	–	–	–
Proc 1 Status	90h	All	Processor 07h	Sensor Specific 6Fh	IERR	Critical	As and De	–	Trig Offset	M	X
					Thermal trip	Non-rec					
					Config error	Critical					
					Presence	OK					
					Disabled	Degraded					
Proc 2 Status	91h	All	Processor 07h	Sensor Specific 6Fh	IERR	Critical	As and De	–	Trig Offset	M	X
					Thermal trip	Non-rec					
					Config error	Critical					
					Presence	OK					
					Disabled	Degraded					
Proc 1 Temp	98h	All	Temperature 01h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
Proc 2 Temp	9Ah	All	Temperature 01h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
PCIe Link0	A0h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link0	Bus correctable error	OK	As	–	See the BIOS EPS	A	–
					Bus uncorrectable error	Degraded					

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
PCIe Link1	A1h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link1	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link2	A2h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link2	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link3	A3h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link3	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link4	A4h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link4	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link5	A5h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link5	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link6	A6h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link6	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link7	A7h	Critical Interrupt	Sensor Specific	PCIe Link7	Bus correctable error	OK	As	-	See the BIOS EPS	A	-

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
		13F	6Fh		Bus uncorrectable error	Degraded					
PCIe Link8	A8h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link8	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link9	A9h	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link9	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link10	AAh	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link10	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link11	ABh	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link11	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link12	ACh	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link12	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					
PCIe Link13	ADh	Critical Interrupt 13F	Sensor Specific 6Fh	PCIe Link13	Bus correctable error	OK	As	-	See the BIOS EPS	A	-
					Bus uncorrectable error	Degraded					

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
Proc 1 Thermal Control	C0h	All	Temperature 01h	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	Trig Offset	M	–
Proc 2 Thermal Control	C1h	All	Temperature 01h	Threshold 01h	[u] [c,nc]	Threshold defined	As and De	Analog	Trig Offset	M	–
Proc 1 VRD Over Temp	C8h	All	Temperature 01h	Digital Discrete 05h	01h – Limit exceeded	Non-Critical	As and De	–	Trig Offset	M	–
Proc 2 VRD Over Temp	C9h	All	Temperature 01h	Digital Discrete 05h	01h – Limit exceeded	Non-Critical	As and De	–	Trig Offset	M	–
Proc 1 Vcc	D0h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
Proc 2 Vcc	D1h	All	Voltage 02h	Threshold 01h	[u,l] [c,nc]	Threshold defined	As and De	Analog	R, T	A	–
Proc 1 Vcc Out-of-Range	D2h	All	Voltage 02h	Digital Discrete 05h	01h – Limit exceeded	Non-Critical	As and De	Discrete	R, T	A	–
Proc 2 Vcc Out-of-Range	D3h	All	Voltage 02h	Digital Discrete 05h	01h – Limit exceeded	Non-Critical	As and De	Discrete	R, T	A	–
CPU Population Error	D8h	All	Processor 07h	Generic 03h	01h – State asserted	Critical	As and De	–	R, T	A	–
DIMM A1	E0h	All	Slot Connector 21h	Sensor Specific 6Fh	Fault status asserted	Degraded	As	–	Trig Offset	A	–
					Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
DIMM A2	E1h	All	Slot Connector	Sensor Specific	Fault status asserted	Degraded	As	–	Trig Offset	A	–

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
			21h	6Fh	Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
DIMM B1	E2h	All	Slot Connector 21h	Sensor Specific 6Fh	Fault status asserted	Degraded	As	–	Trig Offset	A	–
					Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
DIMM B2	E3h	All	Slot Connector 21h	Sensor Specific 6Fh	Fault status asserted	Degraded	As	–	Trig Offset	A	–
					Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
DIMM C1	E4h	All	Slot Connector 21h	Sensor Specific 6Fh	Fault status asserted	Degraded	As	–	Trig Offset	A	–
					Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
DIMM C2	E5h	All	Slot Connector 21h	Sensor Specific 6Fh	Fault status asserted	Degraded	As	–	Trig Offset	A	–
					Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
DIMM D1	E6h	All	Slot Connector 21h	Sensor Specific 6Fh	Fault status asserted	Degraded	As	–	Trig Offset	A	–
					Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
DIMM D2	E7h	All	Slot Connector	Sensor Specific	Fault status asserted	Degraded	As	–	Trig Offset	A	–

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
			21h	6Fh	Device installed	OK					
					Disabled	Degraded					
					Sparing	OK					
Memory A Error	ECh	All	Memory 0Ch	Sensor Specific 6Fh	Correctable ECC Uncorrectable ECC	OK	As	–	Trig Offset	A	–
Memory B Error	EDh	System-specific	Memory 0Ch	Sensor Specific 6Fh	Correctable ECC Uncorrectable ECC	OK	As	–	Trig Offset	A	–
Memory C Error	EEh	System-specific	Memory 0Ch	Sensor Specific 6Fh	Correctable ECC Uncorrectable ECC	OK	As	–	Trig Offset	A	–
Memory D Error	EFh	System-specific	Memory 0Ch	Sensor Specific 6Fh	Correctable ECC Uncorrectable ECC	OK	As	–	Trig Offset	A	–
B0 DIMM Sparing Enabled	F0h	All	Entity Presence 25h	Sensor Specific 6Fh	Entity present	OK	As	–	Trig Offset	A	–
B0 DIMM Sparing Redundancy	F1h	All	Memory 0Ch	Discrete 0Bh	Fully redundant	OK	As	–	Trig Offset	A	–
					Non-red: suff res from redund	Degraded					
					Non-red: suff res from insuff res						
					Non-red: Insuff res	Critical					
B1 DIMM Sparing Enabled	F2h	All	Entity Presence 25h	Sensor Specific 6Fh	Entity present	OK	As	–	Trig Offset	A	–

Sensor Name	Sensor Number	System Applicability	Sensor Type	Event / Reading Type	Event Offset Triggers	Criticality	Assert / De-assert	Readable Value / Offsets	Event Data	Rearm	Standby
B1 DIMM Sparing Redundancy	F3h	All	Memory 0Ch	Discrete 0Bh	Fully redundant	OK	As	-	Trig Offset	A	-
					Non-red: suff res from redund	Degraded					
					Non-red: suff res from insuff res	Critical					
B01 DIMM Mirroring Enabled	F4h	All	Entity Presence 25h	Sensor Specific 6Fh	Entity present	OK	As	-	Trig Offset	A	-
B01 DIMM Mirroring Redundancy	F5h	All	Memory 0Ch	Discrete 0Bh	Fully redundant	OK	As	-	Trig Offset	A	-
					Non-red:suff res from redund	Degraded					
					Non-red:suff res from insuff res	Critical					

Note 1: Not supported except for ESB-2 embedded NICs

Appendix C: POST Code Diagnostic LED Decoder

During the system boot process, BIOS executes a number of platform configuration processes, each of which is assigned a specific hex POST code number. As each configuration routine is started, BIOS will display the given POST code to the POST Code Diagnostic LEDs found on the back edge of the server board. To assist in troubleshooting a system hang during the POST process, the Diagnostic LEDs can be used to identify the last POST process to be executed.

Each POST code will be represented by a combination of colors from the four LEDs. The LEDs are capable of displaying three colors: green, red, and amber. The POST codes are divided into two nibbles, an upper nibble and a lower nibble. Each bit in the upper nibble is represented by a red LED and each bit in the lower nibble is represented by a green LED. If both bits are set in the upper and lower nibbles then both red and green LEDs are lit, resulting in an amber color. If both bits are clear, then the LED is off.

In the below example, BIOS sends a value of ACh to the diagnostic LED decoder. The LEDs are decoded as follows:

- red bits = 1010b = Ah
- green bits = 1100b = Ch

Since the red bits correspond to the upper nibble and the green bits correspond to the lower nibble, the two are concatenated to be ACh.

Table 45: POST Progress Code LED Example

LEDs	8h		4h		2h		1h	
	Red	Green	Red	Green	Red	Green	Red	Green
ACh	1	1	0	1	1	0	0	0
Result	Amber		Green		Red		Off	
	MSB				LSB			

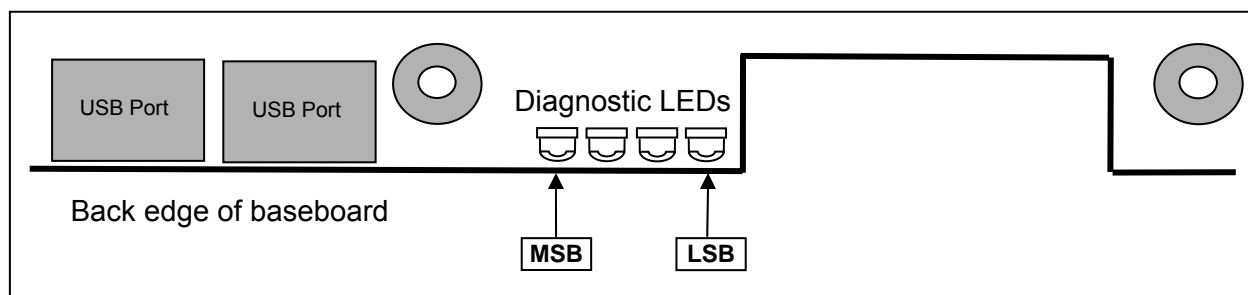


Figure 28. Diagnostic LED Placement Diagram

Table 46. Diagnostic LED POST Code Decoder

Checkpoint	Diagnostic LED Decoder				Description
	G=Green, R=Red, A=Amber				
	MSB			LSB	
Host Processor					
0x10h	OFF	OFF	OFF	R	Power-on initialization of the host processor (bootstrap processor)
0x11h	OFF	OFF	OFF	A	Host processor cache initialization (including AP)
0x12h	OFF	OFF	G	R	Starting application processor initialization
0x13h	OFF	OFF	G	A	SMM initialization
Chipset					
0x21h	OFF	OFF	R	G	Initializing a chipset component
Memory					
0x22h	OFF	OFF	A	OFF	Reading configuration data from memory (SPD on DIMM)
0x23h	OFF	OFF	A	G	Detecting presence of memory
0x24h	OFF	G	R	OFF	Programming timing parameters in the memory controller
0x25h	OFF	G	R	G	Configuring memory parameters in the memory controller
0x26h	OFF	G	A	OFF	Optimizing memory controller settings
0x27h	OFF	G	A	G	Initializing memory, such as ECC init
0x28h	G	OFF	R	OFF	Testing memory
PCI Bus					
0x50h	OFF	R	OFF	R	Enumerating PCI busses
0x51h	OFF	R	OFF	A	Allocating resources to PCI busses
0x52h	OFF	R	G	R	Hot Plug PCI controller initialization
0x53h	OFF	R	G	A	Reserved for PCI bus
0x54h	OFF	A	OFF	R	Reserved for PCI bus
0x55h	OFF	A	OFF	A	Reserved for PCI bus
0x56h	OFF	A	G	R	Reserved for PCI bus
0x57h	OFF	A	G	A	Reserved for PCI bus
USB					
0x58h	G	R	OFF	R	Resetting USB bus
0x59h	G	R	OFF	A	Reserved for USB devices
ATA / ATAPI / SATA					
0x5Ah	G	R	G	R	Resetting PATA / SATA bus and all devices
0x5Bh	G	R	G	A	Reserved for ATA
SMBUS					
0x5Ch	G	A	OFF	R	Resetting SMBUS
0x5Dh	G	A	OFF	A	Reserved for SMBUS
Local Console					
0x70h	OFF	R	R	R	Resetting the video controller (VGA)
0x71h	OFF	R	R	A	Disabling the video controller (VGA)
0x72h	OFF	R	A	R	Enabling the video controller (VGA)
Remote Console					
0x78h	G	R	R	R	Resetting the console controller
0x79h	G	R	R	A	Disabling the console controller
0x7Ah	G	R	A	R	Enabling the console controller
Keyboard (PS2 or USB)					
0x90h	R	OFF	OFF	R	Resetting the keyboard
0x91h	R	OFF	OFF	A	Disabling the keyboard

Checkpoint	Diagnostic LED Decoder				Description
	G=Green, R=Red, A=Amber				
	MSB			LSB	
0x92h	R	OFF	G	R	Detecting the presence of the keyboard
0x93h	R	OFF	G	A	Enabling the keyboard
0x94h	R	G	OFF	R	Clearing keyboard input buffer
0x95h	R	G	OFF	A	Instructing keyboard controller to run Self Test (PS2 only)
Mouse (PS2 or USB)					
0x98h	A	OFF	OFF	R	Resetting the mouse
0x99h	A	OFF	OFF	A	Detecting the mouse
0x9Ah	A	OFF	G	R	Detecting the presence of mouse
0x9Bh	A	OFF	G	A	Enabling the mouse
Fixed Media					
0xB0h	R	OFF	R	R	Resetting fixed media device
0xB1h	R	OFF	R	A	Disabling fixed media device
0xB2h	R	OFF	A	R	Detecting presence of a fixed media device (IDE hard drive detection, etc.)
0xB3h	R	OFF	A	A	Enabling / configuring a fixed media device
Removable Media					
0xB8h	A	OFF	R	R	Resetting removable media device
0xB9h	A	OFF	R	A	Disabling removable media device
0xBAh	A	OFF	A	R	Detecting presence of a removable media device (IDE CDROM detection, etc.)
0xBCh	A	G	R	R	Enabling / configuring a removable media device
Boot Device Selection					
0xD0	R	R	OFF	R	Trying boot device selection
0xD1	R	R	OFF	A	Trying boot device selection
0xD2	R	R	G	R	Trying boot device selection
0xD3	R	R	G	A	Trying boot device selection
0xD4	R	A	OFF	R	Trying boot device selection
0xD5	R	A	OFF	A	Trying boot device selection
0xD6	R	A	G	R	Trying boot device selection
0xD7	R	A	G	A	Trying boot device selection
0xD8	A	R	OFF	R	Trying boot device selection
0xD9	A	R	OFF	A	Trying boot device selection
0XDA	A	R	G	R	Trying boot device selection
0xDB	A	R	G	A	Trying boot device selection
0xDC	A	A	OFF	R	Trying boot device selection
0xDE	A	A	G	R	Trying boot device selection
0xDF	A	A	G	A	Trying boot device selection
Pre-EFI Initialization (PEI) Core					
0xE0h	R	R	R	OFF	Started dispatching early initialization modules (PEIM)
0xE2h	R	R	A	OFF	Initial memory found, configured, and installed correctly
0xE1h	R	R	R	G	Reserved for initialization module use (PEIM)
0xE3h	R	R	A	G	Reserved for initialization module use (PEIM)
Driver Execution Environment (DXE) Core					
0xE4h	R	A	R	OFF	Entered EFI driver execution phase (DXE)
0xE5h	R	A	R	G	Started dispatching drivers
0xE6h	R	A	A	OFF	Started connecting drivers
DXE Drivers					

Checkpoint	Diagnostic LED Decoder				Description
	G=Green, R=Red, A=Amber				
	MSB			LSB	
0xE7h	R	A	A	G	Waiting for user input
0xE8h	A	R	R	OFF	Checking password
0xE9h	A	R	R	G	Entering BIOS setup
0xEAh	A	R	A	OFF	Flash Update
0xEEh	A	A	A	OFF	Calling Int 19. One beep unless silent boot is enabled.
0xEFh	A	A	A	G	Unrecoverable boot failure / S3 resume failure
Runtime Phase / EFI Operating System Boot					
0xF4h	R	A	R	R	Entering Sleep state
0xF5h	R	A	R	A	Exiting Sleep state
0xF8h	A	R	R	R	Operating system has requested EFI to close boot services (ExitBootServices () has been called)
0xF9h	A	R	R	A	Operating system has switched to virtual address mode (SetVirtualAddressMap () has been called)
0xFAh	A	R	A	R	Operating system has requested the system to reset (ResetSystem () has been called)
Pre-EFI Initialization Module (PEIM) / Recovery					
0x30h	OFF	OFF	R	R	Crisis recovery has been initiated because of a user request
0x31h	OFF	OFF	R	A	Crisis recovery has been initiated by software (corrupt flash)
0x34h	OFF	G	R	R	Loading crisis recovery capsule
0x35h	OFF	G	R	A	Handing off control to the crisis recovery capsule
0x3Fh	G	G	A	A	Unable to complete crisis recovery.

Appendix D: POST Error Messages and Handling

Whenever possible, the BIOS will output the current boot progress codes on the video screen. Progress codes are 32-bit quantities plus optional data. The 32-bit numbers include class, subclass, and operation information. The class and subclass fields point to the type of hardware that is being initialized. The operation field represents the specific initialization activity. Based on the data bit availability to display progress codes, a progress code can be customized to fit the data width. The higher the data bit, the higher the granularity of information that can be sent on the progress port. The progress codes may be reported by the system BIOS or option ROMs.

The Response section in the following table is divided into two types:

Pause: The message is displayed in the Error Manager screen, an error is logged to the SEL, and user input is required to continue. The user can take immediate corrective action or choose to continue booting.

Halt: The message is displayed in the Error Manager screen, an error is logged to the SEL, and the system cannot boot unless the error is resolved. The user needs to replace the faulty part and restart the system.

Table 47. POST Error Messages and Handling

Error Code	Error Message	Response
004C	Keyboard / interface error	Pause
0012	CMOS date / time not set	Pause
5220	Configuration cleared by jumper	Pause
5221	Passwords cleared by jumper	Pause
5223	Configuration default loaded	Pause
0048	Password check failed	Halt
0141	PCI resource conflict	Pause
0146	Insufficient memory to shadow PCI ROM	Pause
8110	Processor 01 internal error (IERR) on last boot	Pause
8111	Processor 02 internal error (IERR) on last boot	Pause
8120	Processor 01 thermal trip error on last boot	Pause
8121	Processor 02 thermal trip error on last boot	Pause
8130	Processor 01 disabled	Pause
8131	Processor 02 disabled	Pause
8160	Processor 01 unable to apply BIOS update	Pause
8161	Processor 02 unable to apply BIOS update	Pause
8190	Watchdog timer failed on last boot	Pause
8198	Operating system boot watchdog timer expired on last boot	Pause
0192	L3 cache size mismatch	Halt
0194	CPUID, processor family are different	Halt
0195	Front side bus mismatch	Pause
0197	Processor speeds mismatched	Pause
8300	Baseboard management controller failed self-test	Pause
8306	Front panel controller locked	Pause
8305	Hotswap controller failed	Pause
84F2	Baseboard management controller failed to respond	Pause
84F3	Baseboard management controller in update mode	Pause
84F4	Sensor data record empty	Pause

Appendix D: POST Error Messages and Handling Intel® Server Board S5000PAL / S5000XAL TPS

Error Code	Error Message	Response
84FF	System event log full	Pause
8500	Memory Component could not be configured in the selected RAS mode.	Pause
8520	DIMM_A1 failed Self Test (BIST).	Pause
8521	DIMM_A2 failed Self Test (BIST).	Pause
8522	DIMM_A3 failed Self Test (BIST).	Pause
8523	DIMM_A4 failed Self Test (BIST).	Pause
8524	DIMM_B1 failed Self Test (BIST).	Pause
8525	DIMM_B2 failed Self Test (BIST).	Pause
8526	DIMM_B3 failed Self Test (BIST).	Pause
8527	DIMM_B4 failed Self Test (BIST).	Pause
8528	DIMM_C1 failed Self Test (BIST).	Pause
8529	DIMM_C2 failed Self Test (BIST).	Pause
852A	DIMM_C3 failed Self Test (BIST).	Pause
852B	DIMM_C4 failed Self Test (BIST).	Pause
852C	DIMM_D1 failed Self Test (BIST).	Pause
852D	DIMM_D2 failed Self Test (BIST).	Pause
852E	DIMM_D3 failed Self Test (BIST).	Pause
852F	DIMM_D4 failed Self Test (BIST).	Pause
8540	Memory Component lost redundancy during the last boot.	Pause
8580	DIMM_A1 Correctable ECC error encountered.	Pause
8581	DIMM_A2 Correctable ECC error encountered.	Pause
8582	DIMM_A3 Correctable ECC error encountered.	Pause
8583	DIMM_A4 Correctable ECC error encountered.	Pause
8584	DIMM_B1 Correctable ECC error encountered.	Pause
8585	DIMM_B2 Correctable ECC error encountered.	Pause
8586	DIMM_B3 Correctable ECC error encountered.	Pause
8587	DIMM_B4 Correctable ECC error encountered.	Pause
8588	DIMM_C1 Correctable ECC error encountered.	Pause
8589	DIMM_C2 Correctable ECC error encountered.	Pause
858A	DIMM_C3 Correctable ECC error encountered.	Pause
858B	DIMM_C4 Correctable ECC error encountered.	Pause
858C	DIMM_D1 Correctable ECC error encountered.	Pause
858D	DIMM_D2 Correctable ECC error encountered.	Pause
858E	DIMM_D3 Correctable ECC error encountered.	Pause
858F	DIMM_D4 Correctable ECC error encountered.	Pause
8600	Primary and secondary BIOS IDs do not match.	Pause
8601	Override jumper is set to force boot from lower alternate BIOS bank of flash ROM	Pause
8602	WatchDog timer expired (secondary BIOS may be bad!)	Pause
8603	Secondary BIOS checksum fail	Pause

POST Error Beep Codes

The following table lists POST error beep codes. Prior to system Video initialization, BIOS uses these beep codes to inform users on error conditions. The beep code is followed by a user visible code on POST Progress LEDs.

Table 48. POST Error Beep Codes

Beeps	Error Message	POST Progress Code	Description
3	Memory error		System halted because a fatal error related to the memory was detected.
6	BIOS rolling back error		The system has detected a corrupted BIOS in the flash part, and is rolling back to the last good BIOS.

The BMC may generate beep codes upon detection of failure conditions. Beep codes are sounded each time the problem is discovered, such as on each power-up attempt, but are not sounded continuously. Codes that are common across all Intel® Server Boards and systems that use the Intel® S5000 chipset are listed in Table 49. Each digit in the code is represented by a sequence of beeps whose count is equal to the digit.

Table 49. BMC Beep Codes

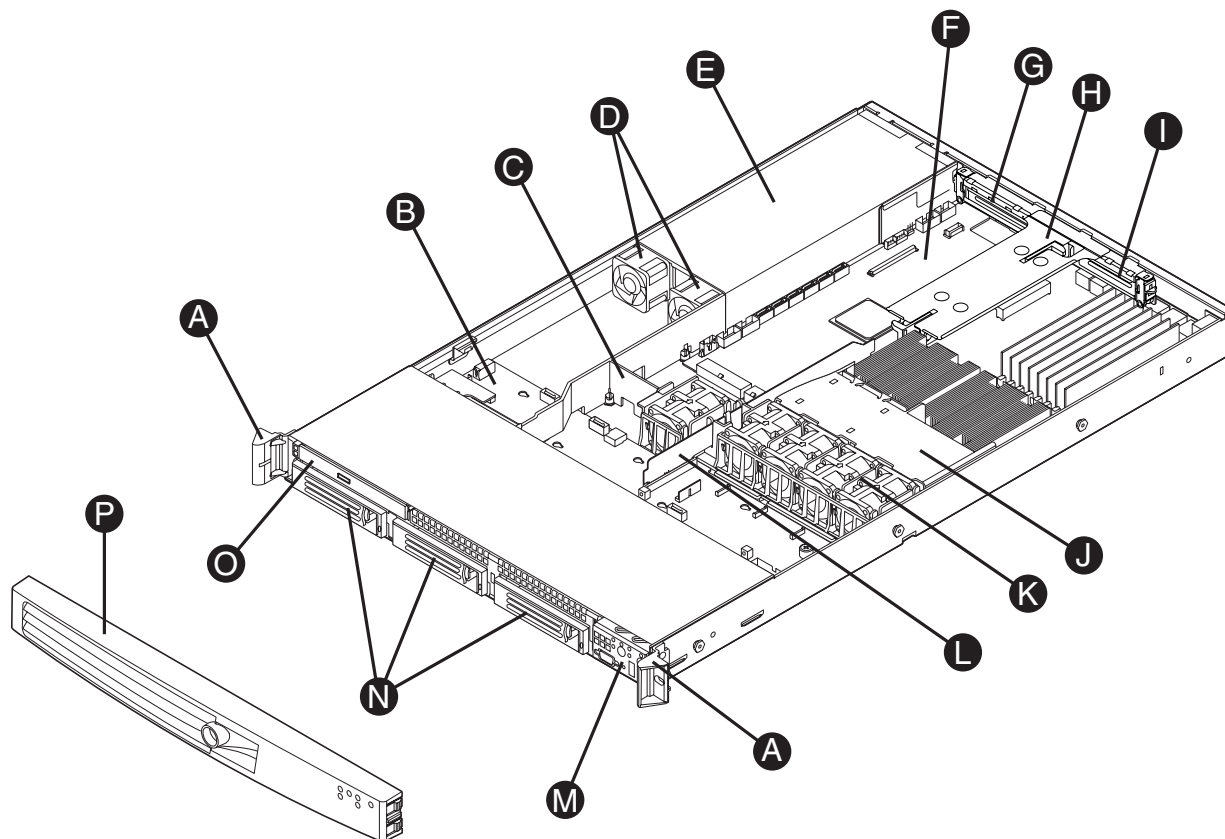
Code	Reason for Beep	Associated Sensors	Supported?
1-5-2-1	CPU: Empty slot / population error – Processor slot 1 is not populated.	CPU Population Error	Yes
1-5-2-2	CPU: No processors (terminators only)	N/A	No
1-5-2-3	CPU: Configuration error (e.g., VID mismatch)	N/A	No
1-5-2-4	CPU: Configuration error (e.g., BSEL mismatch)	N/A	No
1-5-4-2	Power fault: DC power unexpectedly lost (power good dropout)	Power Unit – power unit failure offset	Yes
1-5-4-3	Chipset control failure	N/A	No
1-5-4-4	Power control fault	Power Unit – soft power control failure offset	Yes

Appendix E: Supported Intel® Server Chassis

The Intel® Server Board S5000PAL / S5000XAL is supported in the following Intel high density rack mount server chassis:

- Intel® Server Chassis SR1500
- Intel® Server Chassis SR1550
- Intel® Server Chassis SR2500

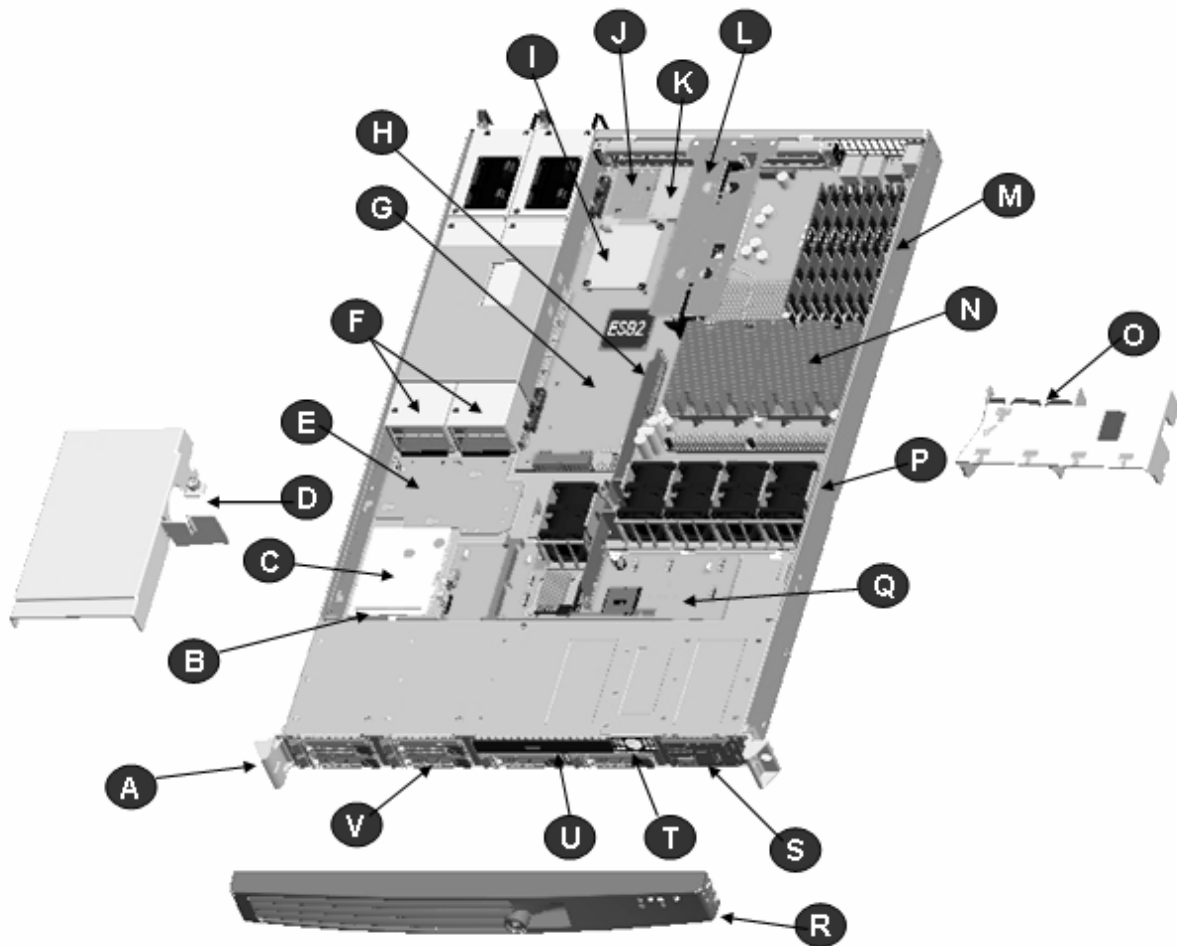
This section provides a high level descriptive overview of each chassis. For more detail, please reference the appropriate Technical Product Specification (TPS) available for each.



TP02154

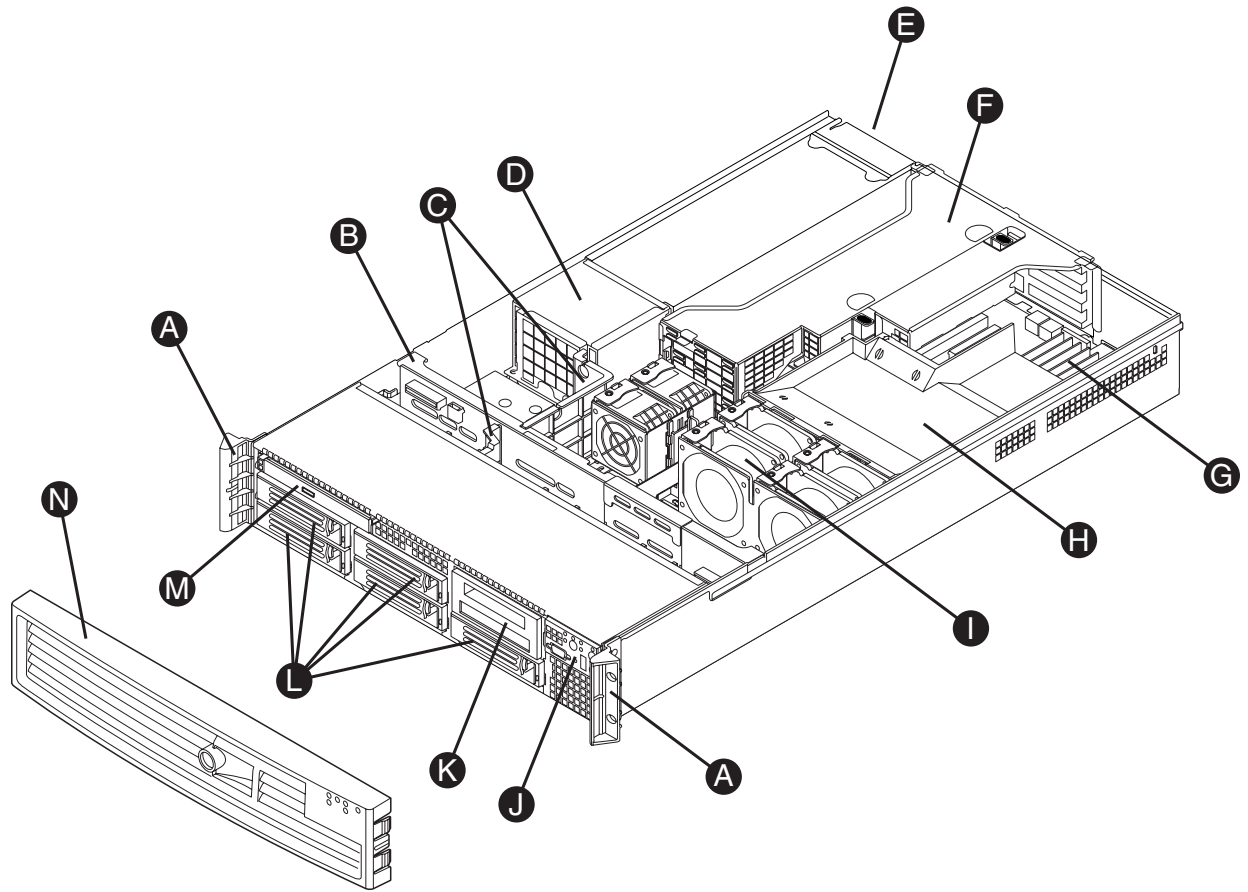
A	Rack handles	I	PCI card bracket (low profile) – PCIe*
B	Backplane – Passive SAS/SATA or Active SAS/SAS RAID	J	Processor air duct
C	Air baffle	K	Fan module
D	Power supply fans	L	Bridge board
E	600 Watt Power supply	M	Control panel (standard control panel shown)
F	Intel® Server Board S5000PAL / S5000XAL	N	Hard drive bays (drives not included)
G	PCI card bracket (full height) – PCI-X* or PCIe*	O	Slimline drive bay (drive not included)
H	PCI add-in riser assembly	P	Front bezel (optional)

Figure 29. 1U – Intel® Server Chassis SR1500 Overview



A	Rack Handles	L	Riser Card Assembly
B	SAS/SATA Backplane	M	System Memory
C	SAS RAID Battery Pack (Optional)	N	Processor and Heat Sink
D	Power Supply Air Duct	O	Processor Air Duct
E	Power Distribution Board	P	System Fan Bank
F	1+1 650 Watt Power Supply Modules	Q	Mid-plane Board (Active - SAS/SAS RAID shown)
G	Intel® Server Board S5000PAL / S5000XAL	R	Front Bezel (Optional; Standard Control Panel shown)
H	Bridge Board	S	Standard Control Panel or Intel® Local Control Panel (Optional)
I	Intel® RMM Module (Optional)	T	Mini Control Panel Bay – required option to support eight hard drives
J	Intel® RMM NIC(Optional)	U	Slimline Optical Drive Bay
K	IO Module (Optional)	V	Up to Eight 2.5" Hard Drive Bays

Figure 30. 1U – Intel® Server Chassis SR1550 Overview



TP02094

- | | |
|--|--|
| A. Rack Handles | H. CPU Air Duct |
| B. SAS/SATA Backplane | I. System Fan Assembly |
| C. Air Baffles | J. Standard Control Panel |
| D. Power Distribution Module | K. Flex Bay – 6 th HDD or Tape (Optional) |
| E. 1+1 750 Watt Power Supply Modules | L. Five SATA/SAS Hard Drive Bays |
| F. Riser Card Assembly | M. Slim-Line Optical Drive Bay |
| G. System Memory | N. Front Bezel (Optional) |
| Mid-pane – Passive SAS/SATA or Active SAS/SAS RAID (Not shown) | |

Figure 31. 2U – Intel® Server Chassis SR2500 Overview

Glossary

This appendix contains important terms used in the preceding chapters. For ease of use, numeric entries are listed first (e.g., “82460GX”) with alpha entries following (e.g., “AGP 4x”). Acronyms are then entered in their respective place, with non-acronyms following.

Term	Definition
ACPI	Advanced Configuration and Power Interface
AP	Application Processor
APIC	Advanced Programmable Interrupt Control
ASIC	Application Specific Integrated Circuit
ASMI	Advanced Server Management Interface
BIOS	Basic Input/Output System
BIST	Built-In Self Test
BMC	Baseboard Management Controller
Bridge	Circuitry connecting one computer bus to another, allowing an agent on one to access the other
BSP	Bootstrap Processor
byte	8-bit quantity.
CBC	Chassis Bridge Controller (A microcontroller connected to one or more other CBCs, together they bridge the IPMB buses of multiple chassis.
CEK	Common Enabling Kit
CHAP	Challenge Handshake Authentication Protocol
CMOS	In terms of this specification, this describes the PC-AT compatible region of battery-backed 128 bytes of memory, which normally resides on the server board.
DPC	Direct Platform Control
EEPROM	Electrically Erasable Programmable Read-Only Memory
EHCI	Enhanced Host Controller Interface
EMP	Emergency Management Port
EPS	External Product Specification
ESB-2	Enterprise South Bridge 2
FBD	Fully Buffered DIMM
FMB	Flexible Mother Board
FRB	Fault Resilient Booting
FRU	Field Replaceable Unit
FSB	Front Side Bus
GB	1024MB
GPIO	General Purpose I/O
GTL	Gunning Transceiver Logic
HSC	Hot-Swap Controller
Hz	Hertz (1 cycle/second)
I2C	Inter-Integrated Circuit Bus
IA	Intel® Architecture
IBF	Input Buffer
ICH	I/O Controller Hub
ICMB	Intelligent Chassis Management Bus
IERR	Internal Error
IFB	I/O and Firmware Bridge
INTR	Interrupt
IP	Internet Protocol
IPMB	Intelligent Platform Management Bus

Term	Definition
IPMI	Intelligent Platform Management Interface
IR	Infrared
ITP	In-Target Probe
KB	1024 bytes
KCS	Keyboard Controller Style
LAN	Local Area Network
LCD	Liquid Crystal Display
LED	Light Emitting Diode
LPC	Low Pin Count
LUN	Logical Unit Number
MAC	Media Access Control
MB	1024KB
MCH	Memory Controller Hub
MD2	Message Digest 2 – Hashing Algorithm
MD5	Message Digest 5 – Hashing Algorithm – Higher Security
ms	milliseconds
MTTR	Memory Type Range Register
Mux	Multiplexor
NIC	Network Interface Controller
NMI	Nonmaskable Interrupt
OBF	Output Buffer
OEM	Original Equipment Manufacturer
Ohm	Unit of electrical resistance
PEF	Platform Event Filtering
PEP	Platform Event Paging
PIA	Platform Information Area (This feature configures the firmware for the platform hardware)
PLD	Programmable Logic Device
PMI	Platform Management Interrupt
POST	Power-On Self Test
PSMI	Power Supply Management Interface
PWM	Pulse-Width Modulation
RAM	Random Access Memory
RASUM	Reliability, Availability, Serviceability, Usability, and Manageability
RISC	Reduced Instruction Set Computing
ROM	Read Only Memory
RTC	Real-Time Clock (Component of ICH peripheral chip on the server board)
SDR	Sensor Data Record
SECC	Single Edge Connector Cartridge
SEEPROM	Serial Electrically Erasable Programmable Read-Only Memory
SEL	System Event Log
SIO	Server Input/Output
SMI	Server Management Interrupt (SMI is the highest priority nonmaskable interrupt)
SMM	Server Management Mode
SMS	Server Management Software
SNMP	Simple Network Management Protocol
TBD	To Be Determined
TIM	Thermal Interface Material
UART	Universal Asynchronous Receiver/Transmitter

Term	Definition
UDP	User Datagram Protocol
UHCI	Universal Host Controller Interface
UTC	Universal time coordinare
VID	Voltage Identification
VRD	Voltage Regulator Down
Word	16-bit quantity
ZIF	Zero Insertion Force

Reference Documents

See the following documents for additional information:

- Intel® S5000 Series Chipsets Server Board Family Datasheet
- Intel® Bensley BIOS Core External Product Specification (Yellow Cover)
- Intel® Bensley BMC Core External Product Specification (Yellow Cover)
- Intel® 5000P Memory Controller Hub External Design Specification (Yellow Cover)
- Intel® Enterprise South Bridge-2 (ESB-2) External Design Specification (Yellow Cover)
- TEB 2.11 – Thin Electronics Bay (1U/2U Rack Optimized)
- EPS 1U Rev. 2.93 – Entry Level Power Supply – 1U non-redundant – Bensley Platform
- ERP 2U – Rev. 2.31 – Entry Redundant Power Supply 2U form factory – Bensley Platform

Note: Yellow Cover documents can only be obtained under NDA with Intel and ordered through an Intel representative.
